COMPAL CONFIDENTIAL

MODEL NAME : *NAL20*

PCB NO : *LA-5571P (DA80000FP00)*

BOM P/N : *43176531LXX*

M10 Margaux UMA

rPGA Auburndale +
FCBGA PCH IBEXPEAK-M

2010-01-21

REV : 1.0(A00)

@ : Nopop Component

MB Type	BOM P/N	TCM		TPM		BOM CONFIG
		W(3@)	W/O(4@)	W(5@)	W/O(6@)	
TPM EN,TCM DIS	43176531L01		*	*		4@,5@
ALL TPM DISABLE	43176531L02		*		*	4@,6@
TCM EN,TPM DIS	43176531L03	*			*	3@,6@

MB PCB

Part Number	Description
DA80000FP00	PCB 0AF LA-5571P REV0 M/B UMA

Block Diagram
Compal confidential
Model: NAL20

Thermal GUARDIAN III EMC4002 +3.3V_M page 23

CPU/PCH XDP Port +1.05V_VCCP page 8,15

Clock Generator SLG8SP585 +3.3V_RUN page6

FAN R3P TPF3000 +FAN1_VOUT page 23

eDP CONN +5V_ALW +PWR_SRC +3.3V_RUN page 24

DP Repeater DP119 +3.3V_RUN page 24

eDP

Auburndale 4MB (Socket G1) PGA CPU 988A pins
+VCC_CORE
+1.5V_MEM
+1.05V_RUN_VTT
+VCC_GFXCORE
page 7-12

Memory BUS (DDR3) +1.5V_MEM 800Mhz/1066MHz

DDRIII-DIMM X2
BANK 0, 1, 2, 3, 4 ,5 ,6 ,7 ,8
page 13,14
+1.5V_MEM
+V_DDR_REF

CRT CONN +5V_RUN page 27

Video Switch PI3V712-AZLE +3.3V_RUN page 27

VGA

FDI Lane x 8

DMI Lane x 4

USB[11]

Camera +5V_RUN page 24

Trough eDP Cable

DP Repeater PS8121 +3.3V_RUN page 26

DPD
DPC
DPB

INTEL IBEXPEAK-M 1060pin BGA
+1.8V_RUN
+1.05V_RUN_VTT
+1.05V_M
+3.3V_ALW_ICH
page 15-22

SATA Repeater SN75LVCP412 +3.3V_RUN page 37

SATA4

USB[2,3] L SIDE

E-SATA

USB Ports X2 +5V_ALW page 37

USB2 : Left side pair top
USB3 Rear Right pair bottom

DP CONN +5V_RUN page 26

48MHz

USB[0,10] R SIDE

USB Ports X2 +5V_ALW page 37

USB0 : Right side pair top
USB1 : Right side pair bottom
On IO/B

DOCKING PORT page 368

DAI
USB[8,9]
SATA5
DOCK LPC BUS

On IO/B

IEEE1394 page 33

PCMCIA SLOT +3.3V_RUN page 34

SD/MMC CONN +3.3V_RUN page 33

CardBus R5U242 +3.3V_RUN page 33-34

PCIE3

PCIE

+1.05V_RUN_VTT /100MHz

HD Audio I/F

Intel Hanksville 82577LM
+3.3V_LAN
+1.0V_LAN page 30

+1.05V_RUN_VTT /100MHz

PCI Express BUS

S-ATA 0/1/4/5 3GB/s

SPI

PCIE5

PCIE2

PCIE1

Option

EXPRESS Card +3.3V_RUN page 35

SATA/PCIE MUX PI2DBS212

Mini Card2 WLAN +3.3V_WLAN +1.5V_RUN page 36

Mini Card 1 WWAN +3.3V_RUN_WWAN_PWR +1.5V_RUN page 36

China TPM1.2 SSX35BCB page 32

W25Q64VSSIG +3.3V_M page 15
64M 4K sector

W25X64VSSIG +3.3V_M page 15
32M 4K sector

SATA1

SATA0

E-Module +5V_MOD page 28

SATA Repeater SN75LVCP412 +3.3V_RUN page 28

S-HDD +5V_HDD +3.3V_HDD page 28

Azalia Codec 92HD81B1 +3.3V_RUN +5V_RUN page 29

INT.Speaker page 29

LAN SWITCH PI3L720 +3.3V_LAN pg 30

HeadPhone & MIC Jack +3.3V_RUN

RJ45

WiFi ON/OFF

On IO/B

USB[7]

USB[4]

USB[5]

Mini Card 3 PCIE\BKT +3.3V_RUN +1.5V_RUN page 36

USH TPM1.2 BCM5882 +3.3V_RUN +2.5V_RUN +1.2V_RUN page 31,32

LPC BUS +3V_RUN 33MHz

Smart Card page 32

TDA8034HN +5V_RUN +3.3V_RUN page 32

USB[13]

RFID page 33

USBH

USB[1]

SMSC KBC MEC5045 +RTC_CELL +3.3V_ALW page 40

DOCK LPC BUS

BC BUS

SMSC SIO ECE5028 +3.3V_ALW page 39

MDC +3V_SUS page 34

On IO/B

RJ11

Trough Cable

TI TLV320AIC3004 +3.3V_RUN page 29

DOCK

Dig. MIC

Trough LVDS Cable

SATA Repeater SN75LVCP412 +3.3V_RUN page 35

SATA2

SMBUS

Trough Cable

Biometric +3.3V_RUN page 36

Touch Pad

Stick

page 40

BC BUS

ECE1077 +3.3V_ALW

Int.KBD & Stick

+VCC_GFXCORE page 53

0.75V page 49

VCORE (IMVP-6) page 51

3V/5V page 47

PWR SELECT page 54

1.1V page 50

CHARGER page 52

1.5V page 48

DC IN & BATT IN page 46

Power On/Off SW & LED page 42

DC/DC Interface page 41

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Compal Electronics, Inc.

Title: Block Diagram

Size | Document Number: LA-5571P | Rev: 0.1

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POWER STATES

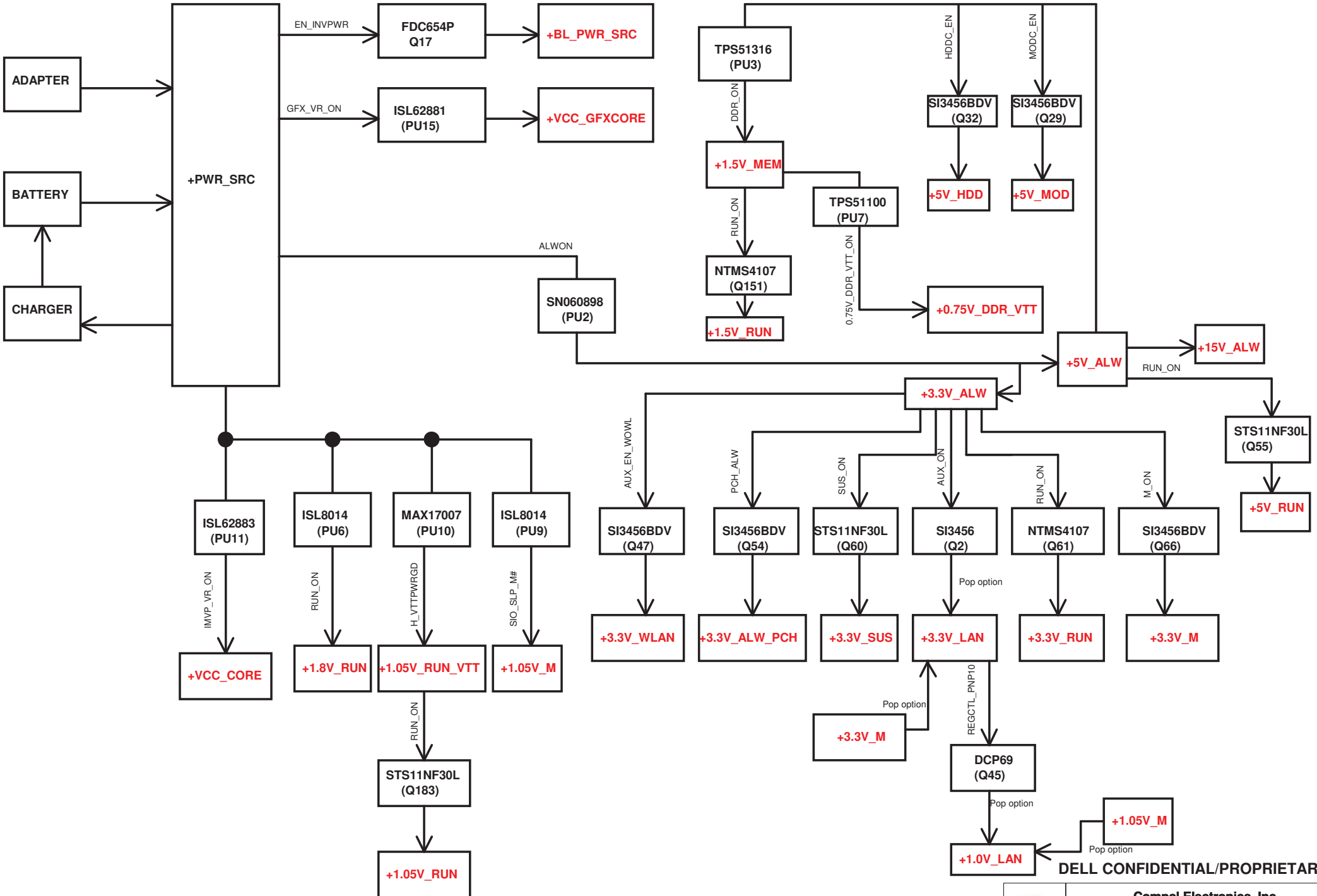
Signal / State	SLP S3#	SLP S4#	SLP S5#	S4 STATE#	SLP M#	ALWAYS PLANE	M PLANE	SUS PLANE	RUN PLANE	CLOCKS
S0 (Full ON) / M0	HIGH	HIGH	HIGH	HIGH	HIGH	ON	ON	ON	ON	ON
S3 (Suspend to RAM) / M1	LOW	HIGH	HIGH	HIGH	HIGH	ON	ON	ON	OFF	OFF
S4 (Suspend to DISK) / M1	LOW	LOW	HIGH	LOW	HIGH	ON	ON	OFF	OFF	OFF
S5 (SOFT OFF) / M1	LOW	LOW	LOW	LOW	HIGH	ON	ON	OFF	OFF	OFF
S3 (Suspend to RAM) / M-OFF	LOW	HIGH	HIGH	HIGH	LOW	ON	OFF	ON	OFF	OFF
S4 (Suspend to DISK) / M-OFF	LOW	LOW	HIGH	LOW	LOW	ON	OFF	OFF	OFF	OFF
S5 (SOFT OFF) / M-OFF	LOW	LOW	LOW	LOW	LOW	ON	OFF	OFF	OFF	OFF

PM TABLE

power plane / State	+15V_ALW +5V_ALW +3.3V_ALW_PCH +3.3V_RTC_LDO	+3.3V_SUS +1.5V_MEM	+5V_RUN +3.3V_RUN +1.8V_RUN +1.5V_RUN +0.75V_DDR_VTT +VCC_CORE +1.05V_RUN_VTT +1.05V_RUN	+3.3V_M +1.05V_M	+3.3V_M +1.05V_M (M-OFF)
S0	ON	ON	ON	ON	ON
S3	ON	ON	OFF	ON	OFF
S5 S4/AC	ON	OFF	OFF	ON	OFF
S5 S4/AC don't exist	OFF	OFF	OFF	OFF	OFF

	USB PORT#	DESTINATION
PCH	0	JUSB1 (Ext Right Side Bottom)
	1	JUSB1 (Ext Right Side Top)
	2	JESA1 (Ext Left Side Top)
	3	JESA1 (Ext Left Side Bottom)
	4	WLAN
	5	WWAN
	6	Bluetooth
	7	USH->BIO
	8	DOCKING
	9	DOCKING
	10	Express card
	11	Camera
	12	NA
	13	WPAN/NVMHCI

PCI EXPRESS	DESTINATION
Lane 1	MINI CARD-1 WWAN
Lane 2	MINI CARD-2 WLAN
Lane 3	Card Bus
Lane 4	EXPRESS CARD
Lane 5	MINI CARD-3 PCIE/BKT
Lane 6	10/100/1G LAN
Lane 7	None
Lane 8	None



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Title	Power Rail
Size	Document Number: LA-5571P
Rev	0.1
Date:	Thursday, January 21, 2010
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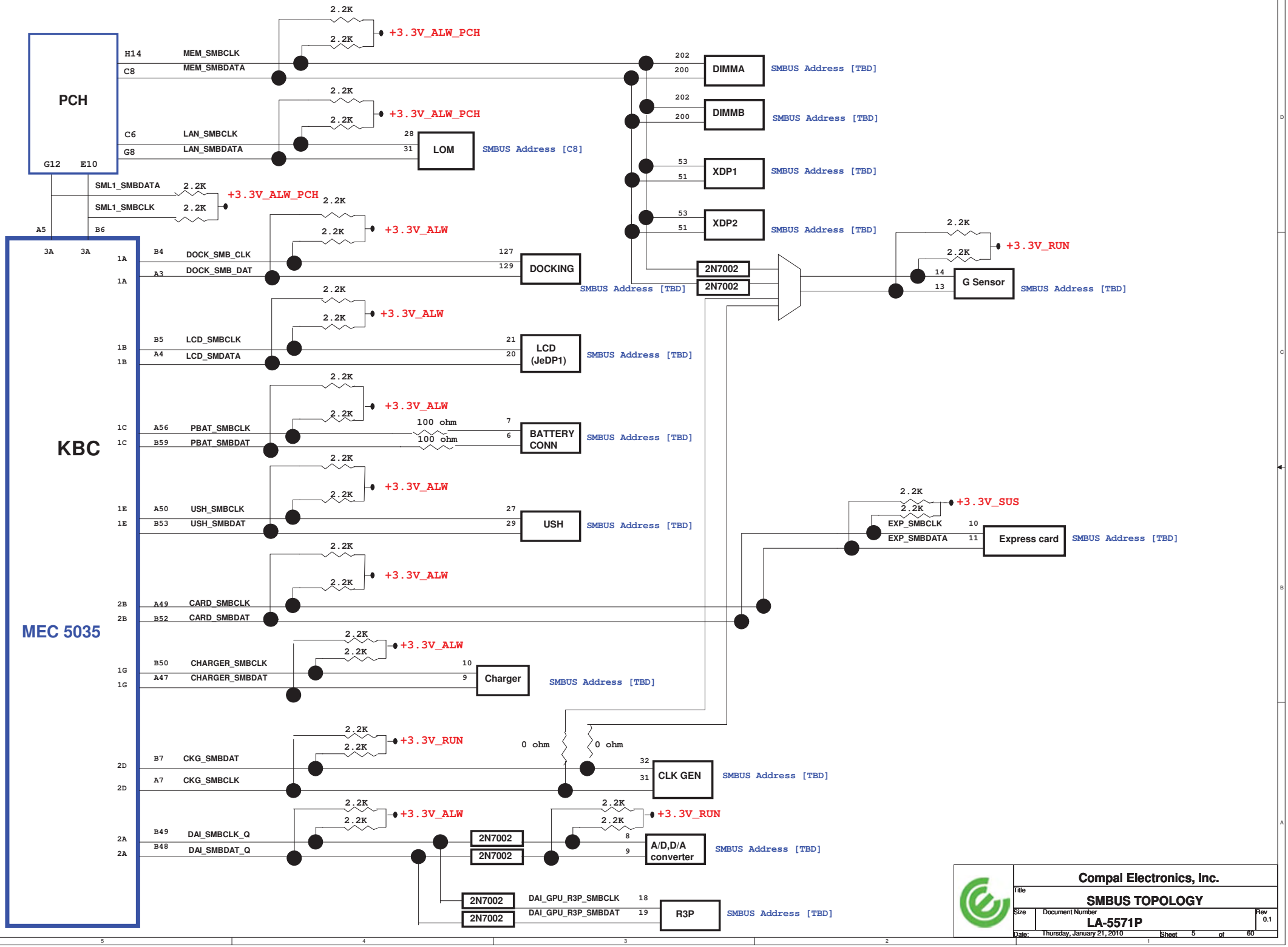

Compal Electronics, Inc.	
Title	SMBUS TOPOLOGY
Size	Document Number: LA-5571P
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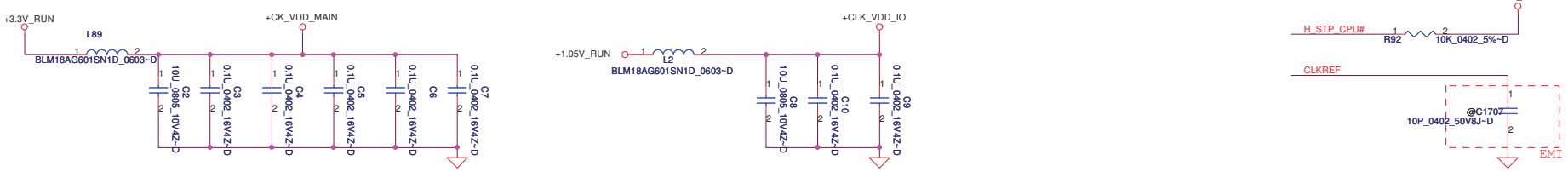
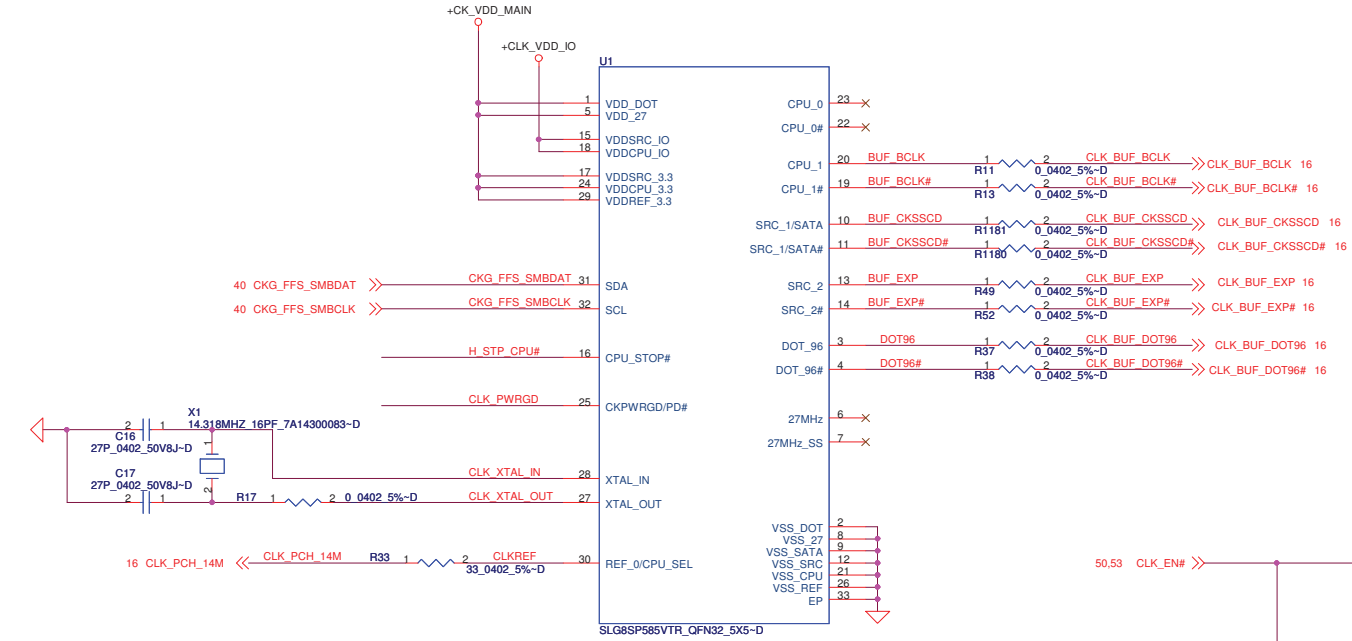
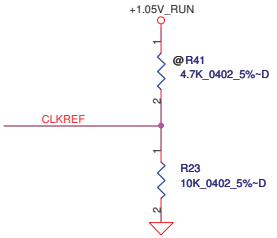
+CLK_VDD_IO CAN BE RANGE FROM 1.05V TO 3V

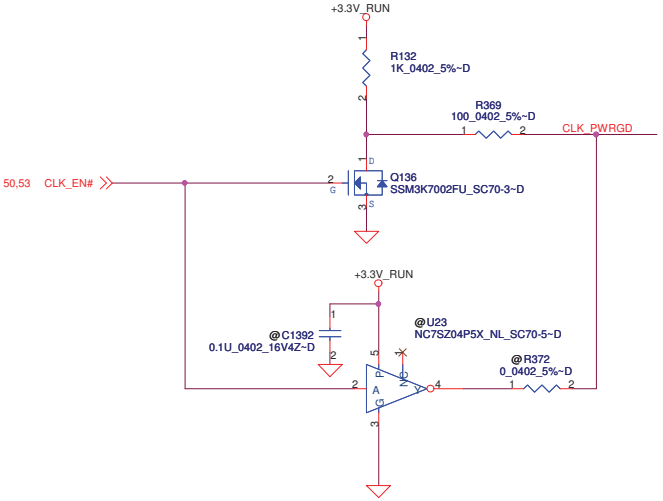






REF_O/CPU_SEL

PIN 30	CPU0	CPU1
1(0.7~1.5v)	100MHz	100MHz
0 (DEFULT)	133MHz	133MHz

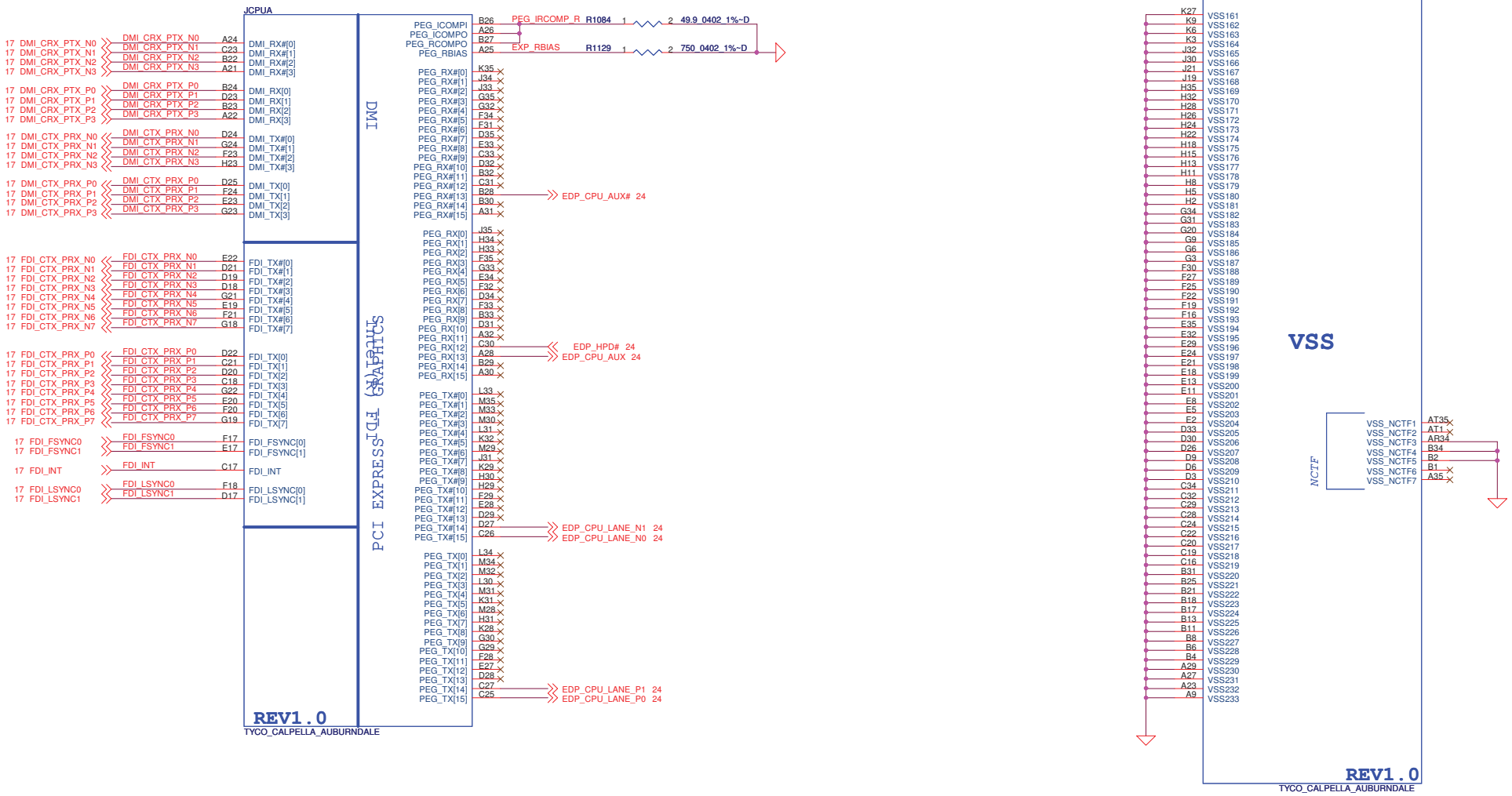


Compal Electronics, Inc.

Title: Clock Generator

Size | Document Number: LA-5571P | Rev: 0.1

Date: Thursday, January 21, 2010 | Sheet 6 of 60

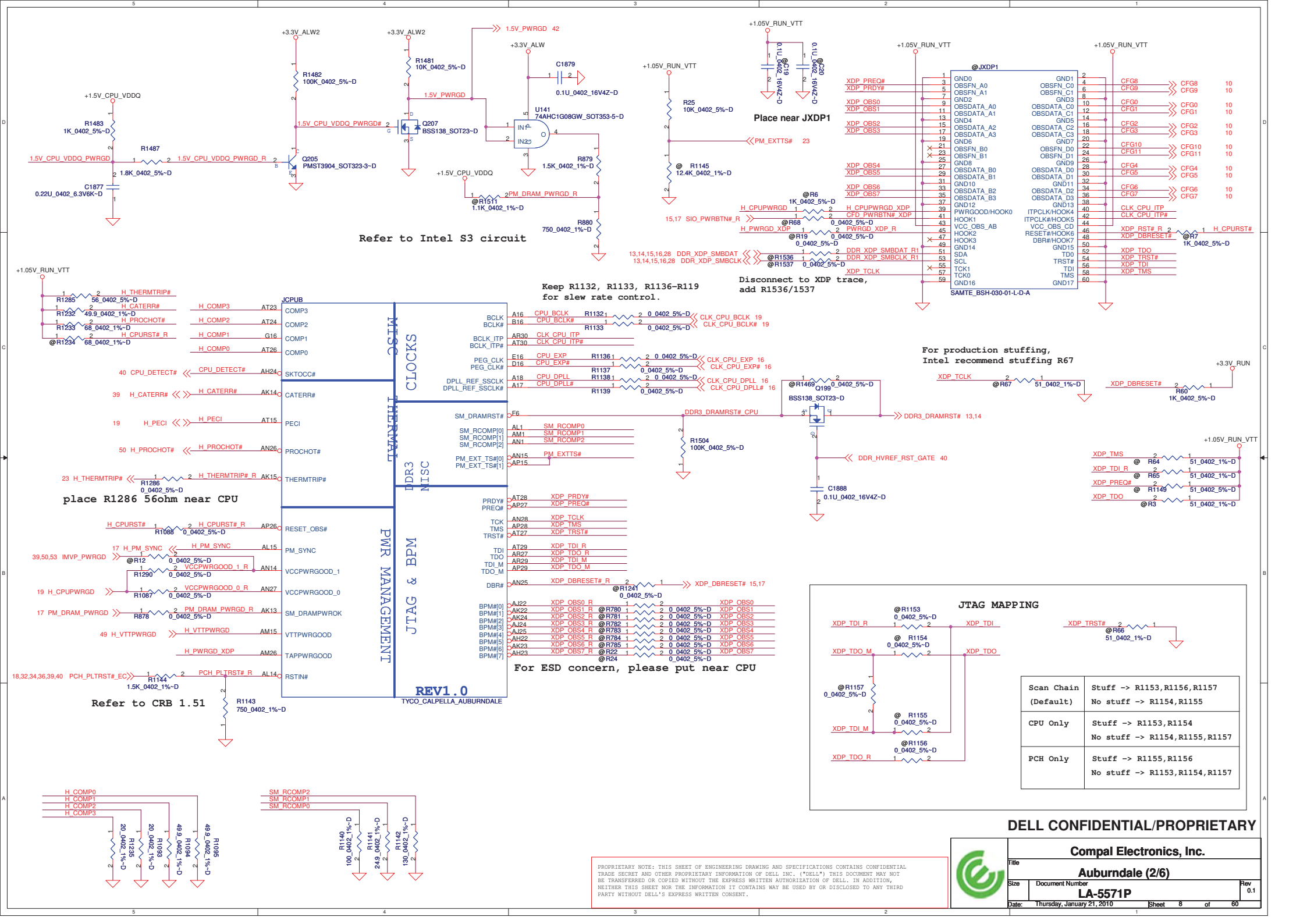


Compal Electronics, Inc.

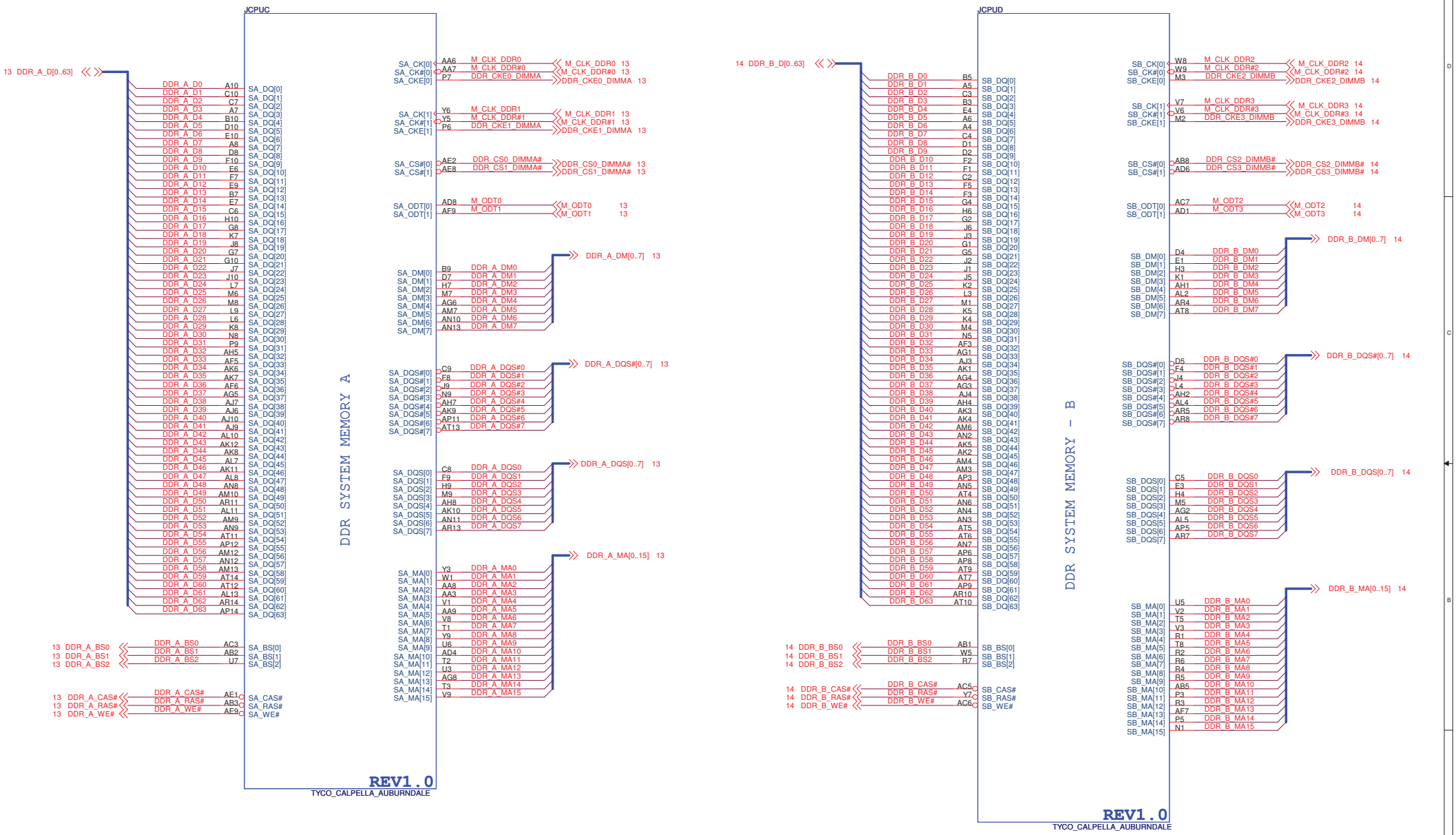
Title: Auburndale (1/6)

Size | Document Number: LA-5571P | Rev: 0.1

Date: Thursday, January 21, 2010 | Sheet 7 of 60



Scan Chain (Default)	Stuff -> R1153,R1156,R1157 No stuff -> R1154,R1155
CPU Only	Stuff -> R1153,R1154 No stuff -> R1154,R1155,R1157
PCH Only	Stuff -> R1155,R1156 No stuff -> R1153,R1154,R1157



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Title	Auburndale (3/6)
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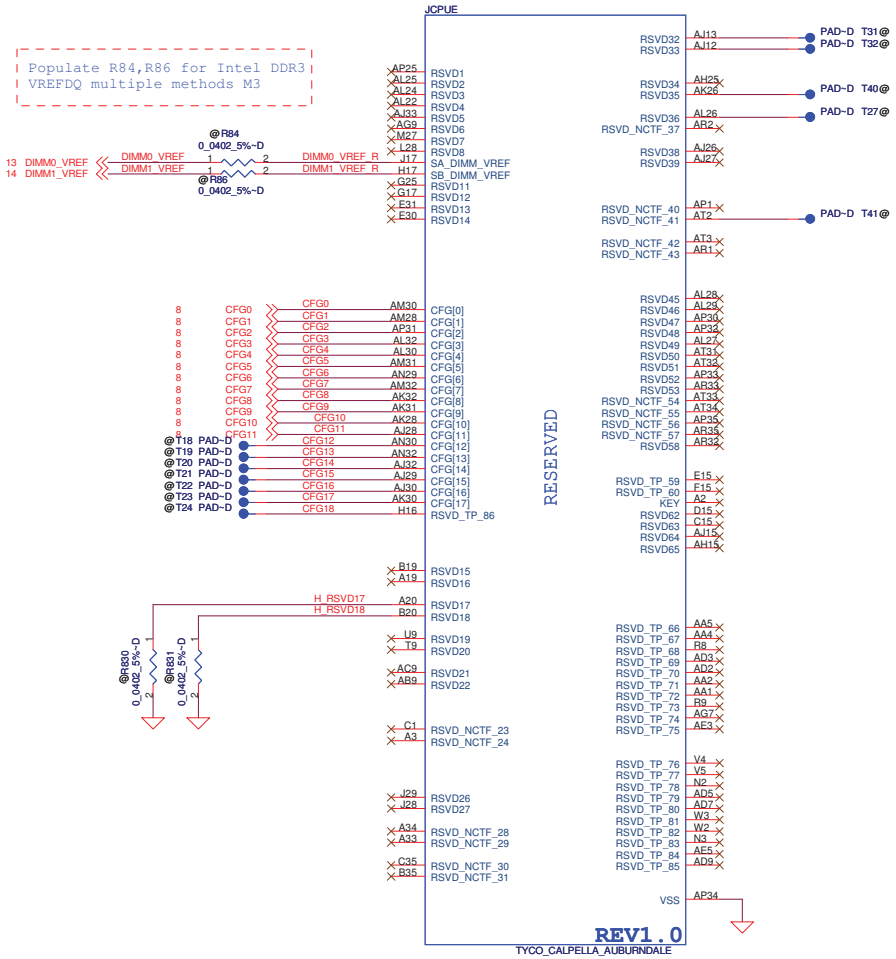
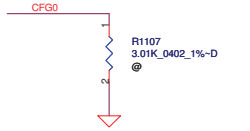
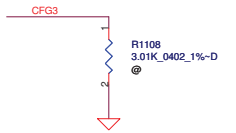
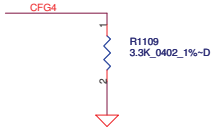




PCI-Express Configuration Select	
CFG0	1 : Single PEG 0 : Bifurcation enable



PCI-Express Static Lane Reversal	
CFG3	1 : Normal Operation 0 : Lane Number Reversed 15->0, 14->1 ...



Display Port Presence	
CFG4	1 : Disabled; No Physical Display Port attached to Embedded Display Port 0 : Enabled; An external Display Port device is connected to the Embedded Display Port

Compal Electronics, Inc.

Title: Auburndale (4/6)

Size | Document Number: LA-5571P | Rev: 0.1

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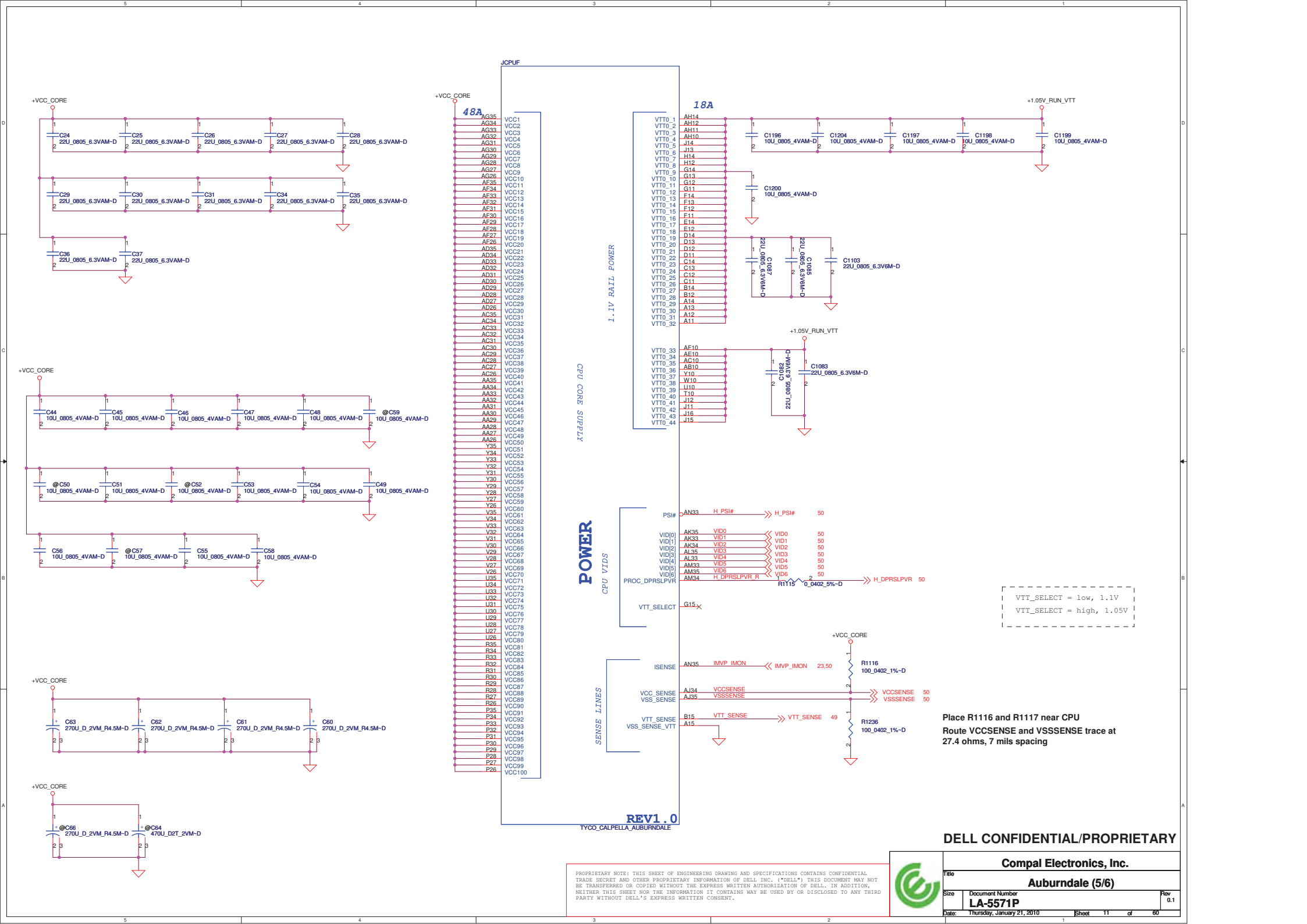

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Title	Auburndale (5/6)
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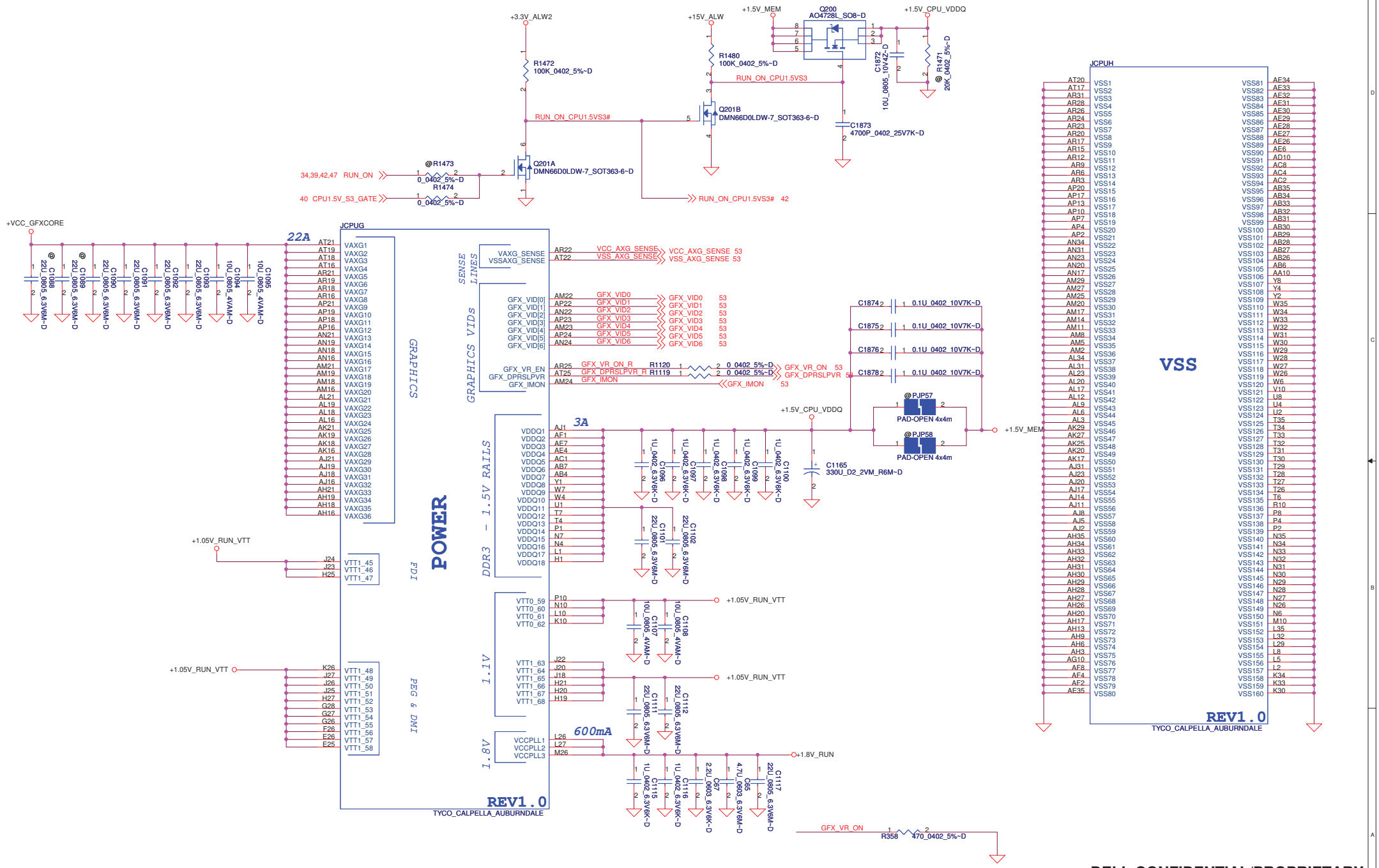
+1.5V_CPU_VDDQ Source



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Title	Auburndale (6/6)
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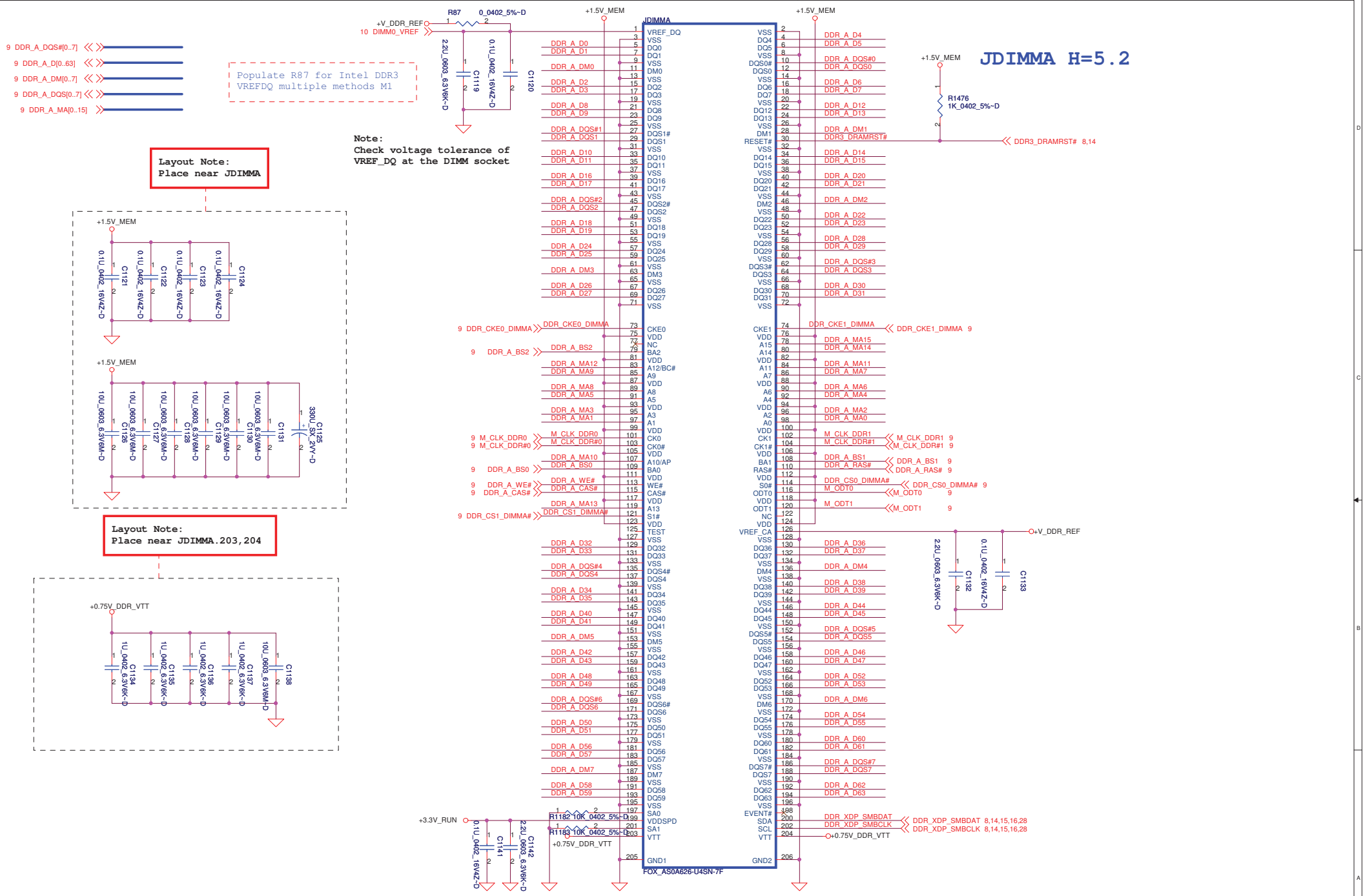

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Title: DDRIII-SODIMM SLOT1

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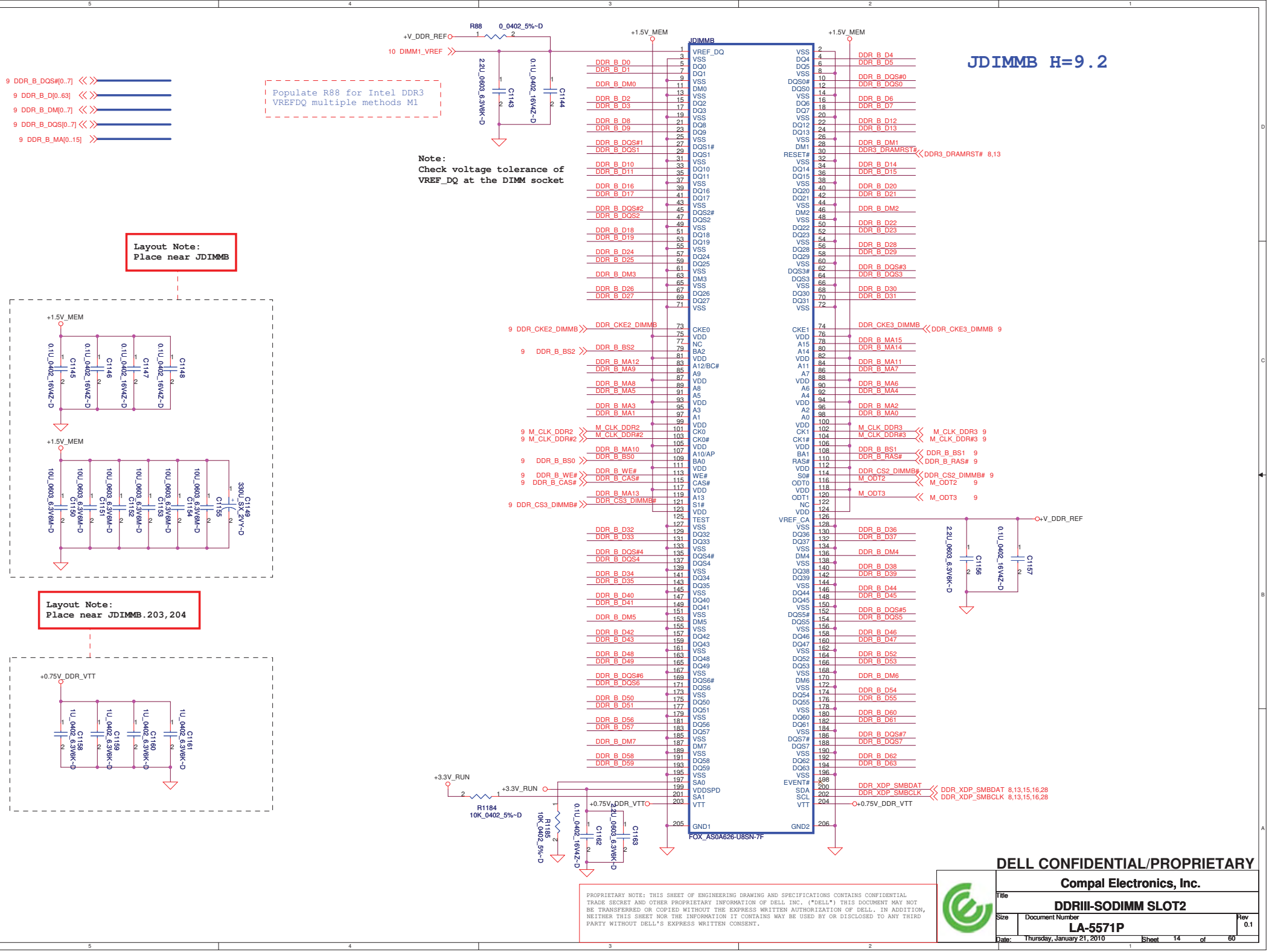

Compal Electronics, Inc.

Title: DDRIII-SODIMM SLOT2

Size | Document Number: LA-5571P | Rev: 0.1

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CMOS_CLR1	CMOS setting
Shunt	Clear CMOS
Open	Keep CMOS

ME_CLR1	TPM setting
Shunt	Clear ME RTC Registers
Open	Keep ME RTC Registers

INTVRMEN- Integrated SUS 1.1V VRM Enable
High - Enable Internal VRs

On Die PLL VR is supplied by 1.5V when sampled high, 1.8 V when sampled low

Disconnect to XDP trace, add R1532/1533

CMOS place near DIMM

Stuff R128,no stuff R123 when production

200 MIL SO8
64Mb Flash ROM
For iAMT

200 MIL SO8
32Mb Flash ROM

		PCH JTAG Enable		PCH JTAG Disable		Production
PCH Pin	Ref.	ES1	ES2	ES1	ES2	All
TDO	R806	No Stuff	200 ohm	No Stuff	No Stuff	No Stuff
	R1315	No Stuff	100 ohm	No Stuff	No Stuff	No Stuff
TMS	R807	200 ohm	200 ohm	No Stuff	No Stuff	No Stuff
	R1281	100 ohm	100 ohm	No Stuff	No Stuff	No Stuff
TDI	R805	200 ohm	200 ohm	20K ohm	No Stuff	No Stuff
	R1282	100 ohm	100 ohm	10K ohm	No Stuff	No Stuff
TCK	R804	4.7K ohm	4.7K ohm	4.7K ohm	4.7K ohm	No Stuff
TRST#	R808	20K ohm	20K ohm	No Stuff	No Stuff	
	R1316	10K ohm	10K ohm	No Stuff	No Stuff	

No Reboot Strap	
SPKR	Low = Default
	High = No Reboot

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Compal Electronics, Inc.

Title: PCH (1/8)

Size: | Document Number: LA-5571P | Rev: 0.1

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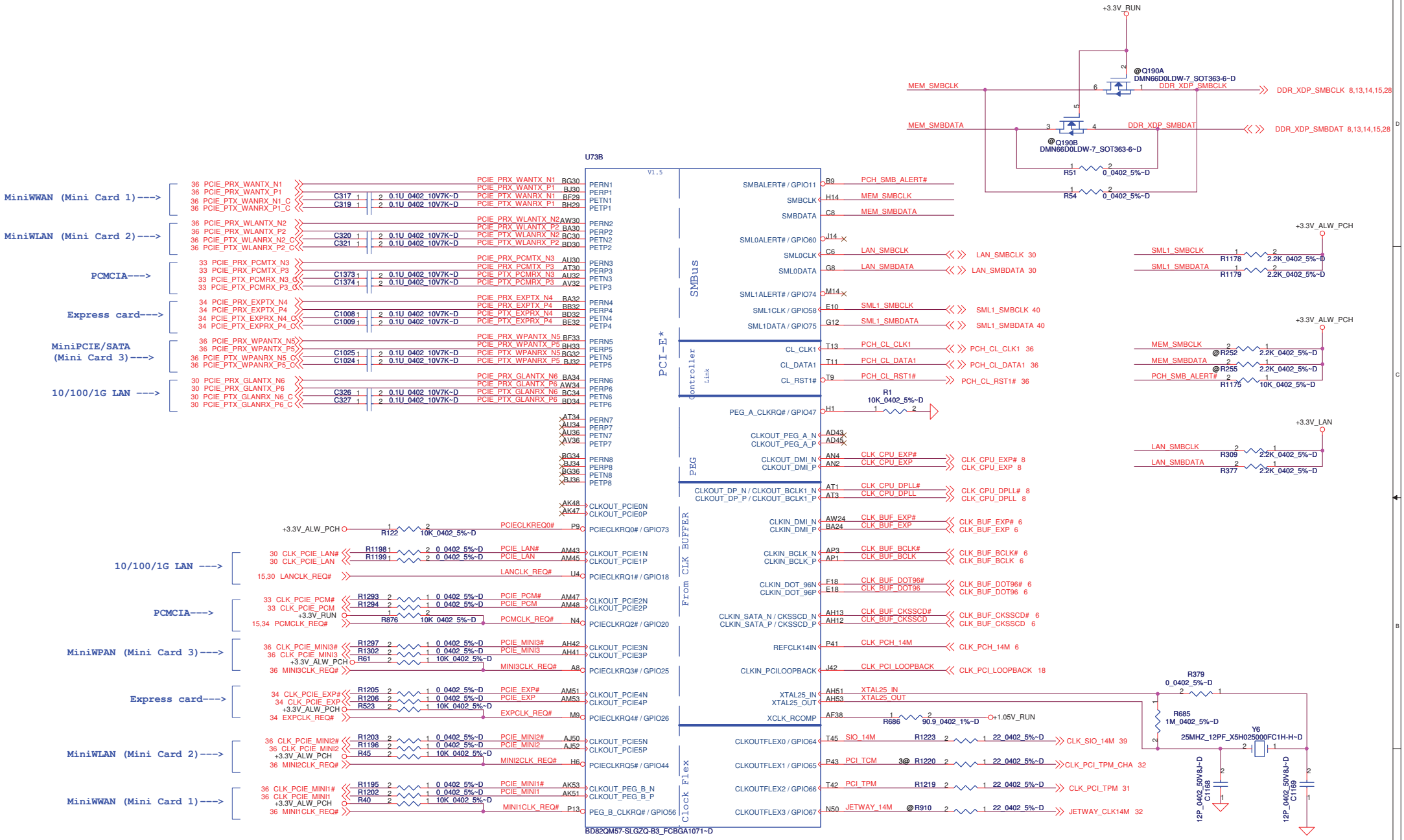

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Compal Electronics, Inc.	
Title	PCH (2/8)
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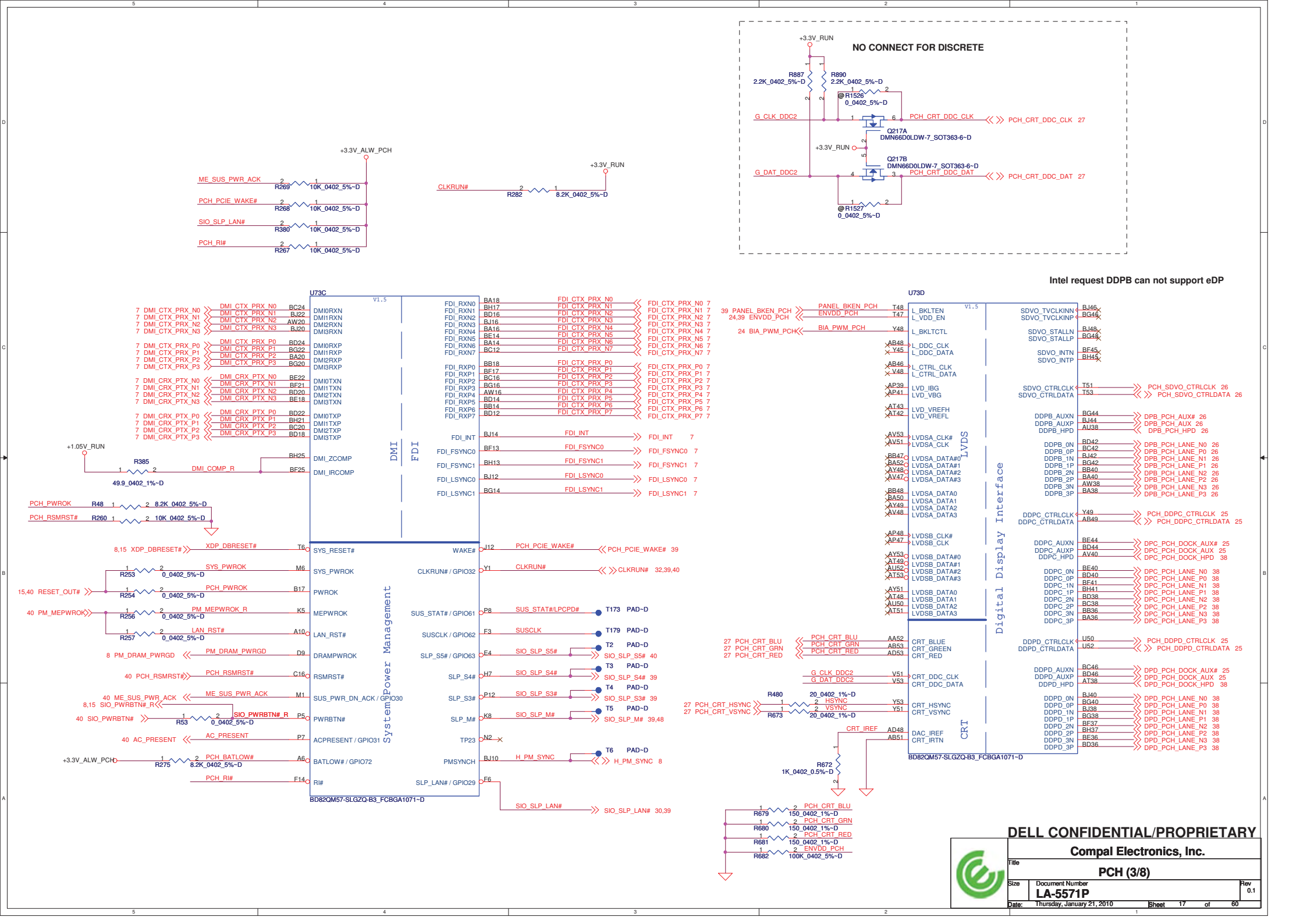

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Title: PCH (3/8)		
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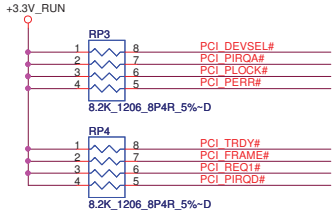
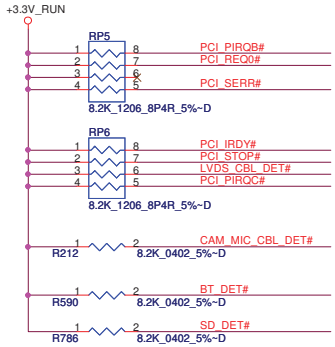
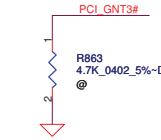
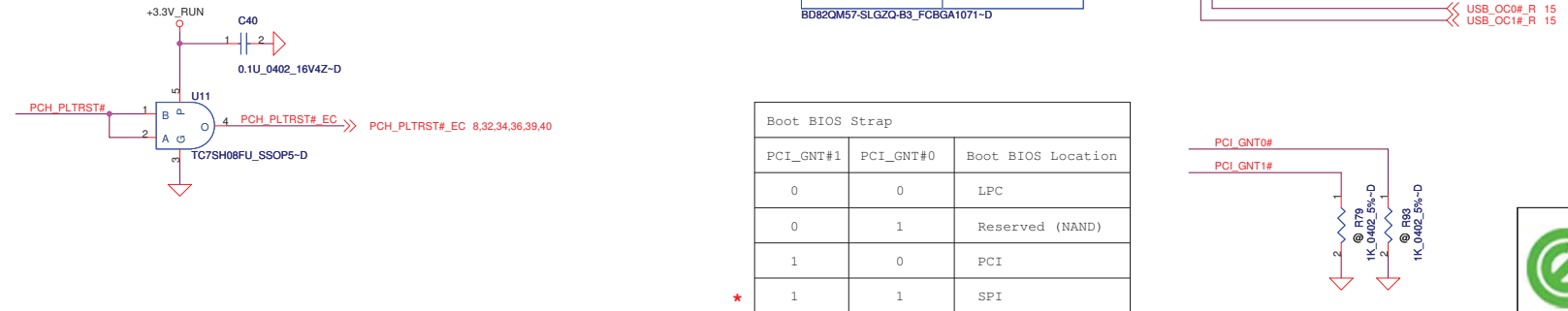
PCH XDP ENABLE	Stuff: R78,R89,R101~R116
	No Stuff: R71,R77,RP1,RP2,R45,R40,R131,R58,R1242,R1243,R1244,R1245,R74,R130
PCH XDP DISABLE	Stuff: R71,R77,RP1,RP2,R45,R40,R131,R58,R1242,R1243,R1244,R1245,R74,R130
	No Stuff: R78,R89,R101~R116



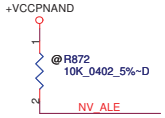




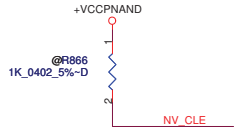
A16 swap override Strap/Top-Block	
Swap Override jumper	
PCI_GNT#3	Low = A16 swap High = Default



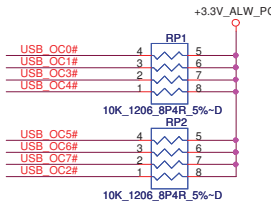
Boot BIOS Strap		
PCI_GNT#1	PCI_GNT#0	Boot BIOS Location
0	0	LPC
0	1	Reserved (NAND)
1	0	PCI
1	1	SPI



Danbury Technology Enabled	
NV_ALE	High = Enabled (Default) Low = Disabled



DMI Termination Voltage	
NV_CLE	Set to Vss when LOW Set to Vcc when HIGH



->Right Side Bottom
->Right Side Top
->Left Side Top
->Left Side Bottom
->WLAN
->WWAN
->Blue Tooth
->BIO
->DOCK
->DOCK
->Express Card
->Camera

->PCIE/BKT

Within 500 mils

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Title	PCH (4/8)	
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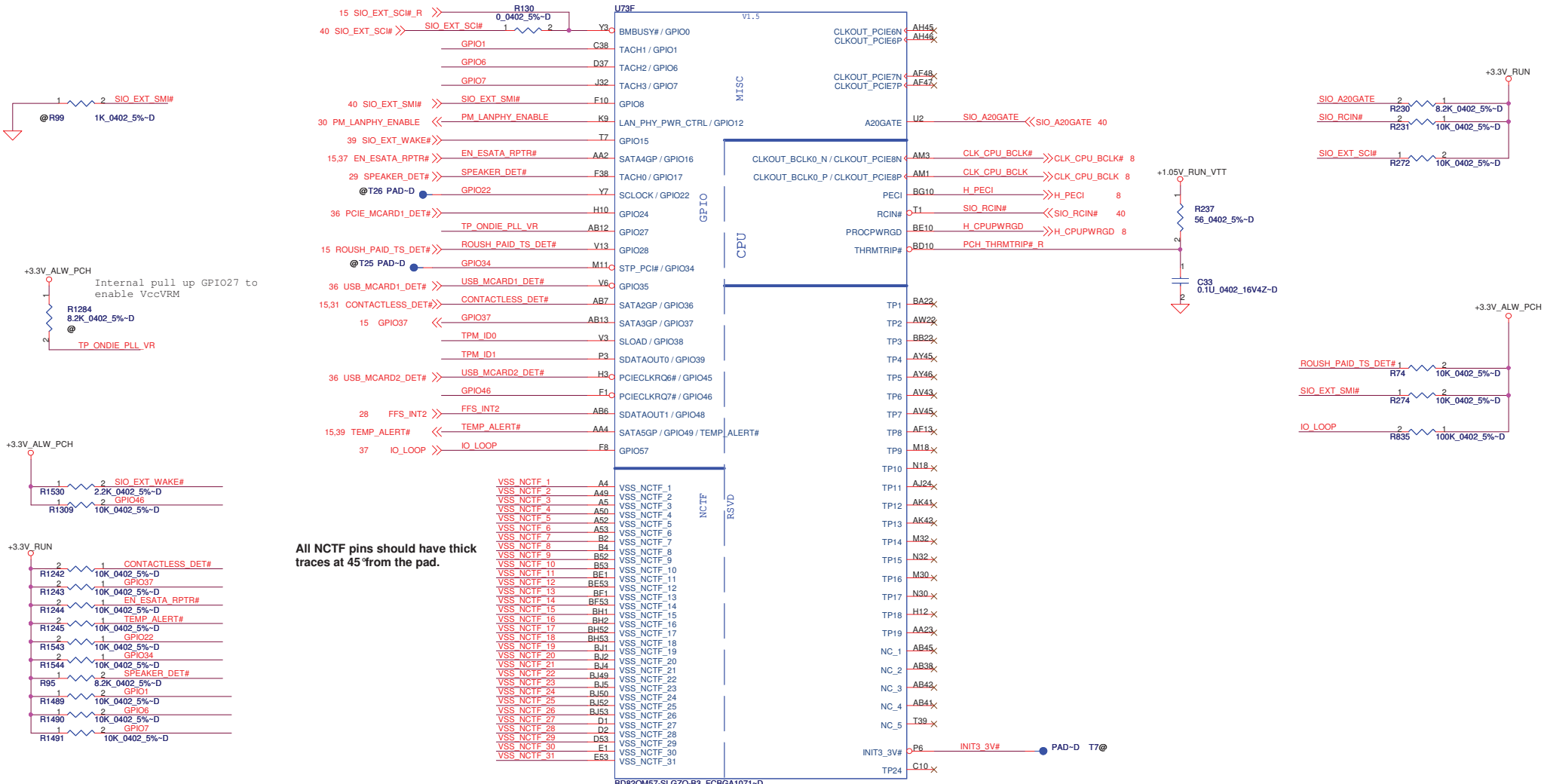

	TPM_ID0	TPM_ID1
China TPM	0	0
No TPM, No China TPM	0	1
USH1.0 (For SSI)	1	0
USH2.0	1	1

-----> will use MEMO control pop R339 & de-pop R787 when USH1.0 enable for SSI build only

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Title: PCH (5/8)

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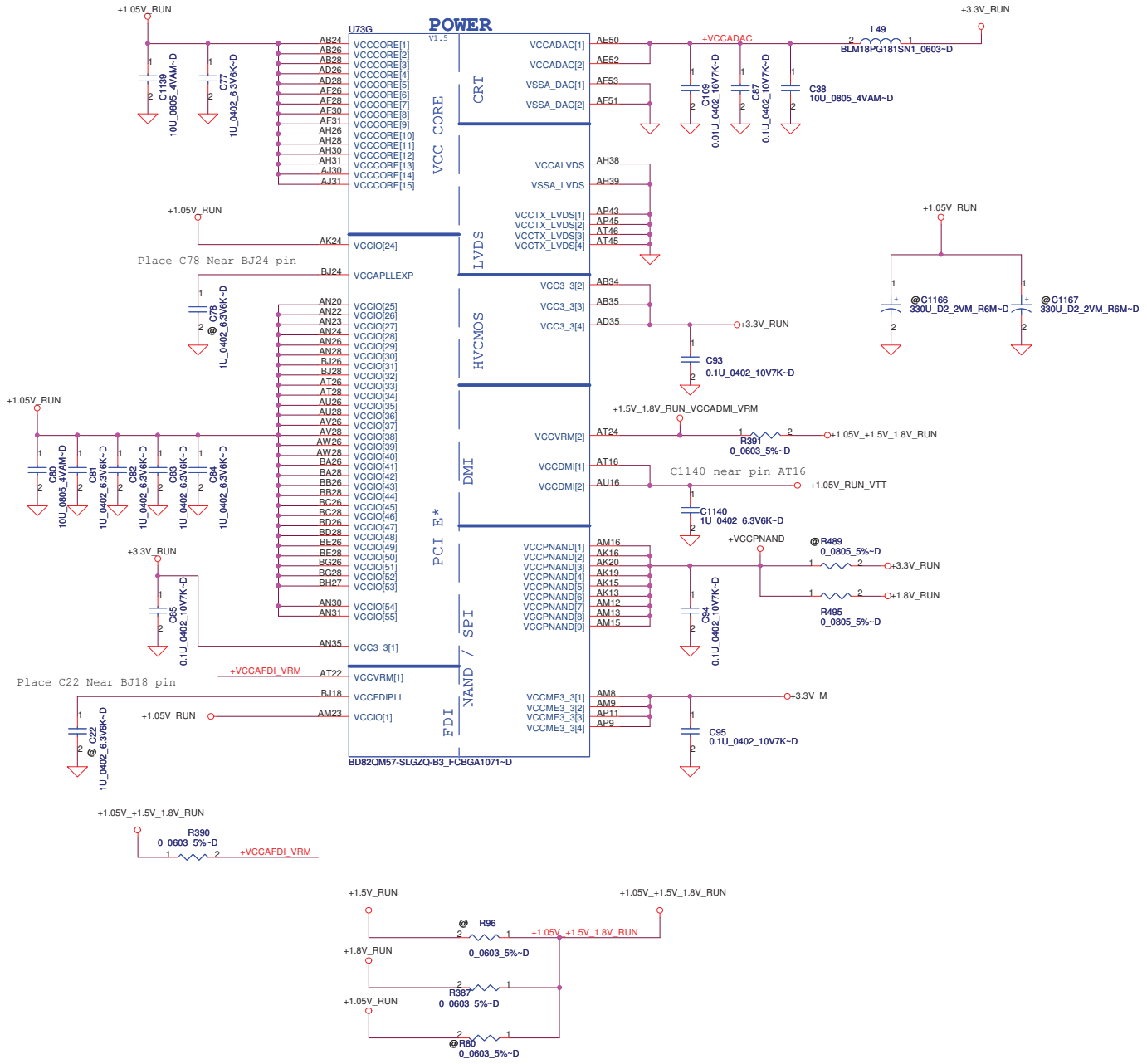
Date: Thursday, January 21, 2010 | Sheet 19 of 60



PCH Power Rail Table

Voltage Rail	Voltage	S0 Iccmax Current (A)
V_CPU_IO	1.1/1.05	< 1 (mA)
V5REF	5	< 1 (mA)
V5REF_Sus	5	< 1 (mA)
Vcc3_3	3.3	0.357
VccAClk	1.1	0.052
VccADAC	3.3	0.069
VccADPLLA	1.1	0.068
VccADPLLB	1.1	0.069
VccapllEXP	1.1	0.04
VccCore	1.1	1.432
VccDMI	1.1	0.058
VccDMI	1.1	0.061
VccFDIPLL	1.1	0.037
VccIO	1.1	3.062
VccLAN	1.1	0.32
VccME	1.1	1.849
VccME3_3	3.3	0.085
VccpNAND	1.8	0.156
VccRTC	3.3	2 (mA)
VccSATAPLL	1.1	0.031
VccSus3_3	3.3	0.163
VccSusHDA	3.3	0.006
VccVRM	1.8 / 1.5	0.196
VccVRM	1.05	< 1 (mA)
VccALVDS	3.3	< 1 (mA)
VccTX_LVDS	1.8	0.059

Compal Electronics, Inc.

Title: PCH (6/8)

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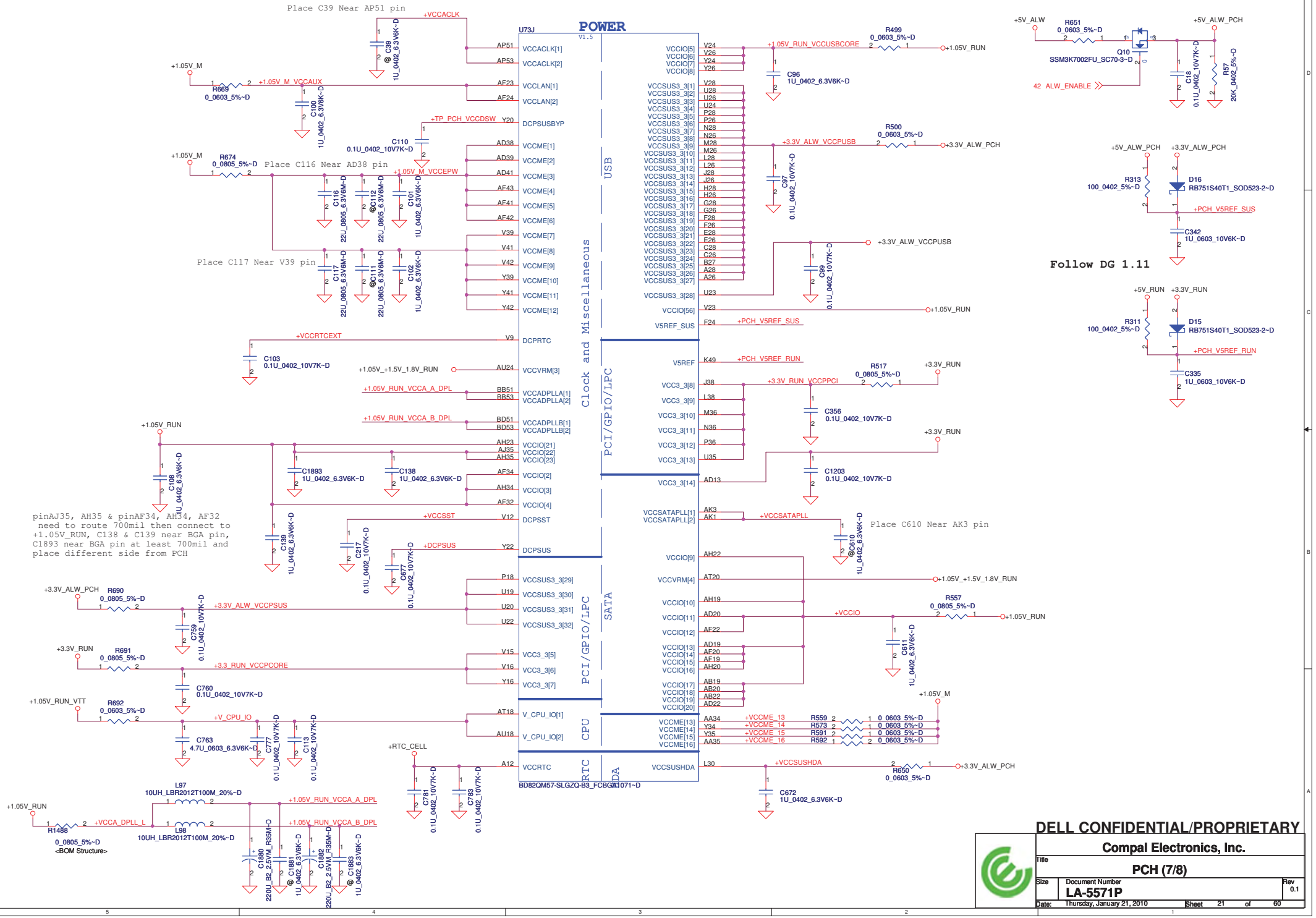
POWER
U73J
Clock and Miscellaneous
USB
PCI/GPIO/LPC
SATA
CPU
RTC
SMB/DA
BD82QM57-SLGZQ-B3_FCBGA1071~D
Place C39 Near AP51 pin
Place C116 Near AD38 pin
Place C117 Near V39 pin
pinAJ35, AH35 & pinAF34, AH34, AF32 need to route 700mil then connect to +1.05V_RUN, C138 & C139 near BGA pin, C1893 near BGA pin at least 700mil and place different side from PCH
Place C610 Near AK3 pin
Follow DG 1.11
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Compal Electronics, Inc.
PCH (7/8)
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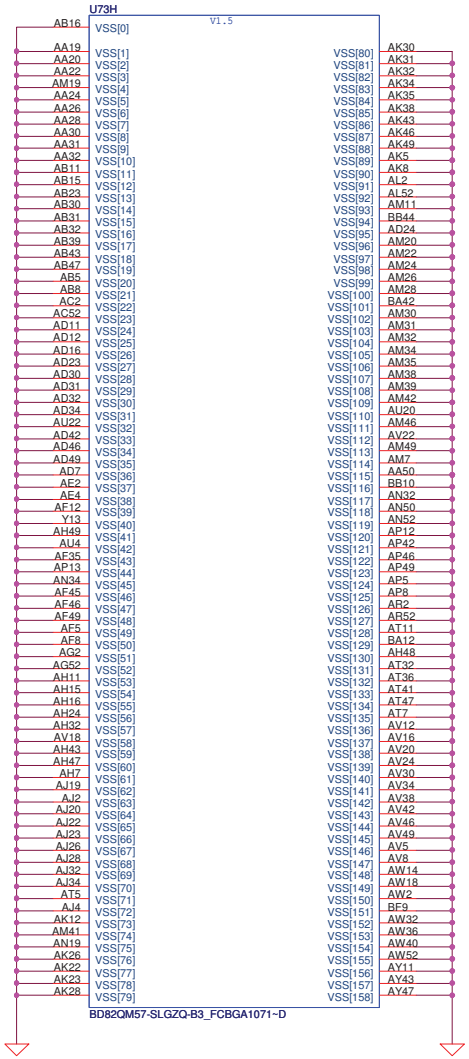

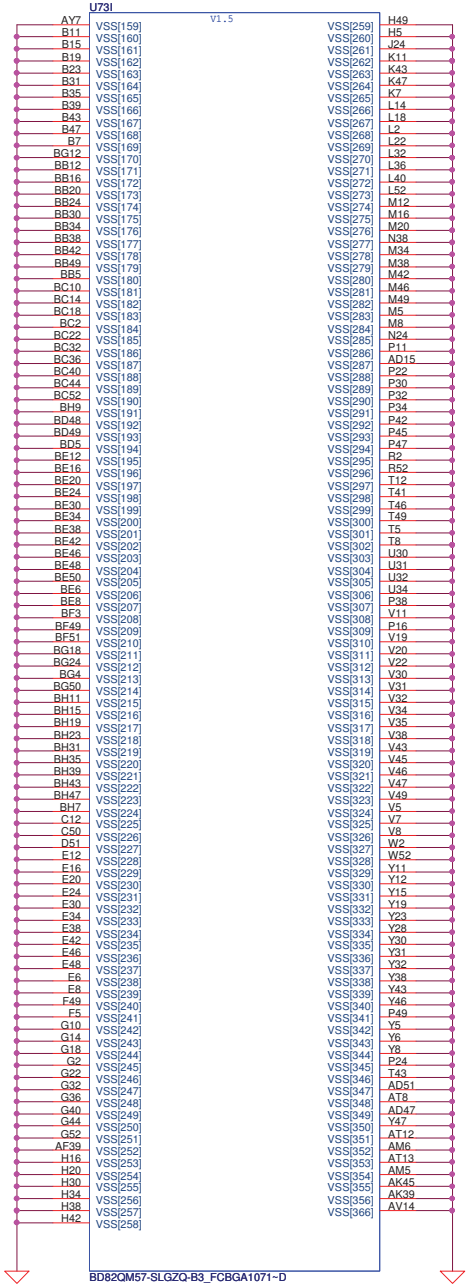

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Title: PCH (8/8)

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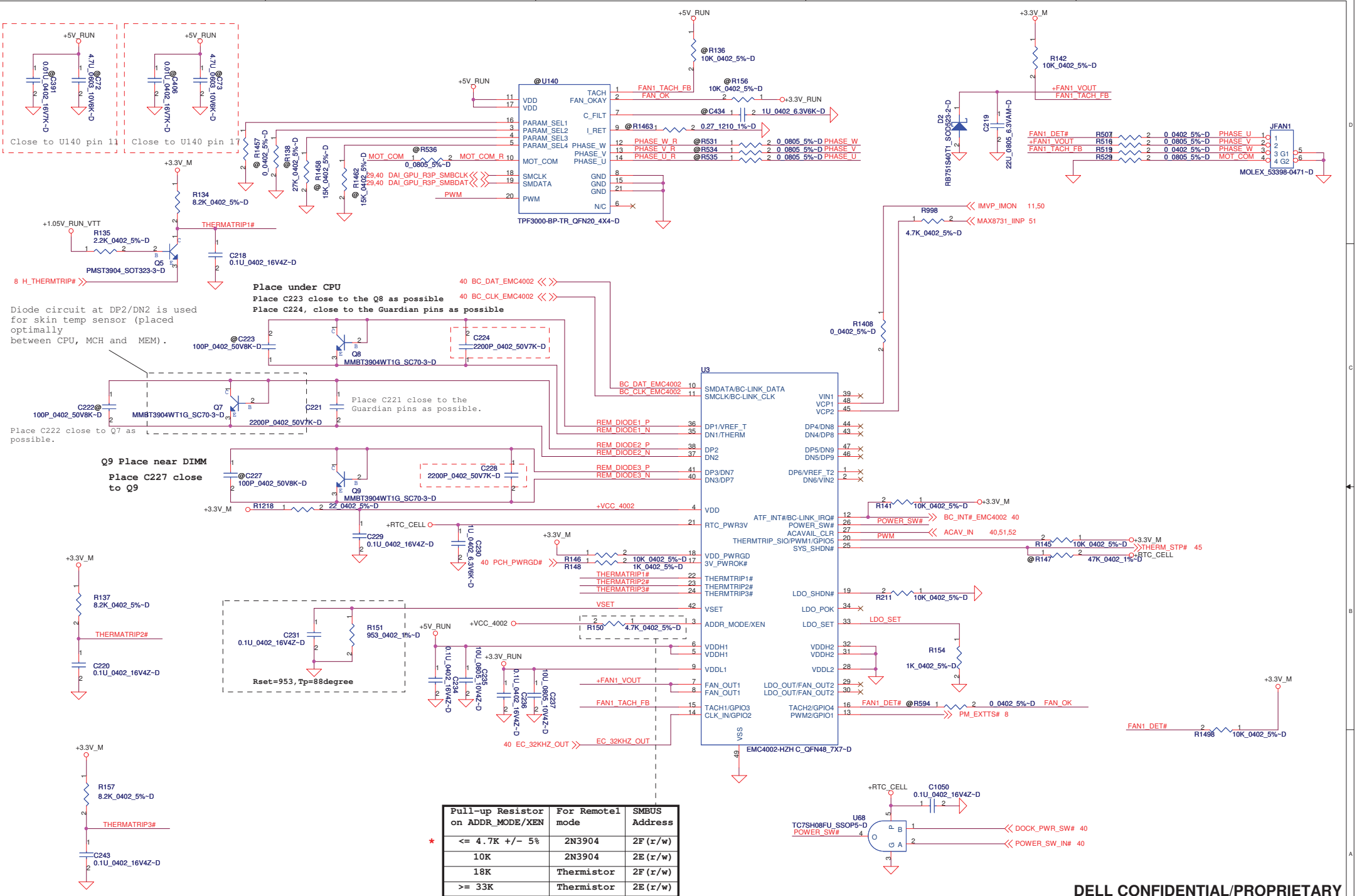

Pull-up Resistor on ADDR_MODE/XEN	For Remote1 mode	SMBUS Address
* <= 4.7K +/- 5%	2N3904	2F(r/w)
10K	2N3904	2E(r/w)
18K	Thermistor	2F(r/w)
>= 33K	Thermistor	2E(r/w)

Compal Electronics, Inc.

Title: FAN & Thermal Sensor

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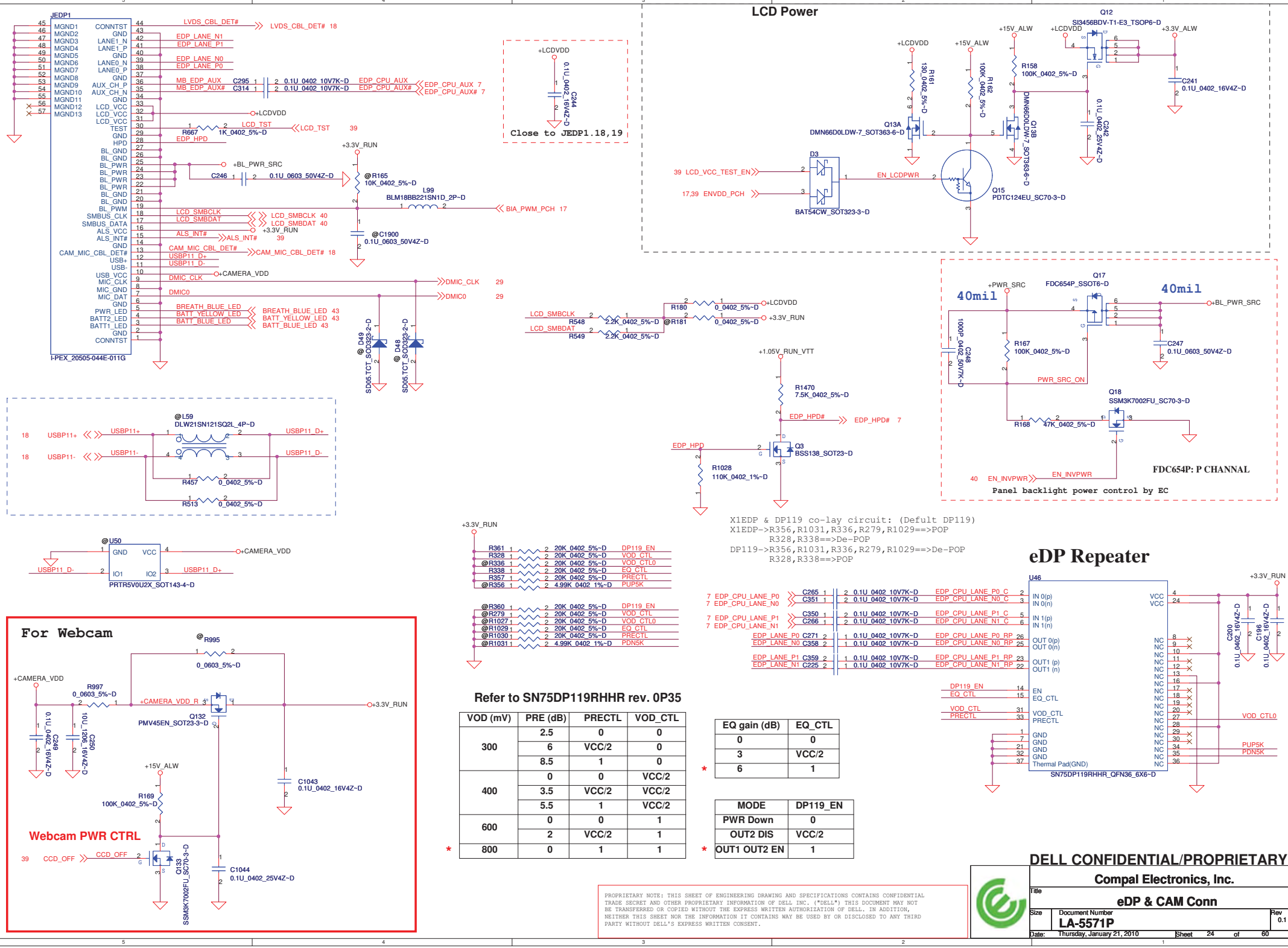
JEDP1
I-PEX_20505-044E-011G
LVDS_CBL_DET# 18
EDP_LANE_N1
EDP_LANE_P1
EDP_LANE_N0
EDP_LANE_P0
MB_EDP_AUX C295 0.1U_0402_10V7K~D EDP_CPU_AUX
MB_EDP_AUX# C314 0.1U_0402_10V7K~D EDP_CPU_AUX#
EDP_CPU_AUX 7
EDP_CPU_AUX# 7
+LCDVDD
LCD_TST
LCD_TST 39
R667 1K_0402_5%~D
EDP_HPD
+3.3V_RUN
+BL_PWR_SRC
C246 0.1U_0603_50V4Z~D
@R165 10K_0402_5%~D
L99 BLM18BB221SN1D_2P~D
BIA_PWM_PCH 17
LCD_SMBCLK
LCD_SMBDAT
LCD_SMBCLK 40
LCD_SMBDAT 40
+3.3V_RUN
ALS_INT#
ALS_INT# 39
@C1900 0.1U_0603_50V4Z~D
CAM_MIC_CBL_DET#
CAM_MIC_CBL_DET# 18
USBP11_D+
USBP11_D-
+CAMERA_VDD
DMIC_CLK
DMIC_CLK 29
DMIC0
DMIC0 29
BREATH_BLUE_LED
BATT_YELLOW_LED
BATT_BLUE_LED
BREATH_BLUE_LED 43
BATT_YELLOW_LED 43
BATT_BLUE_LED 43
@D49 SD05.TCT_SOD323-2~D
@D48 SD05.TCT_SOD323-2~D
Close to JEDP1.18,19
+LCDVDD
0.1U_0402_16V4Z~D C244
LCD Power
Q12 SI3456BDV-T1-E3_TSOP6~D
+15V_ALW
+LCDVDD
+3.3V_ALW
R161 130_0402_5%~D
R162 100K_0402_5%~D
R158 100K_0402_5%~D
C241 0.1U_0402_16V4Z~D
C242 0.1U_0402_25V4Z~D
Q13A DMN66D0LDW-7_SOT363-6~D
Q13B DMN66D0LDW-7_SOT363-6~D
39 LCD_VCC_TEST_EN
17,39 ENVDD_PCH
D3 BAT54CW_SOT323-3~D
EN_LCDPWR
Q15 PDTC124EU_SC70-3~D
R180 0_0402_5%~D
R181 0_0402_5%~D
LCD_SMBCLK R548 2.2K_0402_5%~D
LCD_SMBDAT R549 2.2K_0402_5%~D
+1.05V_RUN_VTT
R1470 7.5K_0402_5%~D
EDP_HPD#
EDP_HPD# 7
EDP_HPD
Q3 BSS138_SOT23~D
R1028 110K_0402_1%~D
Q17 FDC654P_SSOT6~D
+PWR_SRC
40mil
40mil
+BL_PWR_SRC
C248 1000P_0402_50V7K~D
R167 100K_0402_5%~D
C247 0.1U_0603_50V4Z~D
PWR_SRC_ON
Q18 SSM3K7002FU_SC70-3~D
R168 47K_0402_5%~D
40 EN_INVPWR
EN_INVPWR
FDC654P: P CHANNAL
Panel backlight power control by EC
@L59 DLW21SN121SQ2L_4P~D
18 USBP11+
18 USBP11-
USBP11+
USBP11-
USBP11_D+
USBP11_D-
R457 0_0402_5%~D
R513 0_0402_5%~D
@U50
GND
VCC
IO1
IO2
USBP11_D-
USBP11_D+
+CAMERA_VDD
PRTR5V0U2X_SOT143-4~D
+3.3V_RUN
R361 20K_0402_5%~D DP119_EN
R328 20K_0402_5%~D VOD_CTL
@R336 20K_0402_5%~D VOD_CTL0
R338 20K_0402_5%~D EQ_CTL
R357 20K_0402_5%~D PRECTL
@R356 4.99K_0402_1%~D PUP5K
@R360 20K_0402_5%~D DP119_EN
@R279 20K_0402_5%~D VOD_CTL
@R1027 20K_0402_5%~D VOD_CTL0
@R1029 20K_0402_5%~D EQ_CTL
@R1030 20K_0402_5%~D PRECTL
@R1031 4.99K_0402_1%~D PDN5K
X1EDP & DP119 co-lay circuit: (Defult DP119)
X1EDP->R356,R1031,R336,R279,R1029==>POP
R328,R338==>De-POP
DP119->R356,R1031,R336,R279,R1029==>De-POP
R328,R338==>POP
eDP Repeater
U46
7 EDP_CPU_LANE_P0
7 EDP_CPU_LANE_N0
7 EDP_CPU_LANE_P1
7 EDP_CPU_LANE_N1
C265 0.1U_0402_10V7K~D EDP_CPU_LANE_P0_C
C351 0.1U_0402_10V7K~D EDP_CPU_LANE_N0_C
C350 0.1U_0402_10V7K~D EDP_CPU_LANE_P1_C
C266 0.1U_0402_10V7K~D EDP_CPU_LANE_N1_C
EDP_LANE_P0 C271 0.1U_0402_10V7K~D EDP_CPU_LANE_P0_RP
EDP_LANE_N0 C358 0.1U_0402_10V7K~D EDP_CPU_LANE_N0_RP
EDP_LANE_P1 C359 0.1U_0402_10V7K~D EDP_CPU_LANE_P1_RP
EDP_LANE_N1 C225 0.1U_0402_10V7K~D EDP_CPU_LANE_N1_RP
IN 0(p)
IN 0(n)
IN 1(p)
IN 1(n)
OUT 0(p)
OUT 0(n)
OUT1 (p)
OUT1 (n)
DP119_EN
EQ_CTL
VOD_CTL
PRECTL
EN
EQ_CTL
VOD_CTL
PRECTL
GND
Thermal Pad(GND)
SN75DP119RHHR_QFN36_6X6~D
VOD_CTL0
PUP5K
PDN5K
C200 0.1U_0402_16V4Z~D
C196 0.1U_0402_16V4Z~D
For Webcam
@R995 0_0603_5%~D
+CAMERA_VDD
R997 0_0603_5%~D
+CAMERA_VDD_R
Q132 PMV45EN_SOT23~D
+3.3V_RUN
C249 0.1U_0402_16V4Z~D
C250 10U_1206_16V4Z~D
C1043 0.1U_0402_16V4Z~D
+15V_ALW
R169 100K_0402_5%~D
Webcam PWR CTRL
39 CCD_OFF
CCD_OFF
Q133 SSM3K7002FU_SC70-3~D
C1044 0.1U_0402_25V4Z~D
Refer to SN75DP119RHHR rev. 0P35
VOD (mV) | PRE (dB) | PRECTL | VOD_CTL
300 | 2.5 | 0 | 0
300 | 6 | VCC/2 | 0
300 | 8.5 | 1 | 0
400 | 0 | 0 | VCC/2
400 | 3.5 | VCC/2 | VCC/2
400 | 5.5 | 1 | VCC/2
600 | 0 | 0 | 1
600 | 2 | VCC/2 | 1
* 800 | 0 | 1 | 1
EQ gain (dB) | EQ_CTL
0 | 0
3 | VCC/2
* 6 | 1
MODE | DP119_EN
PWR Down | 0
OUT2 DIS | VCC/2
* OUT1 OUT2 EN | 1
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Title
eDP & CAM Conn
Size
Document Number
LA-5571P
Rev
0.1
Date: Thursday, January 21, 2010
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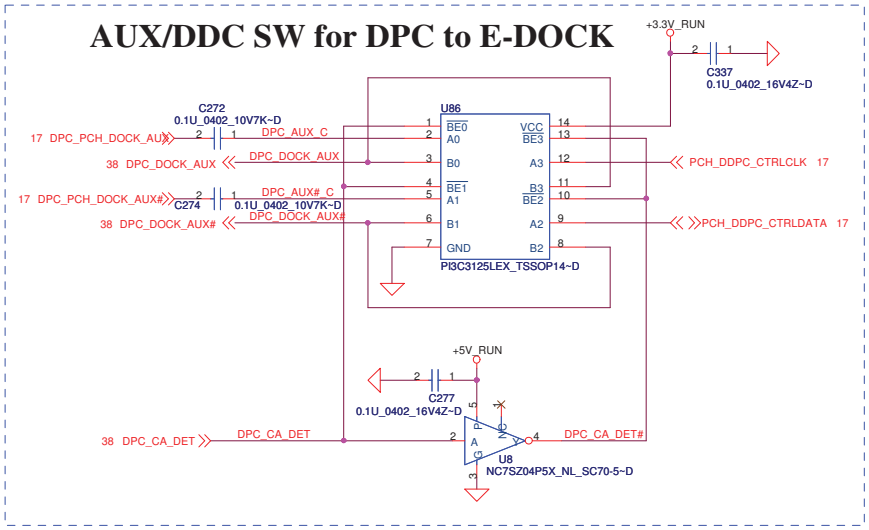

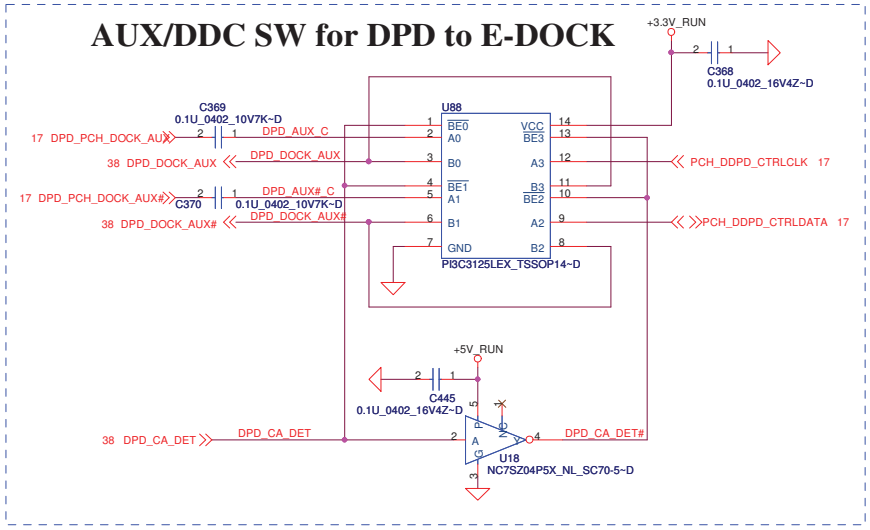

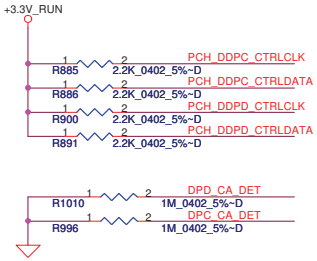

Intel WW18 Strapping option

Intel WW18 Strapping option

Compal Electronics, Inc.

Title: DPC DPD SW for DOCK

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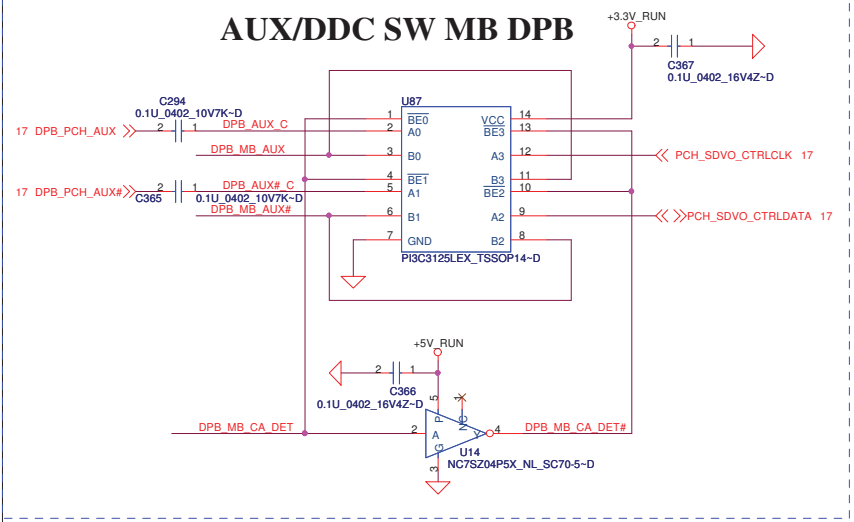
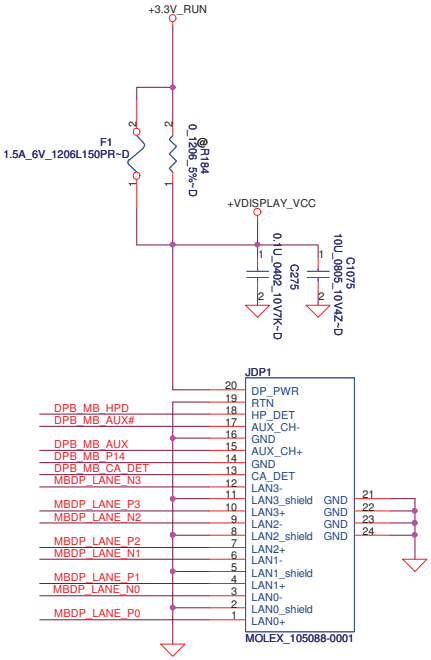
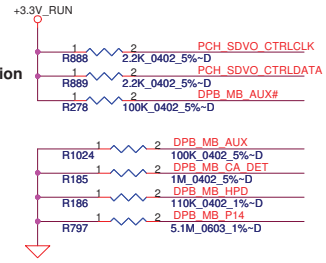
AUX/DDC SW MB DPB



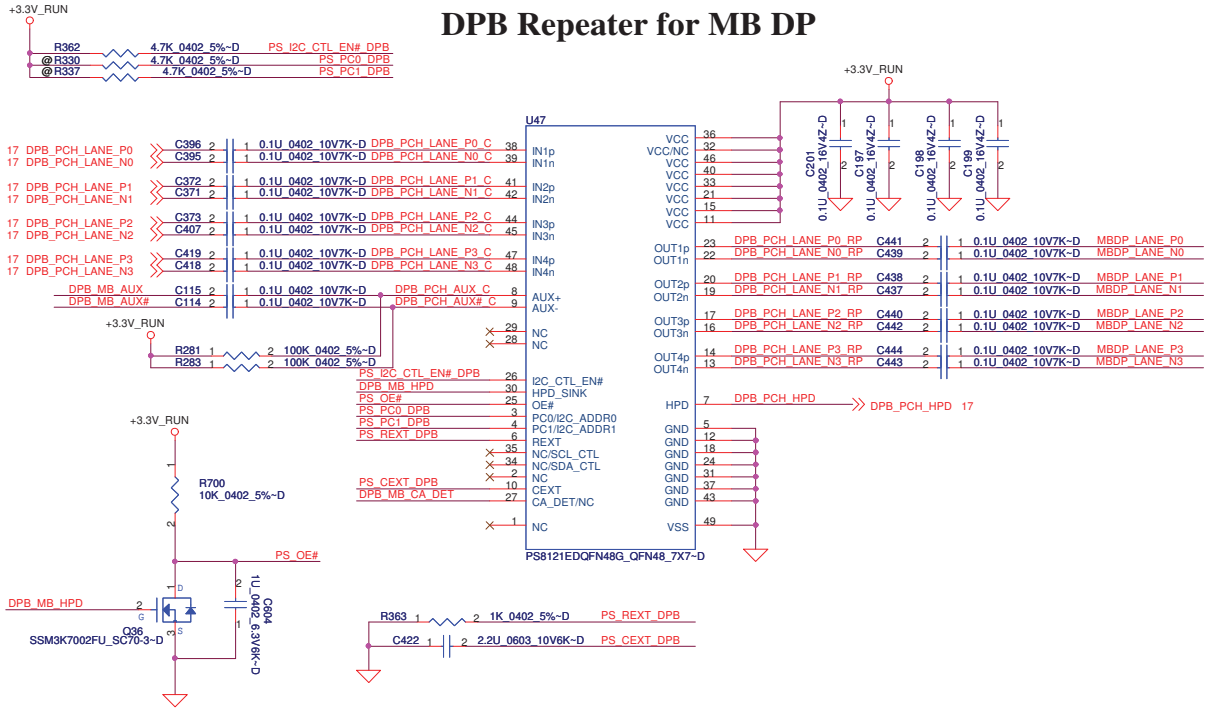
Display port Dip Connector



Intel WW18 Strapping option



DPB Repeater for MB DP



Compal Electronics, Inc.

Title: Display port

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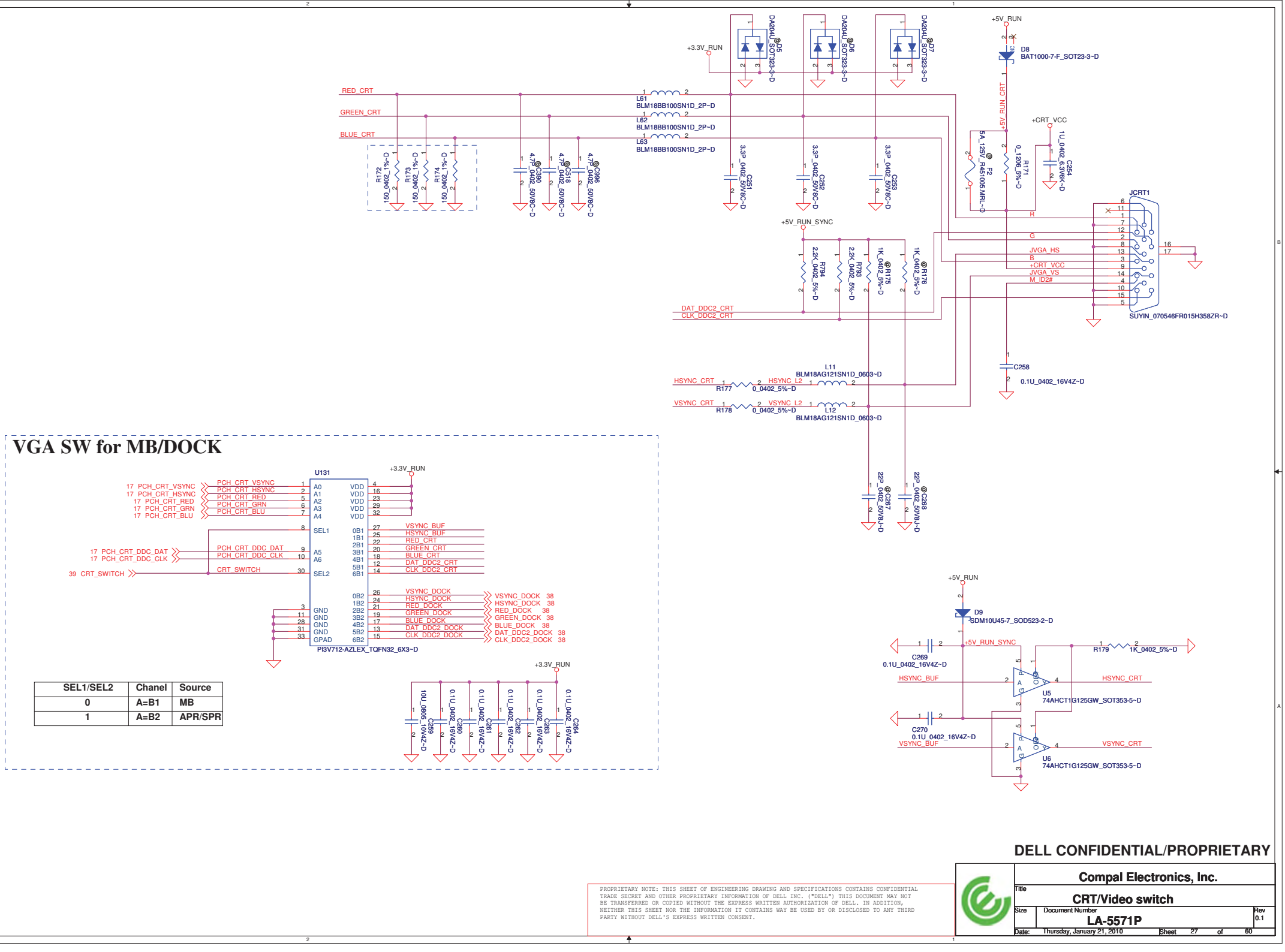
VGA SW for MB/DOCK
U131
PI3V712-AZLEX_TQFN32_6X3~D
+3.3V_RUN
+5V_RUN
+5V_RUN_SYNC
+CRT_VCC
JCRT1
SUYIN_070546FR015H358ZR~D
D8
BAT1000-7-F_SOT23-3~D
D9
SDM10U45-7_SOD523-2~D
U5
74AHCT1G125GW_SOT353-5~D
U6
74AHCT1G125GW_SOT353-5~D
L61
BLM18BB100SN1D_2P~D
L62
BLM18BB100SN1D_2P~D
L63
BLM18BB100SN1D_2P~D
L11
BLM18AG121SN1D_0603~D
L12
BLM18AG121SN1D_0603~D
RED_CRT
GREEN_CRT
BLUE_CRT
HSYNC_CRT
VSYNC_CRT
DAT_DDC2_CRT
CLK_DDC2_CRT
JVGA_HS
JVGA_VS
M_ID2#
PCH_CRT_VSYNC
PCH_CRT_HSYNC
PCH_CRT_RED
PCH_CRT_GRN
PCH_CRT_BLU
PCH_CRT_DDC_DAT
PCH_CRT_DDC_CLK
CRT_SWITCH
VSYNC_BUF
HSYNC_BUF
RED_CRT
GREEN_CRT
BLUE_CRT
DAT_DDC2_CRT
CLK_DDC2_CRT
VSYNC_DOCK
HSYNC_DOCK
RED_DOCK
GREEN_DOCK
BLUE_DOCK
DAT_DDC2_DOCK
CLK_DDC2_DOCK
SEL1/SEL2 | Chanel | Source
0 | A=B1 | MB
1 | A=B2 | APR/SPR
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Compal Electronics, Inc.
Title
CRT/Video switch
Size
Document Number
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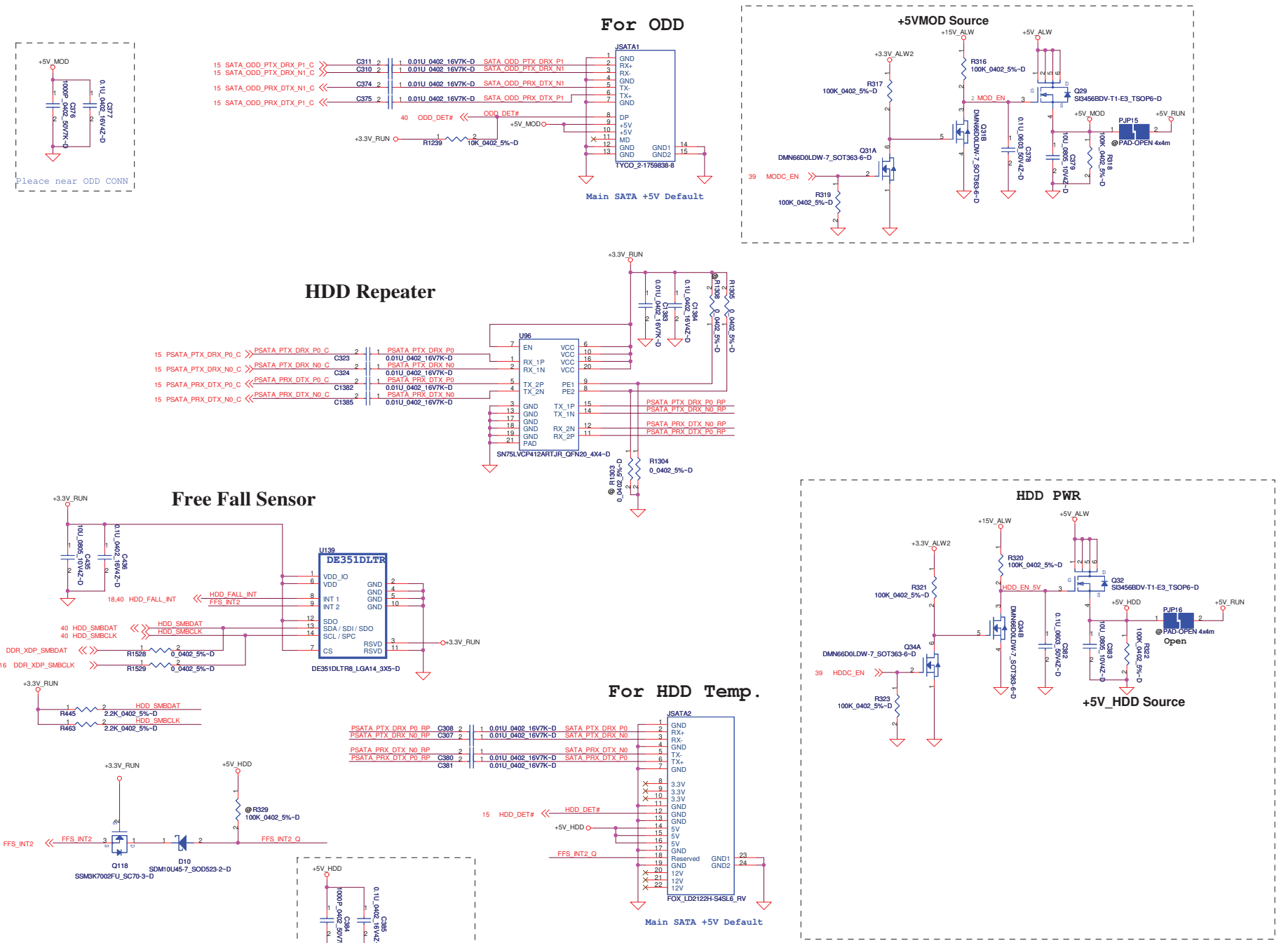

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Title: ODD/HDD CONNECTOR

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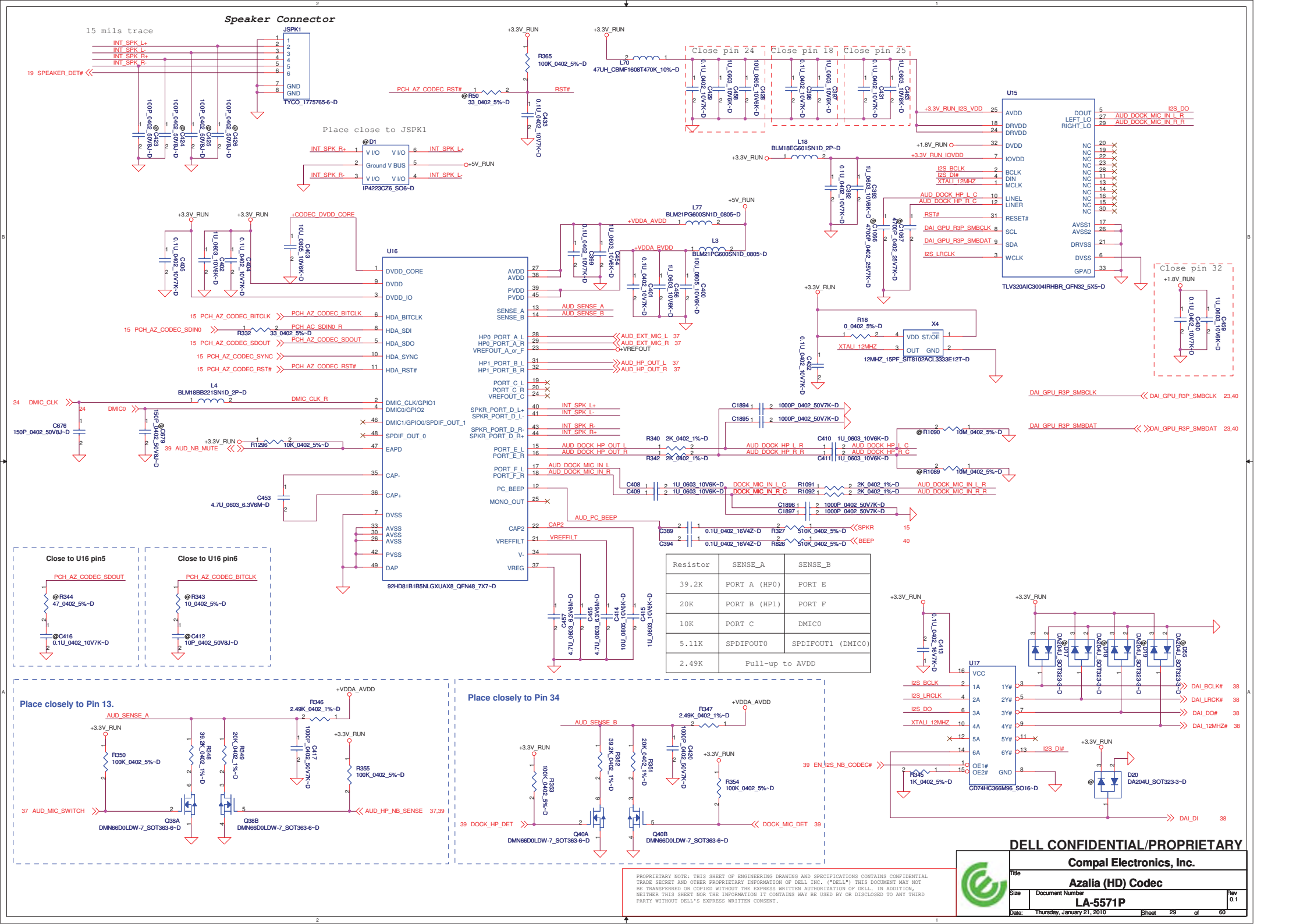

Resistor	SENSE_A	SENSE_B
39.2K	PORT A (HP0)	PORT E
20K	PORT B (HP1)	PORT F
10K	PORT C	DMIC0
5.11K	SPDIFOUT0	SPDIFOUT1 (DMIC0)
2.49K	Pull-up to AVDD	

Compal Electronics, Inc.

Title: Azalia (HD) Codec

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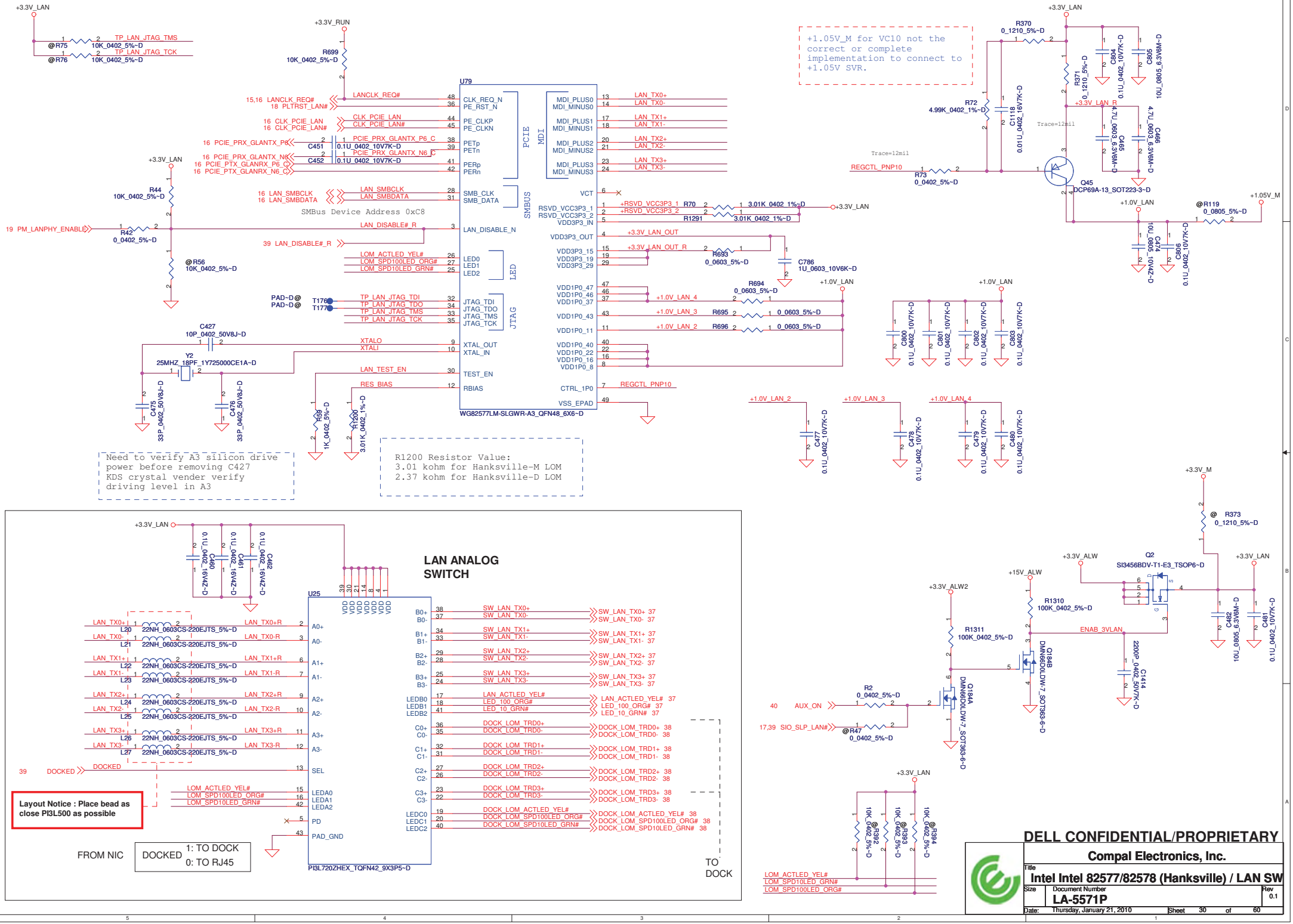
+3.3V_LAN
+3.3V_RUN
+1.05V_M for VC10 not the correct or complete implementation to connect to +1.05V SVR.
U79
WG82577LM-SLGWR-A3_QFN48_6X6~D
SMBus Device Address 0xC8
Need to verify A3 silicon drive power before removing C427
KDS crystal vender verify driving level in A3
R1200 Resistor Value:
3.01 kohm for Hanksville-M LOM
2.37 kohm for Hanksville-D LOM
LAN ANALOG SWITCH
PI3L720ZHEX_TQFN42_9X3P5~D
Layout Notice : Place bead as close PI3L500 as possible
FROM NIC
DOCKED 1: TO DOCK 0: TO RJ45
TO DOCK
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Intel Intel 82577/82578 (Hanksville) / LAN SW
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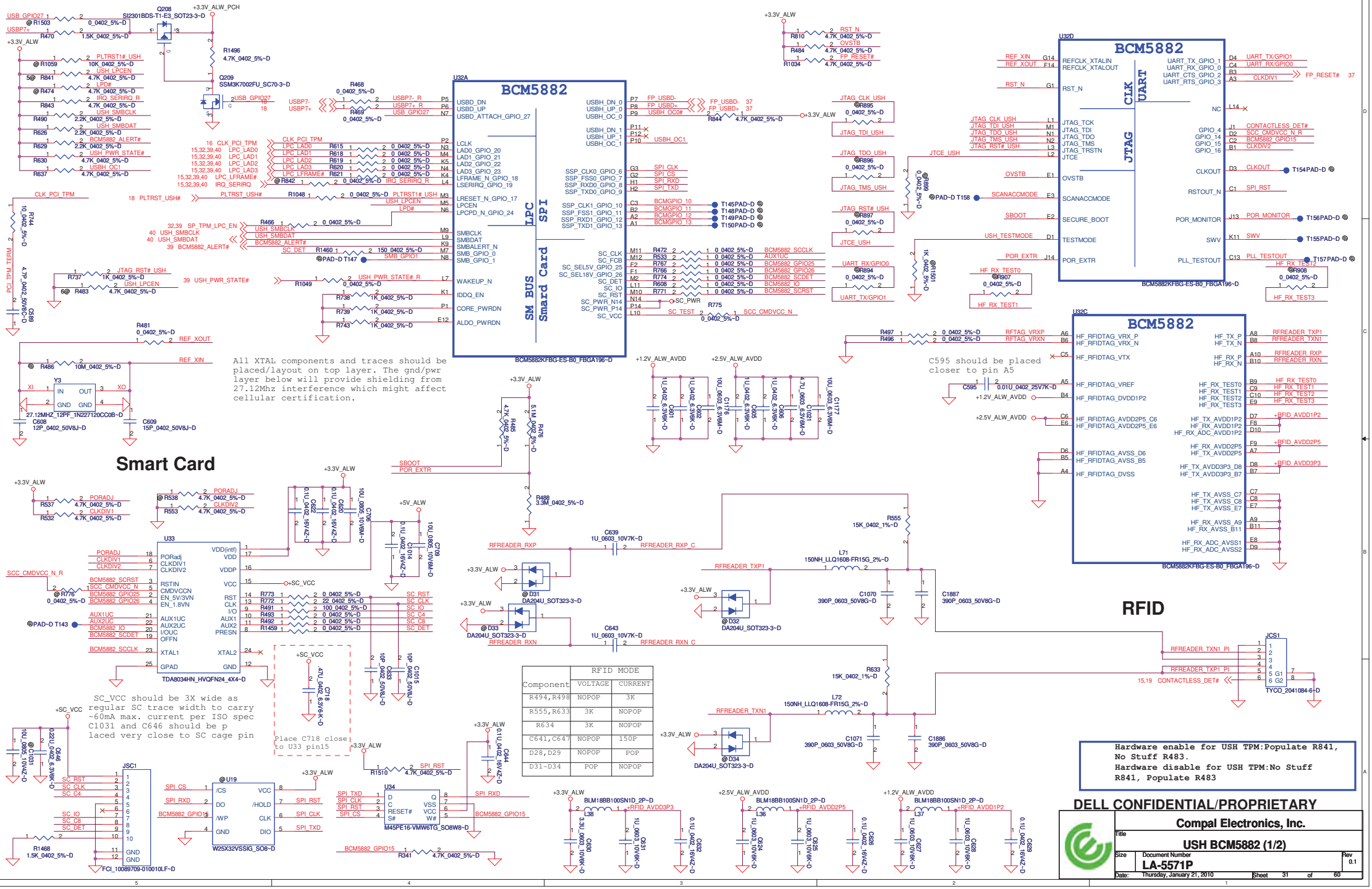
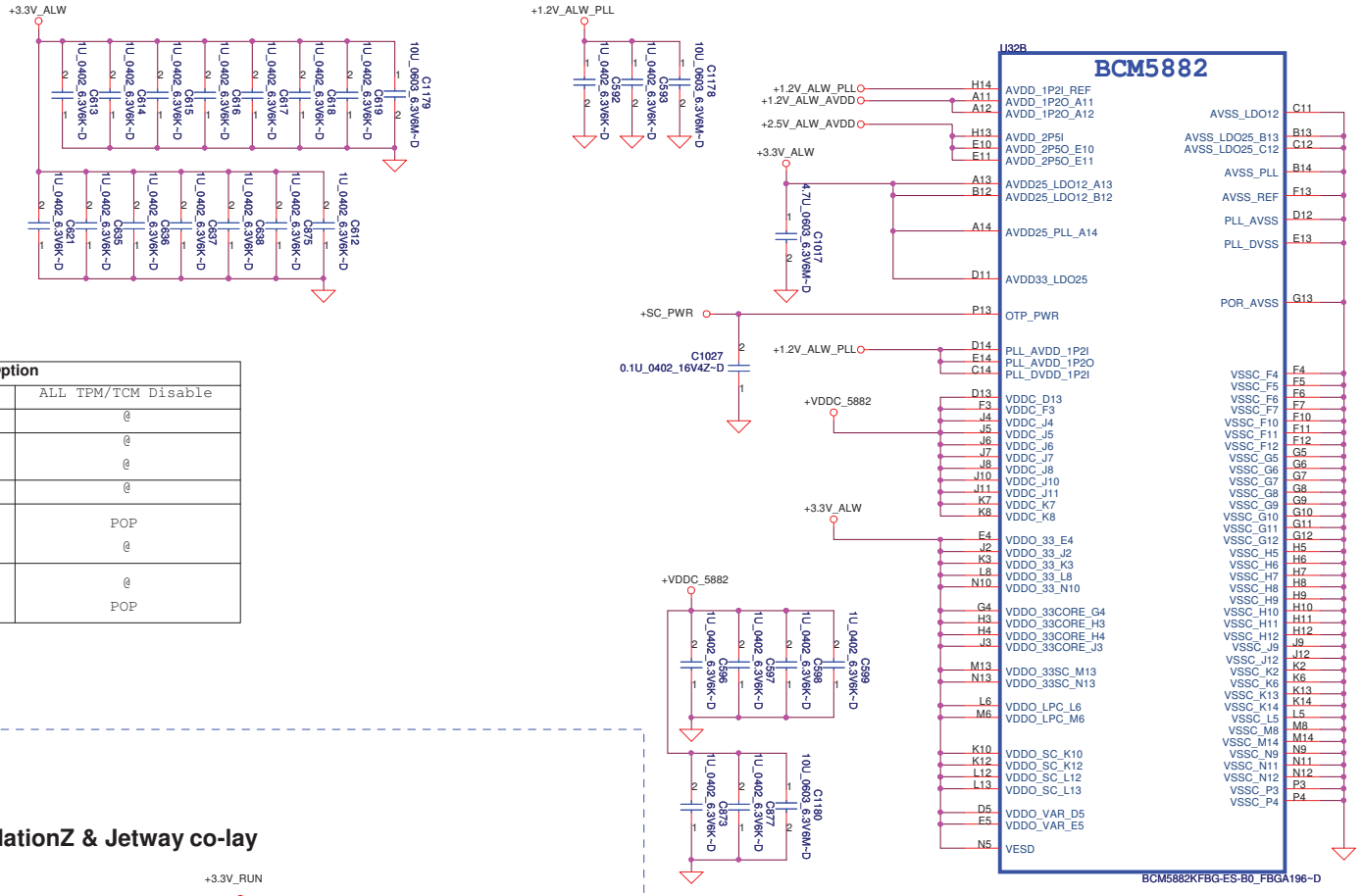
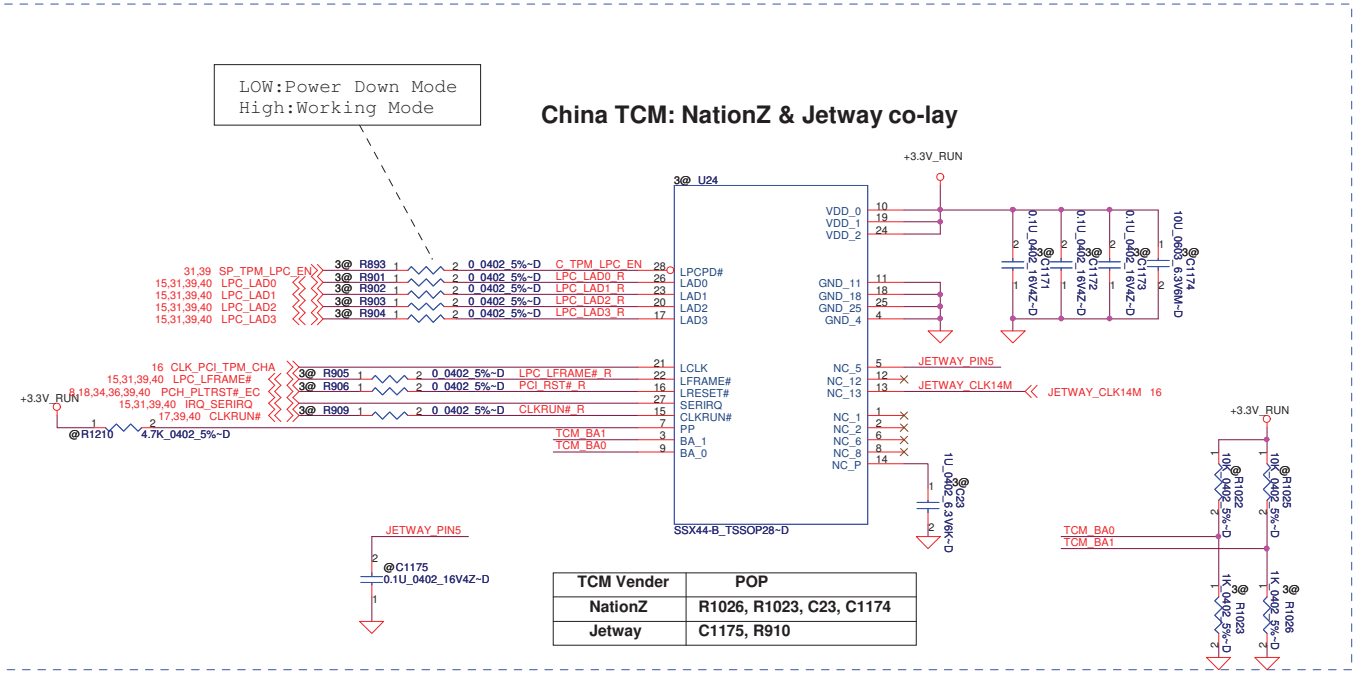


Component	RFID MODE	
	VOLTAGE	CURRENT
R494,R498	NOPOP	3K
R555,R633	3K	NOPOP
R634	3K	NOPOP
C641,C647	NOPOP	150P
D28,D29	NOPOP	POP
D31~D34	POP	NOPOP



USH BCM5882 and China TCM Z8H172T Option				
PART/PIN	Ref Des	TCM Enable	TPM Enable	ALL TPM/TCM Disable
TCM circuit	All 3@	POP	@	@
USH_LPCEN	PU R841	@	POP	@
	PD R483	POP	@	@
SIO 5028 ->SP_TPM_LPC_EN	PU R788	@	@	@
PCH GPIO39 ->TPM_ID1	PU R787	@	@	POP
	PD R339	POP	POP	@
PCH GPIO38 ->TPM_ID0	PU R273	POP	POP	@
	PD R922	@	@	POP



TCM Vender	POP
NationZ	R1026, R1023, C23, C1174
Jetway	C1175, R910

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Compal Electronics, Inc.

Title: USH BCM5882 (2/2)

Size | Document Number: LA-5571P | Rev: 0.1

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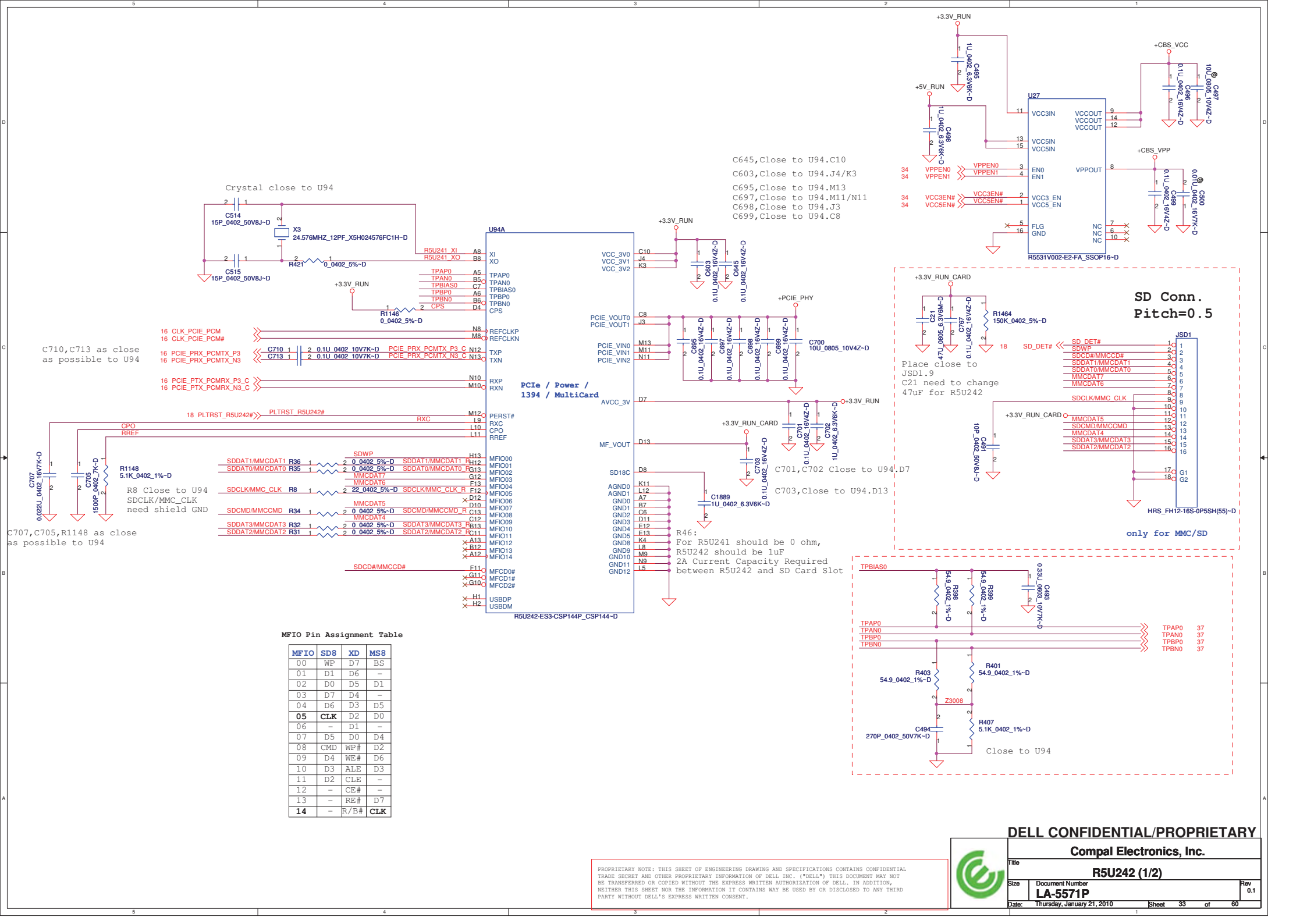

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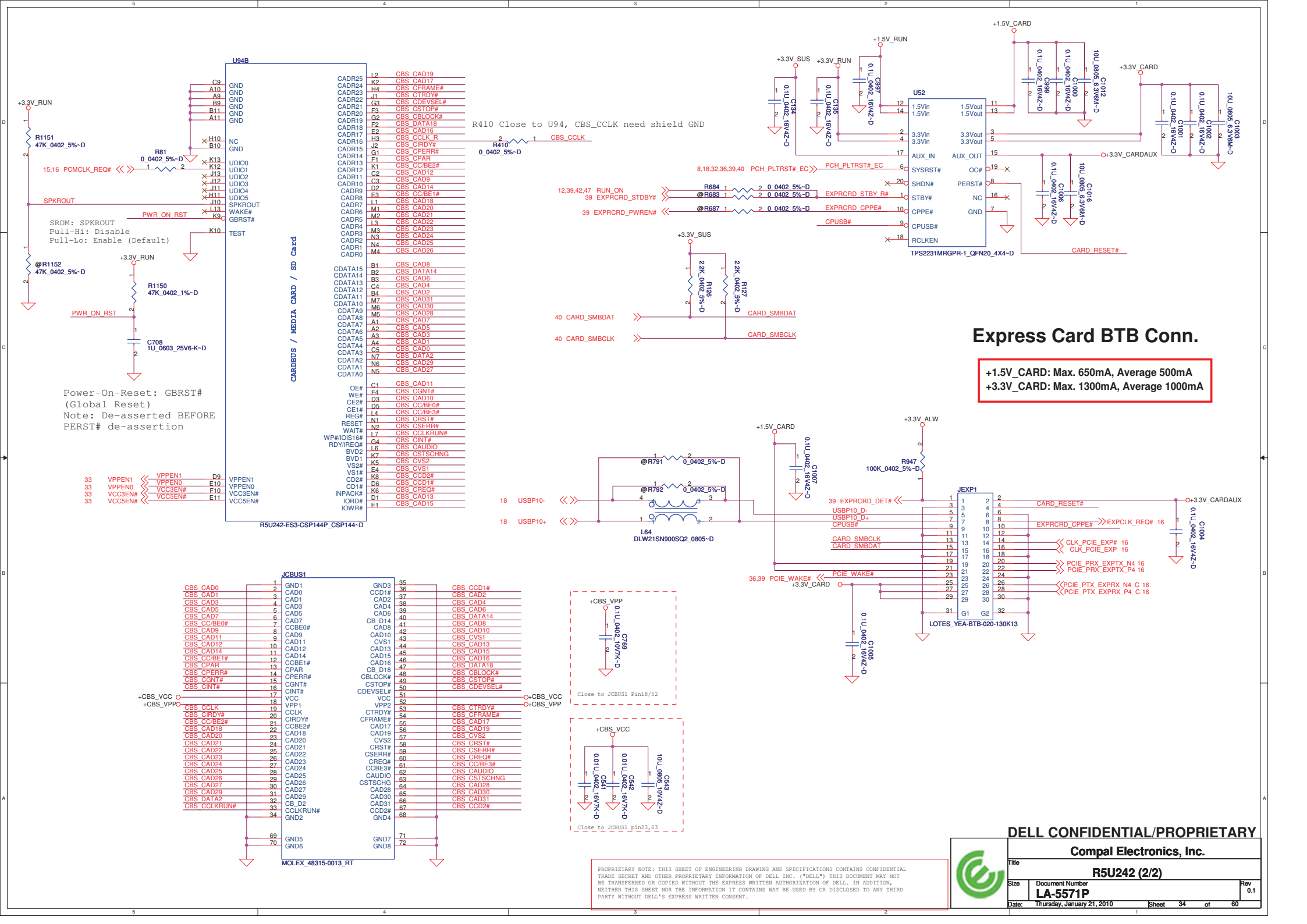
Compal Electronics, Inc.

Title: R5U242 (1/2)

Size: | Document Number: LA-5571P | Rev: 0.1

Date: Thursday, January 21, 2010 | Sheet 33 of 60


U94B
CARDBUS / MEDIA CARD / SD Card
R5U242-ES3-CSP144P_CSP144~D
+3.3V_RUN
R1151 47K_0402_5%~D
R81 0_0402_5%~D
15,16 PCMCLK_REQ#
SPKROUT
PWR_ON_RST
SROM: SPKROUT
Pull-Hi: Disable
Pull-Lo: Enable (Default)
@R1152 47K_0402_5%~D
R1150 47K_0402_1%~D
C708 1U_0603_25V6-K~D
Power-On-Reset: GBRST#
(Global Reset)
Note: De-asserted BEFORE
PERST# de-assertion
R410 Close to U94, CBS_CCLK need shield GND
R410 0_0402_5%~D
CBS_CCLK
+1.5V_CARD
+1.5V_RUN
+3.3V_SUS
+3.3V_RUN
+3.3V_CARD
U52
TPS2231MRGPR-1_QFN20_4X4~D
+3.3V_CARDAUX
PCH_PLTRST#_EC
EXPRCRD_STBY_R#
EXPRCRD_CPPE#
CPUSB#
CARD_RESET#
R684 @R683 @R687 0_0402_5%~D
12,39,42,47 RUN_ON
39 EXPRCRD_STDBY#
39 EXPRCRD_PWREN#
8,18,32,36,39,40 PCH_PLTRST#_EC
+3.3V_SUS
R126 2.2K_0402_5%~D
R127 2.2K_0402_5%~D
40 CARD_SMBDAT
40 CARD_SMBCLK
CARD_SMBDAT
CARD_SMBCLK
Express Card BTB Conn.
+1.5V: Max. 650mA, Average 500mA
+3.3V: Max. 1300mA, Average 1000mA
+1.5V_CARD
+3.3V_ALW
R947 100K_0402_5%~D
@R791 @R792 0_0402_5%~D
L64 DLW21SN900SQ2_0805~D
18 USBP10-
18 USBP10+
JEXP1
LOTES_YEA-BTB-020-130K13
39 EXPRCRD_DET#
USBP10_D-
USBP10_D+
CPUSB#
CARD_SMBCLK
CARD_SMBDAT
CLK_PCIE_EXP# 16
CLK_PCIE_EXP 16
PCIE_PRX_EXPTX_N4 16
PCIE_PRX_EXPTX_P4 16
PCIE_PTX_EXPRX_N4_C 16
PCIE_PTX_EXPRX_P4_C 16
EXPCLK_REQ# 16
36,39 PCIE_WAKE#
JCBUS1
MOLEX_48315-0013_RT
+CBS_VCC
+CBS_VPP
Close to JCBUS1 Pin18/52
Close to JCBUS1 pin23,63
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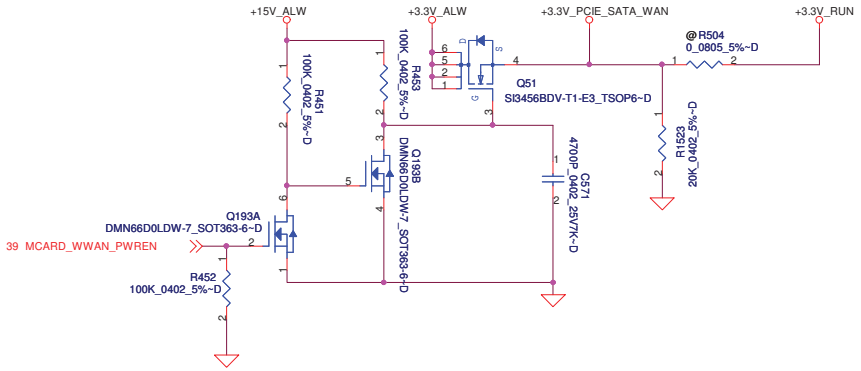
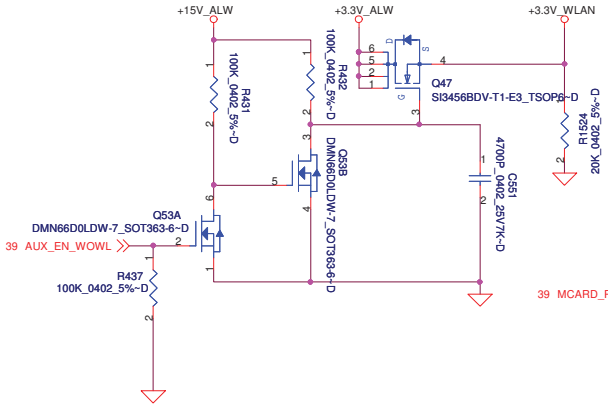
Compal Electronics, Inc.
Title
R5U242 (2/2)
Size
Document Number
LA-5571P
Rev 0.1
Date: Thursday, January 21, 2010
Sheet 34 of 60

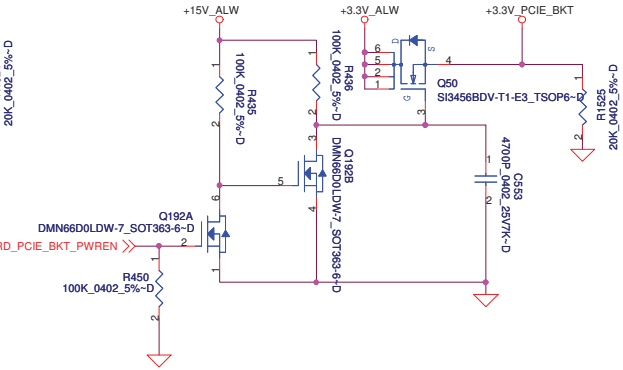
Power Control for Mini card1



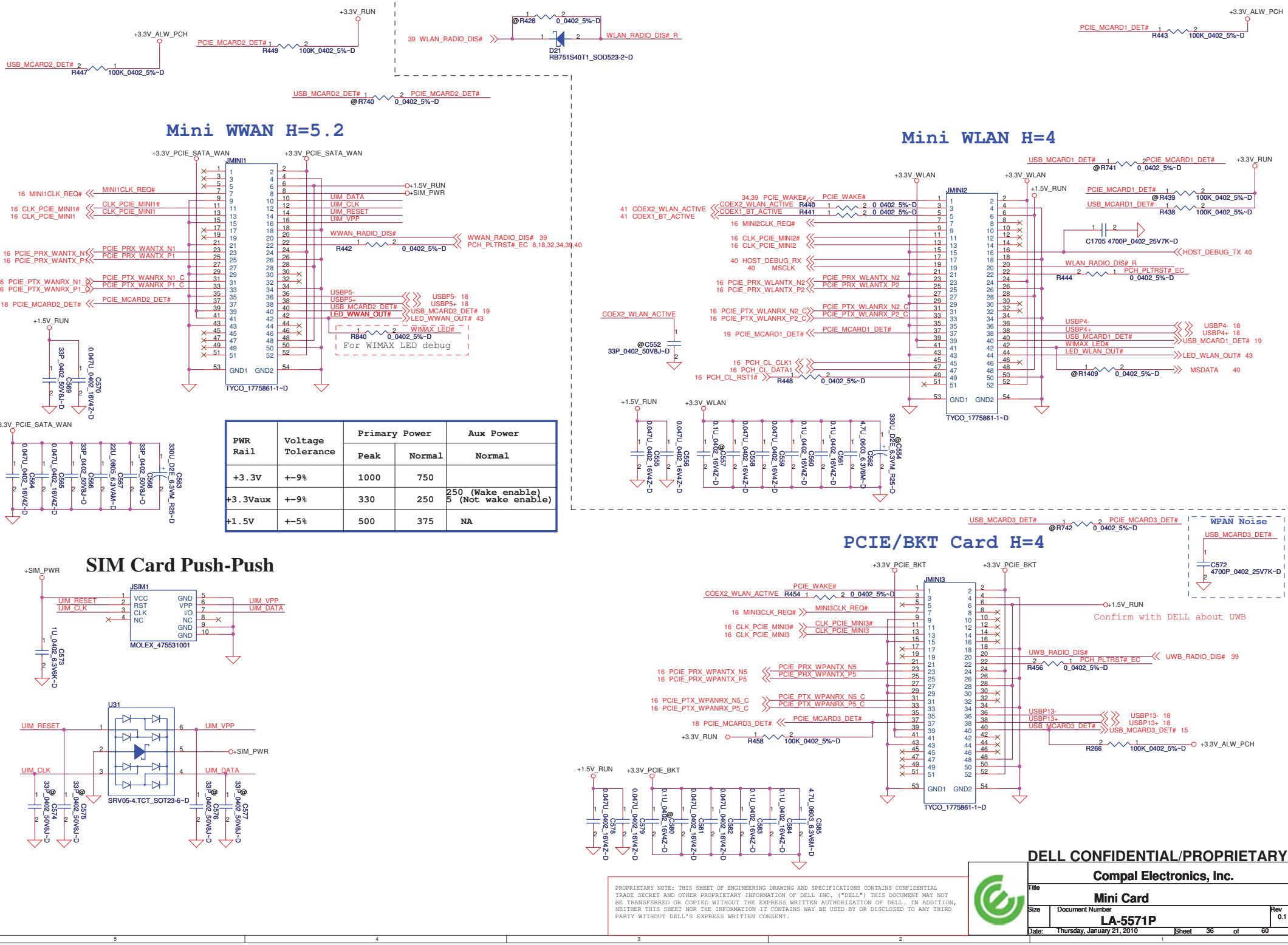
Power Control for Mini card2



Power Control for Mini card3



Compal Electronics, Inc.		
Title: PCIE PWR		
Size	Document Number: LA-5571P	Rev: 0.1
Date: Thursday, January 21, 2010	Sheet 35 of 60	


+3.3V_RUN
+3.3V_ALW_PCH
PCIE_MCARD2_DET#
R449 100K_0402_5%~D
USB_MCARD2_DET#
R447 100K_0402_5%~D
39 WLAN_RADIO_DIS#
@R428 0_0402_5%~D
WLAN_RADIO_DIS#_R
D21
RB751S40T1_SOD523-2~D
PCIE_MCARD1_DET#
R443 100K_0402_5%~D
USB_MCARD2_DET#
@R740 0_0402_5%~D
PCIE_MCARD2_DET#
Mini WWAN H=5.2
+3.3V_PCIE_SATA_WAN
JMINI1
16 MINI1CLK_REQ#
16 CLK_PCIE_MINI1#
16 CLK_PCIE_MINI1
16 PCIE_PRX_WANTX_N1
16 PCIE_PRX_WANTX_P1
16 PCIE_PTX_WANRX_N1
16 PCIE_PTX_WANRX_P1
18 PCIE_MCARD2_DET#
+1.5V_RUN
+SIM_PWR
UIM_DATA
UIM_CLK
UIM_RESET
UIM_VPP
WWAN_RADIO_DIS#
R442 0_0402_5%~D
WWAN_RADIO_DIS# 39
PCH_PLTRST#_EC 8,18,32,34,39,40
USBP5-
USBP5+
USB_MCARD2_DET#
LED_WWAN_OUT#
USBP5- 18
USBP5+ 18
USB_MCARD2_DET# 19
LED_WWAN_OUT# 43
WIMAX_LED#
R840 0_0402_5%~D
For WIMAX LED debug
GND1 GND2
TYCO_1775861-1~D
C569 33P_0402_50V8J~D
C570 0.047U_0402_16V4Z~D
C564 0.047U_0402_16V4Z~D
C565 0.047U_0402_16V4Z~D
C566 33P_0402_50V8J~D
C567 22U_0805_6.3V6M~D
C568 33P_0402_50V8J~D
C569 330U_D2E_6.3VM_R25~D
PWR Rail
Voltage Tolerance
Primary Power
Peak
Normal
Aux Power
Normal
+3.3V
+-9%
1000
750
+3.3Vaux
+-9%
330
250
250 (Wake enable)
5 (Not wake enable)
+1.5V
+-5%
500
375
NA
SIM Card Push-Push
+SIM_PWR
JSIM1
UIM_RESET
UIM_CLK
UIM_VPP
UIM_DATA
MOLEX_475531001
C573 1U_0402_6.3V6K~D
U31
SRV05-4.TCT_SOT23-6~D
C574 33P@_0402_50V8J~D
C575 33P@_0402_50V8J~D
C576 33P@_0402_50V8J~D
C577 33P@_0402_50V8J~D
Mini WLAN H=4
+3.3V_WLAN
JMINI2
41 COEX2_WLAN_ACTIVE
41 COEX1_BT_ACTIVE
34,39 PCIE_WAKE#
COEX2_WLAN_ACTIVE
COEX1_BT_ACTIVE
R440 0_0402_5%~D
R441 0_0402_5%~D
16 MINI2CLK_REQ#
16 CLK_PCIE_MINI2#
16 CLK_PCIE_MINI2
40 HOST_DEBUG_RX
40 MSCLK
16 PCIE_PRX_WLANTX_N2
16 PCIE_PRX_WLANTX_P2
16 PCIE_PTX_WLANRX_N2_C
16 PCIE_PTX_WLANRX_P2_C
19 PCIE_MCARD1_DET#
16 PCH_CL_CLK1
16 PCH_CL_DATA1
16 PCH_CL_RST1#
R448 0_0402_5%~D
USB_MCARD1_DET#
@R741 0_0402_5%~D
PCIE_MCARD1_DET#
@R439 100K_0402_5%~D
R438 100K_0402_5%~D
C1705 4700P_0402_25V7K~D
HOST_DEBUG_TX 40
WLAN_RADIO_DIS#_R
R444 PCH_PLTRST#_EC 0_0402_5%~D
USBP4-
USBP4+
USB_MCARD1_DET#
WIMAX_LED#
LED_WLAN_OUT#
USBP4- 18
USBP4+ 18
USB_MCARD1_DET# 19
LED_WLAN_OUT# 43
@R1409 0_0402_5%~D
MSDATA 40
COEX2_WLAN_ACTIVE
@C552 33P_0402_50V8J~D
GND1 GND2
TYCO_1775861-1~D
C555 0.047U_0402_16V4Z~D
C556 0.047U_0402_16V4Z~D
@C557 0.1U_0402_16V4Z~D
C558 0.047U_0402_16V4Z~D
C559 0.047U_0402_16V4Z~D
C560 0.1U_0402_16V4Z~D
C561 0.1U_0402_16V4Z~D
C562 4.7U_0603_6.3V6M~D
@C554 330U_D2E_6.3VM_R25~D
PCIE/BKT Card H=4
+3.3V_PCIE_BKT
JMINI3
COEX2_WLAN_ACTIVE
PCIE_WAKE#
R454 0_0402_5%~D
16 MINI3CLK_REQ#
16 CLK_PCIE_MINI3#
16 CLK_PCIE_MINI3
16 PCIE_PRX_WPANTX_N5
16 PCIE_PRX_WPANTX_P5
16 PCIE_PTX_WPANRX_N5_C
16 PCIE_PTX_WPANRX_P5_C
18 PCIE_MCARD3_DET#
+3.3V_RUN
R458 100K_0402_5%~D
USB_MCARD3_DET#
@R742 0_0402_5%~D
PCIE_MCARD3_DET#
WPAN Noise
USB_MCARD3_DET#
C572 4700P_0402_25V7K~D
+1.5V_RUN
Confirm with DELL about UWB
UWB_RADIO_DIS#
R456 PCH_PLTRST#_EC 0_0402_5%~D
UWB_RADIO_DIS# 39
USBP13-
USBP13+
USB_MCARD3_DET#
USBP13- 18
USBP13+ 18
USB_MCARD3_DET# 15
R266 100K_0402_5%~D
+3.3V_ALW_PCH
GND1 GND2
TYCO_1775861-1~D
C578 0.047U_0402_16V4Z~D
C579 0.047U_0402_16V4Z~D
@C580 0.1U_0402_16V4Z~D
C581 0.047U_0402_16V4Z~D
C582 0.047U_0402_16V4Z~D
C583 0.1U_0402_16V4Z~D
C584 0.1U_0402_16V4Z~D
C585 4.7U_0603_6.3V6M~D
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Compal Electronics, Inc.
Title
Mini Card
Size
Document Number
LA-5571P
Rev
0.1
Date: Thursday, January 21, 2010
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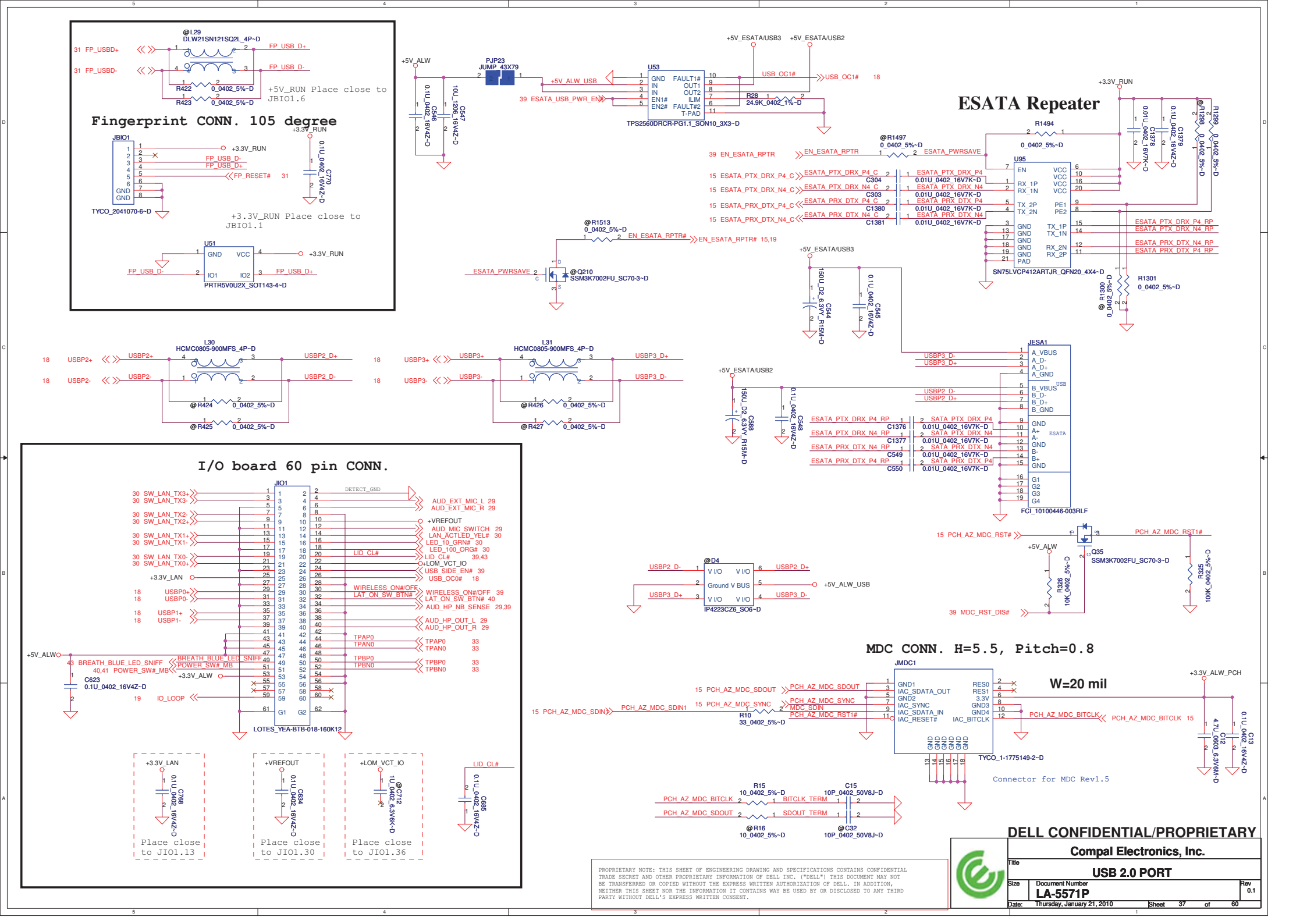
Fingerprint CONN. 105 degree
@L29
DLW21SN121SQ2L_4P~D
FP_USB_D+
FP_USB_D-
R422 0_0402_5%~D
R423 0_0402_5%~D
+5V_RUN Place close to JBIO1.6
JBIO1
TYCO_2041070-6~D
+3.3V_RUN Place close to JBIO1.1
U51
PRTR5V0U2X_SOT143-4~D
I/O board 60 pin CONN.
JIO1
LOTES_YEA-BTB-018-160K12
+3.3V_LAN Place close to JIO1.13
+VREFOUT Place close to JIO1.30
+LOM_VCT_IO Place close to JIO1.36
ESATA Repeater
PJP23
JUMP_43X79
U53
TPS2560DRCR-PG1.1_SON10_3X3~D
R28 24.9K_0402_1%~D
@R1497 0_0402_5%~D
R1494 0_0402_5%~D
U95
SN75LVCP412ARTJR_QFN20_4X4~D
R1300 0_0402_5%~D
R1301 0_0402_5%~D
@R1513 0_0402_5%~D
@Q210
SSM3K7002FU_SC70-3~D
L30
HCMC0805-900MFS_4P~D
L31
HCMC0805-900MFS_4P~D
@R424 0_0402_5%~D
@R425 0_0402_5%~D
@R426 0_0402_5%~D
@R427 0_0402_5%~D
JESA1
FCI_10100446-003RLF
@D4
IP4223CZ6_SO6~D
Q35
SSM3K7002FU_SC70-3~D
R325 100K_0402_5%~D
R326 10K_0402_5%~D
MDC CONN. H=5.5, Pitch=0.8
JMDC1
TYCO_1-1775149-2~D
Connector for MDC Rev1.5
W=20 mil
R10 33_0402_5%~D
R15 10_0402_5%~D
@R16 10_0402_5%~D
C15 10P_0402_50V8J~D
@C32 10P_0402_50V8J~D
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Compal Electronics, Inc.
Title
USB 2.0 PORT
Size
Document Number
LA-5571P
Rev
0.1
Date: Thursday, January 21, 2010
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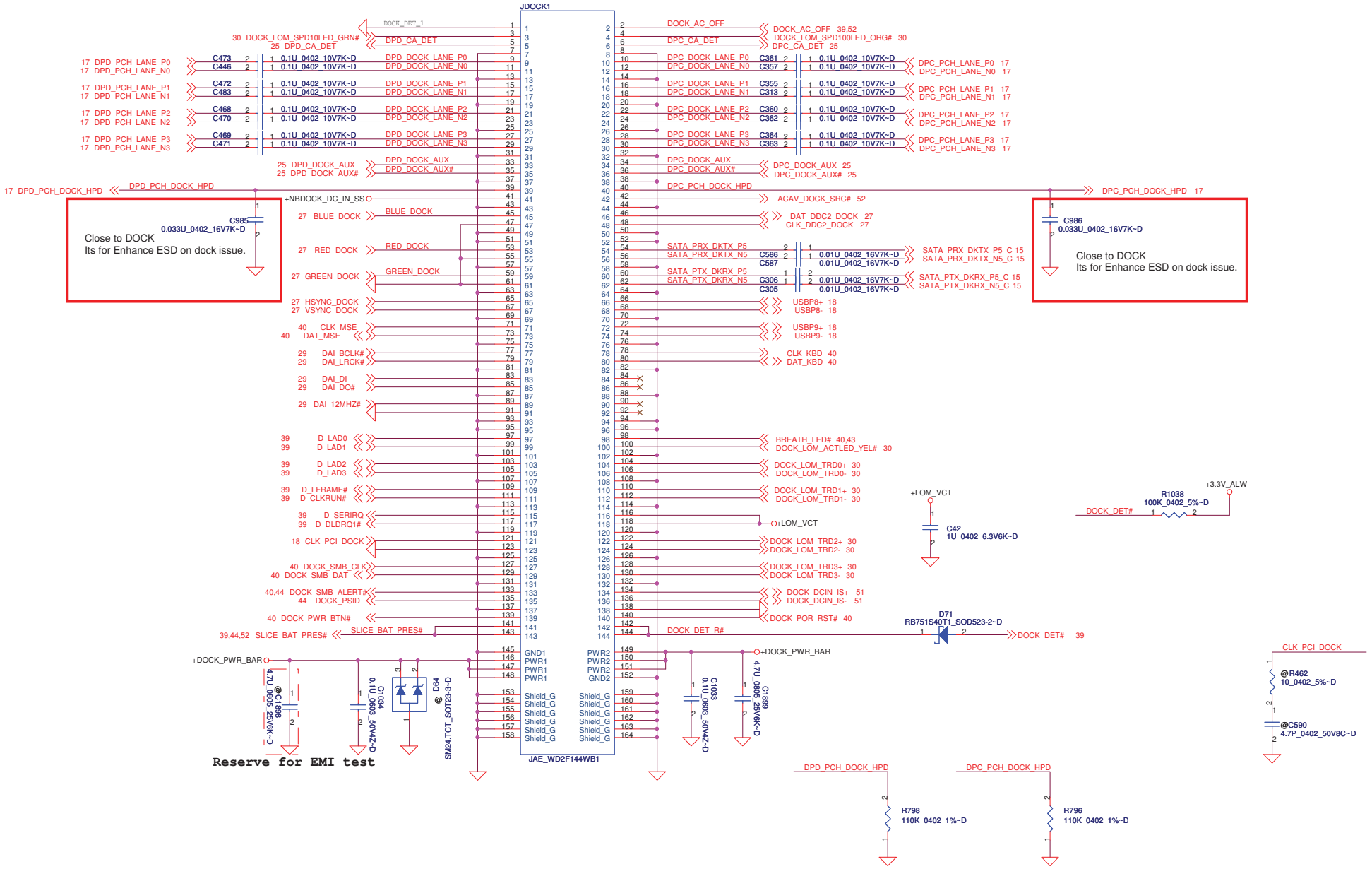

Compal Electronics, Inc.	
Title	DOCKING CONN
Size	Document Number: LA-5571P
Rev	0.1
Date:	Thursday, January 21, 2010
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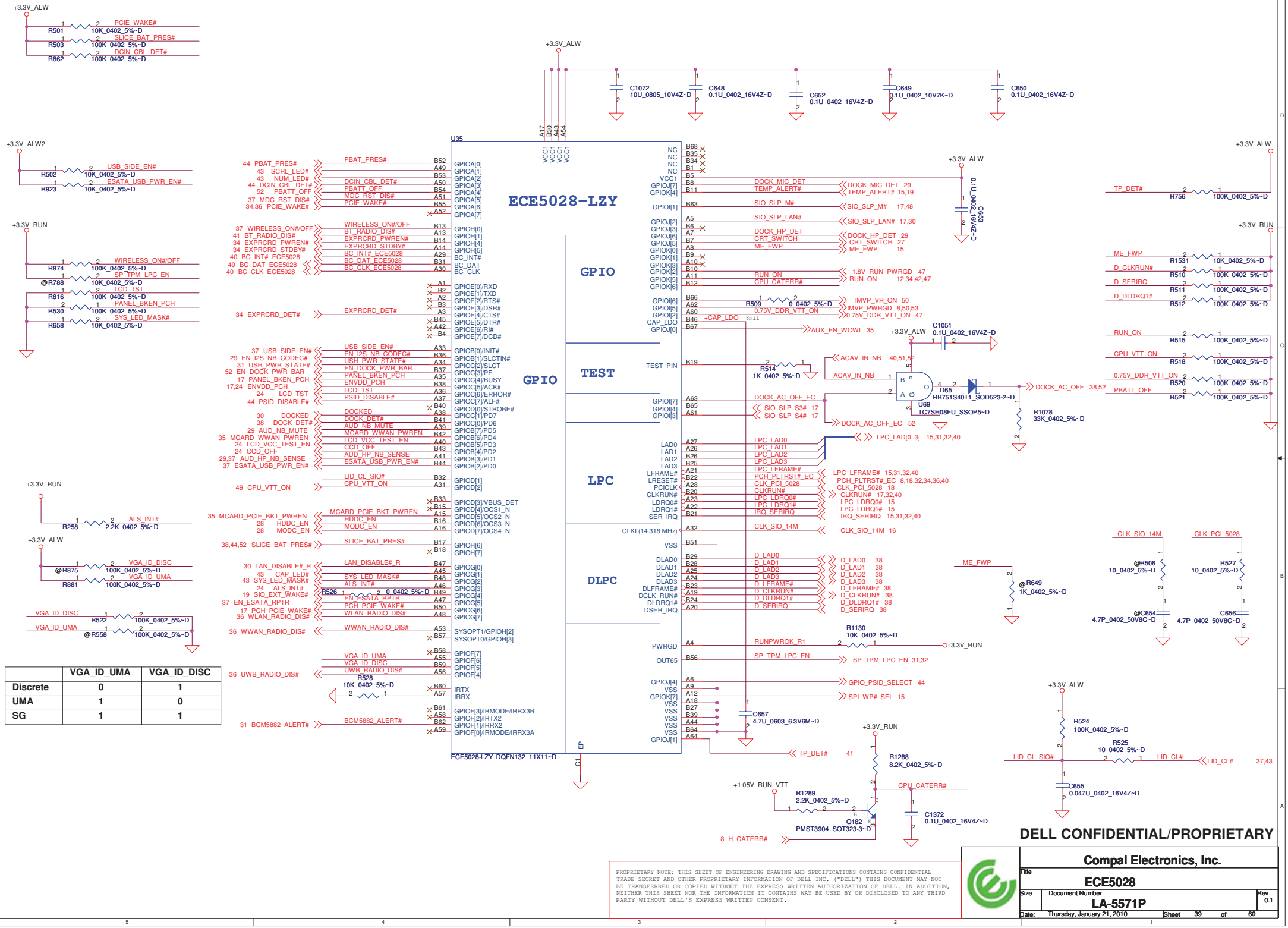
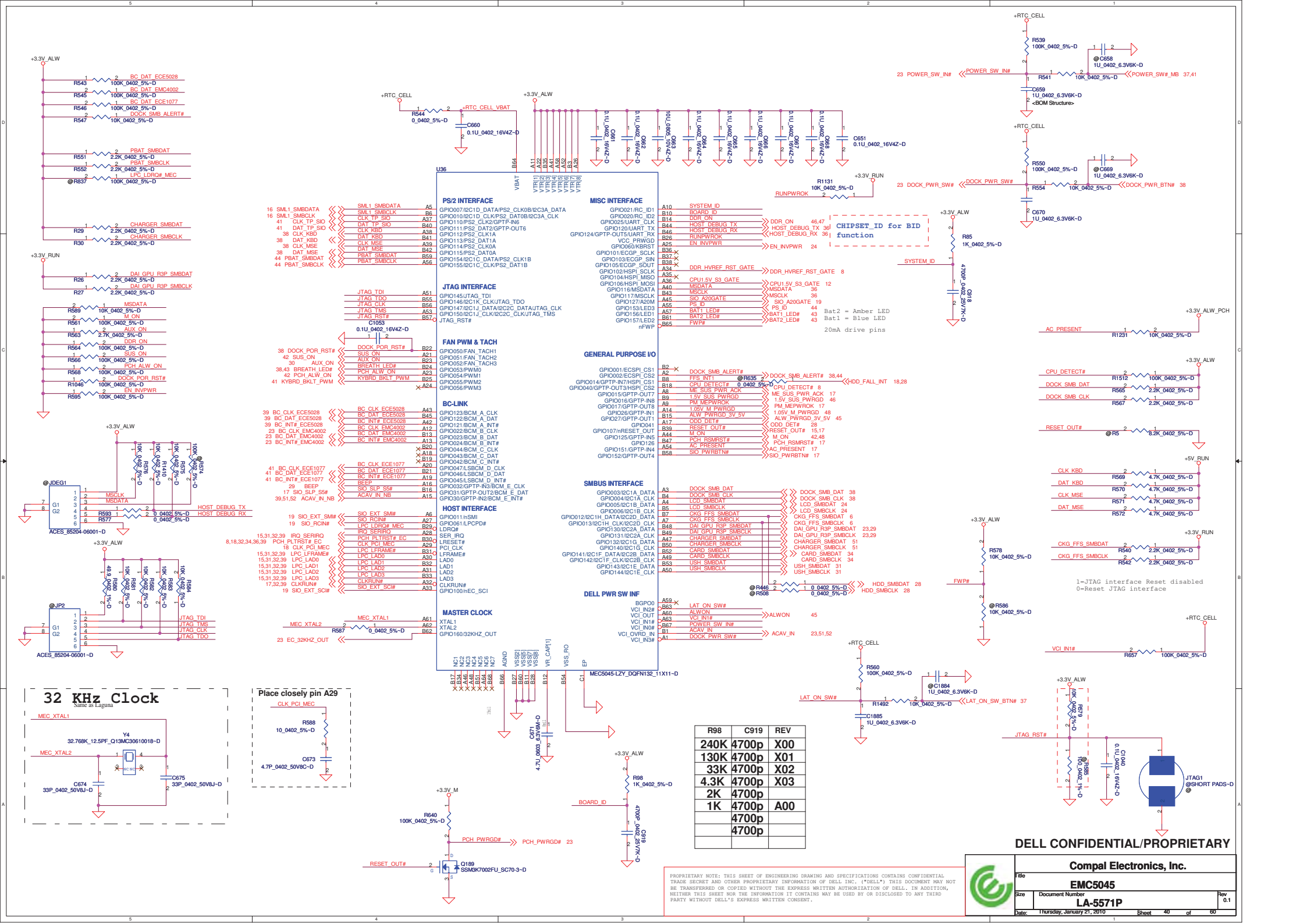


	VGA_ID_UMA	VGA_ID_DISC
Discrete	0	1
UMA	1	0
SG	1	1



R98	C919	REV
240K	4700p	X00
130K	4700p	X01
33K	4700p	X02
4.3K	4700p	X03
2K	4700p	
1K	4700p	A00
	4700p	
	4700p	

Compal Electronics, Inc.

Title: EMC5045

Size: | Document Number: LA-5571P | Rev: 0.1

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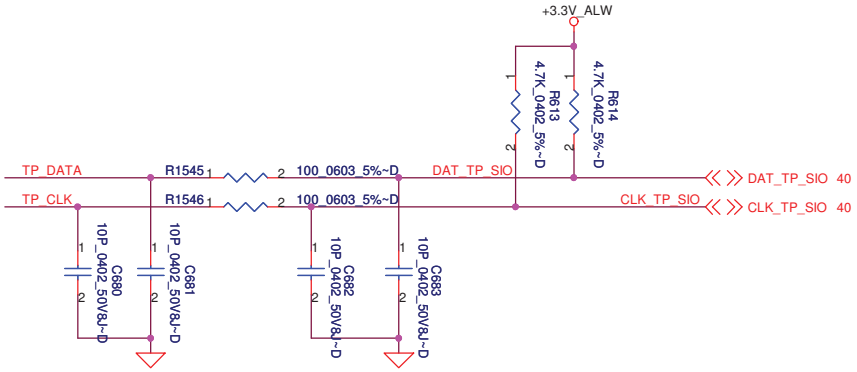
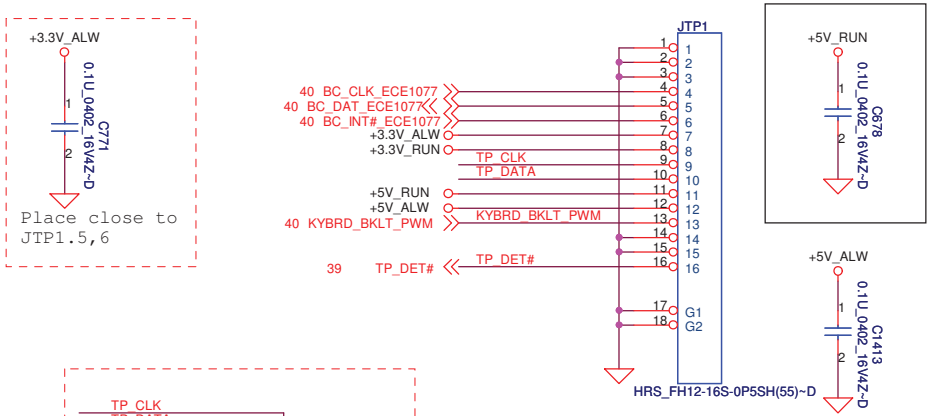
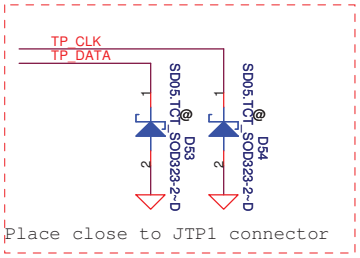
Touch Pad

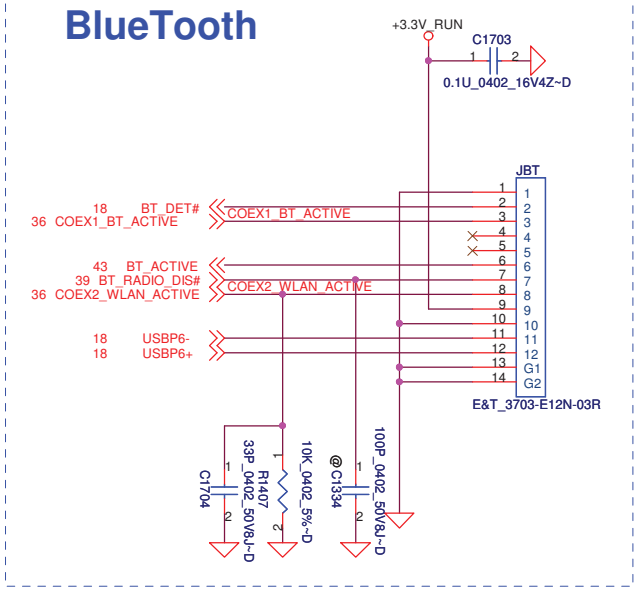


Touch Pad Conn. Pitch=0.5

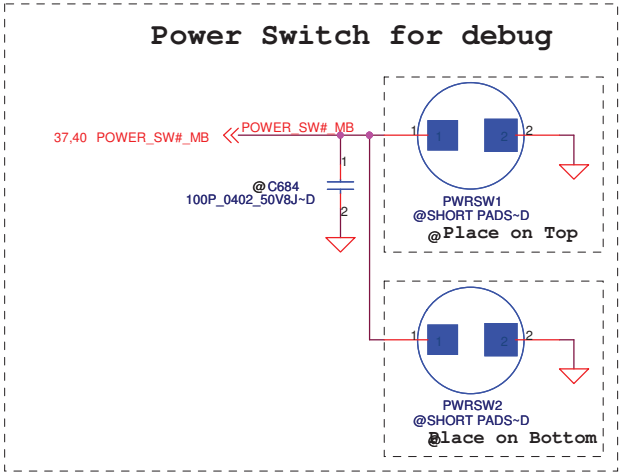




BlueTooth



Power Switch for debug



@FAN

Part Number	Description
DC28A000800	FAN SET DAQ20 DC5V AB7405HB-HB3 ADDA

@Speak

Part Number	Description
PK230003Q0L	SPK PACK ZJX 2.0W 4 OHM FG

@SM CARD BODY

Part Number	Description
SP070007V0L	S SOCKET TYCO 1770551-1 10P H5.9 SMART

@PCMCIA BODY

Part Number	Description
DC000001Q0L	PCMCIA TYCO 1759096-1

@MDC wire set cable

Part Number	Description
DC02000CS0L	H-CONN SET ZGX MB-MDC

@T/P wire set cable

Part Number	Description
DC02000840L	H-CONN SET ZJX MB-B/T-TP-FP

@LVDS cable

Part Number	Description
DC020003Y0L	H-CONN SET ZJX MB-LCD 14 WXGA+(-1ch)

@LVDS cable

Part Number	Description
DC02000870L	H-CONN SET ZJX MB-LCD 14 WXGA+(-2ch)

@RTC BATT

Part Number	Description
GC20323MX00	BATT CR2032 3V 220MAH MAXELL

Compal Electronics, Inc.

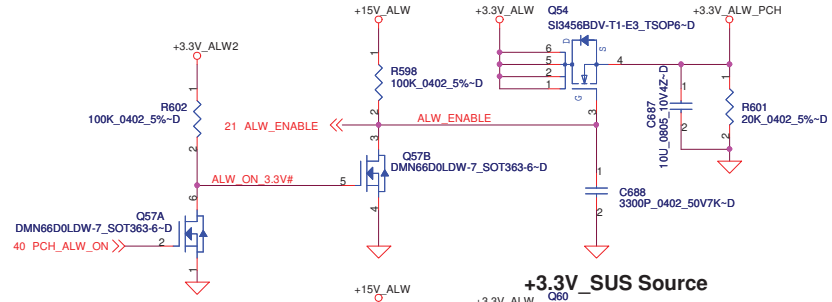
Title: Touch PAD/Int KB/LID

Size | Document Number: LA-5571P | Rev: 0.1

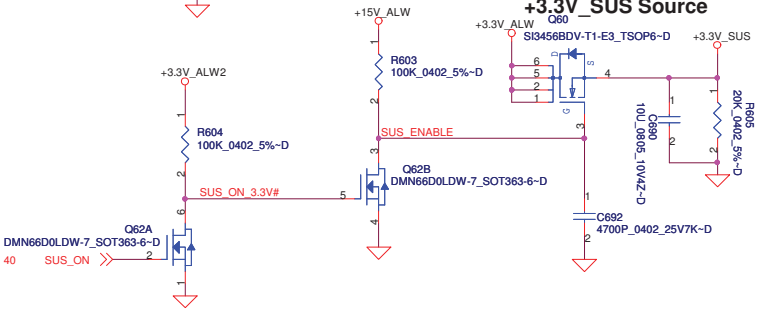
Date: Thursday, January 21, 2010 | Sheet 41 of 60

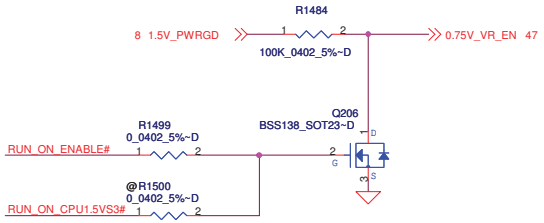
DC/DC Interface

+3.3V_ALW_PCH Source

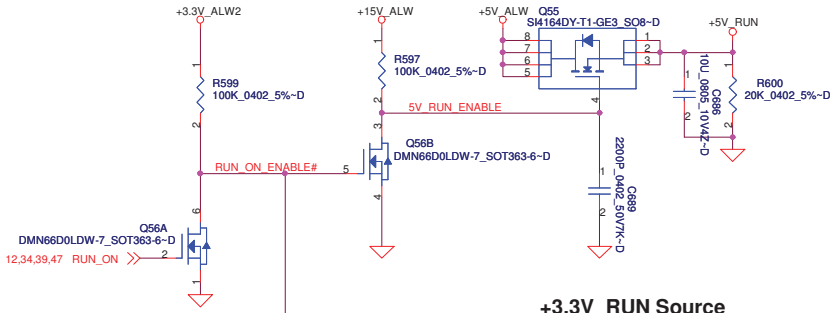


+3.3V_SUS Source

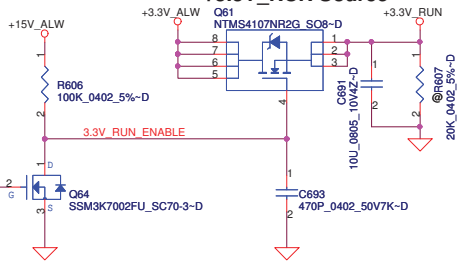




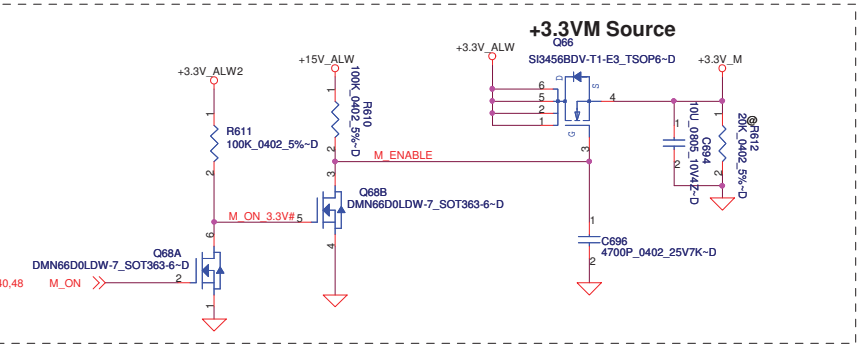
+5VRUN Source



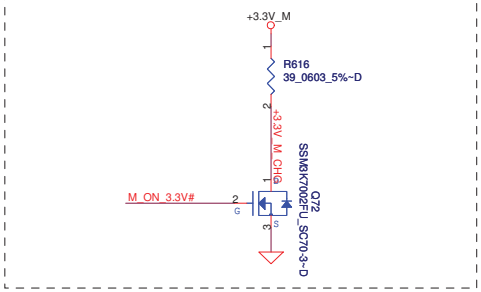
+3.3V_RUN Source



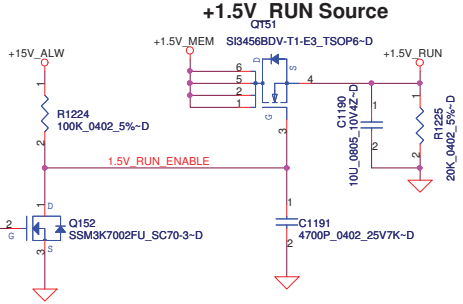
+3.3VM Source



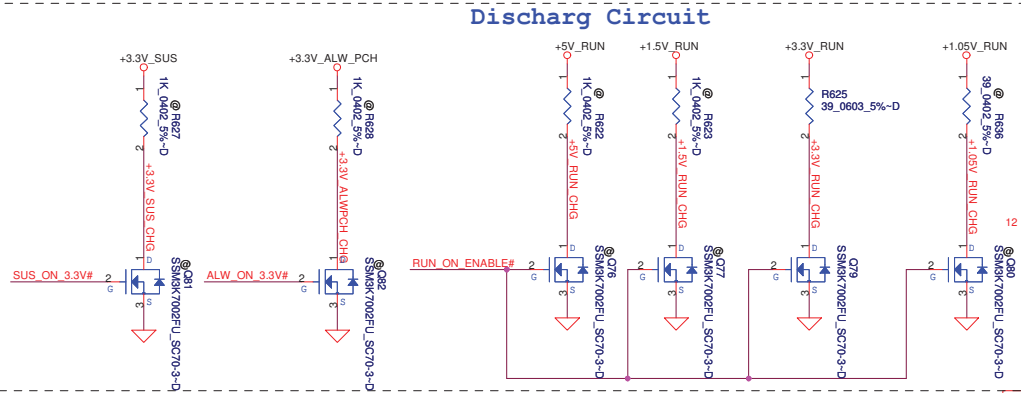
Discharg Circuit



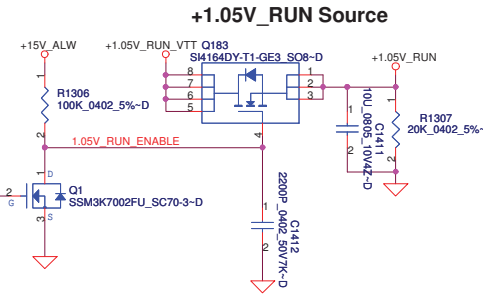
+1.5V_RUN Source



Discharg Circuit



+1.05V_RUN Source



Compal Electronics, Inc.

Title: POWER CONTROL

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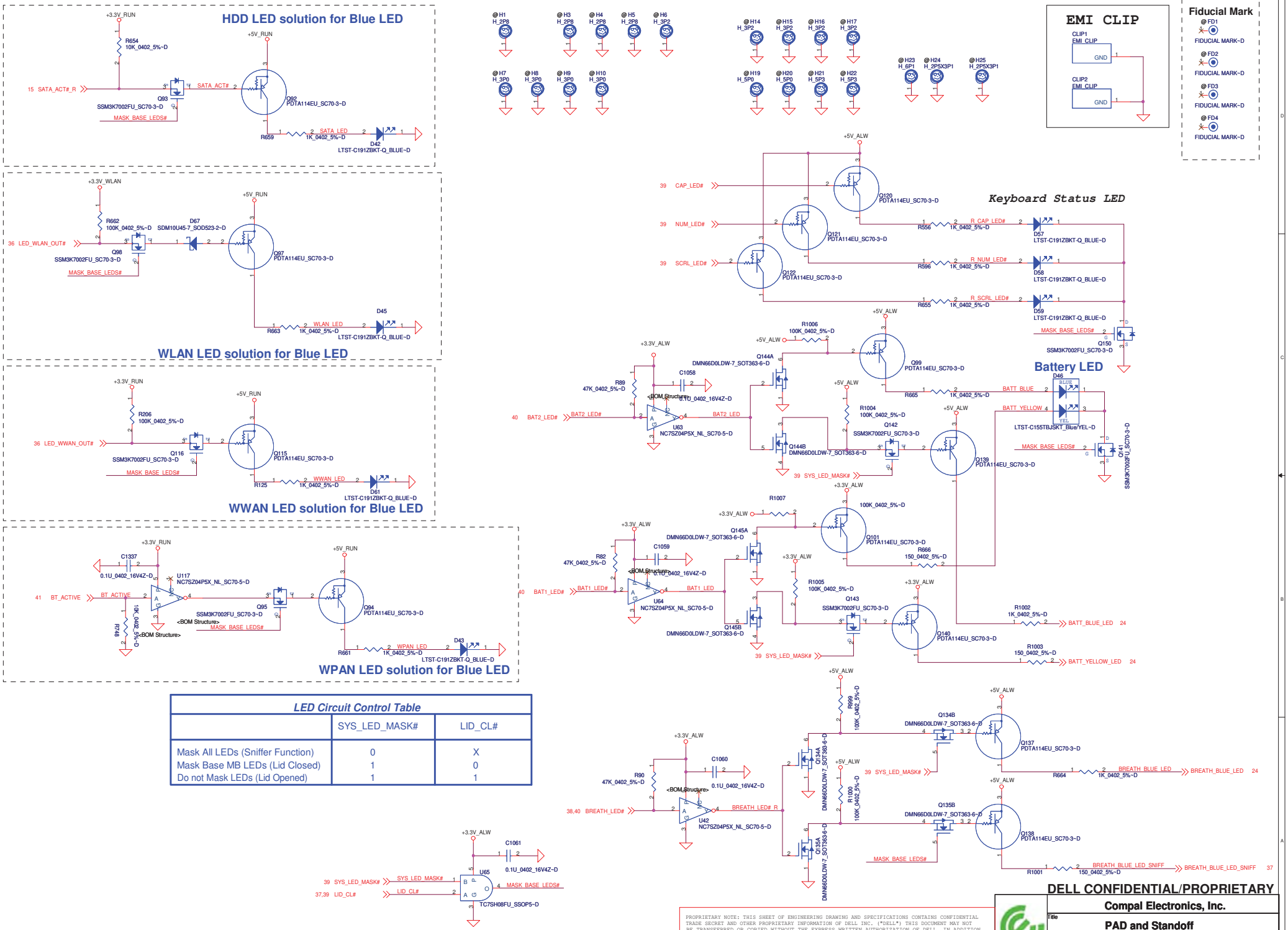
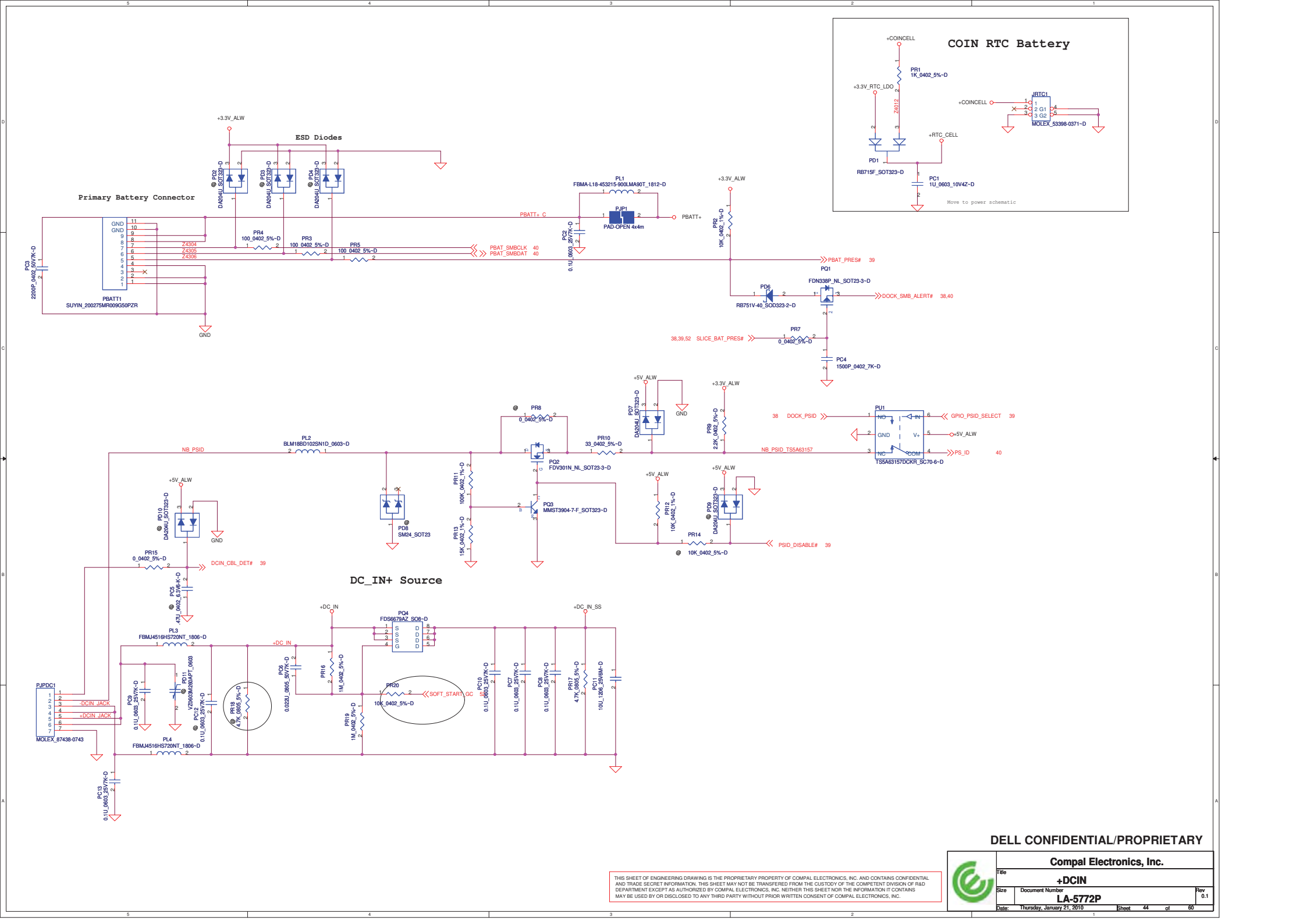


LED Circuit Control Table	SYS_LED_MASK#	LID_CL#
Mask All LEDs (Sniffer Function)	0	X
Mask Base MB LEDs (Lid Closed)	1	0
Do not Mask LEDs (Lid Opened)	1	1



Compal Electronics, Inc.		
Title	+DCIN	
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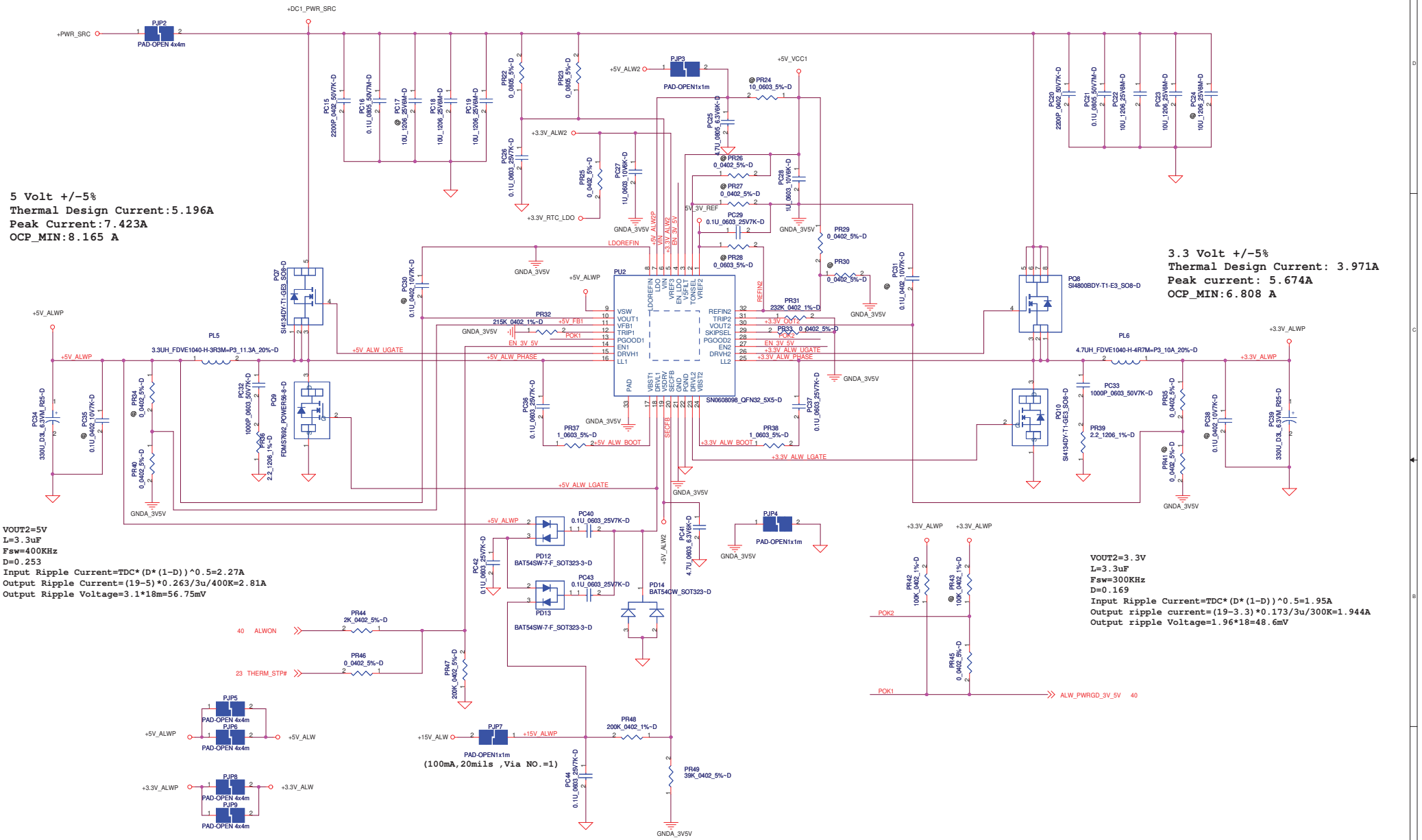
+3.3V_ALWP/ +5V_ALWP/ +5V_ALW2 / +15V_ALWP/ +3.3V_RTC_LDO



Compal Electronics, Inc.		
Title: DC/DC +3V/ +5V		
Size	Document Number: LA-5772P	Rev: 0.1
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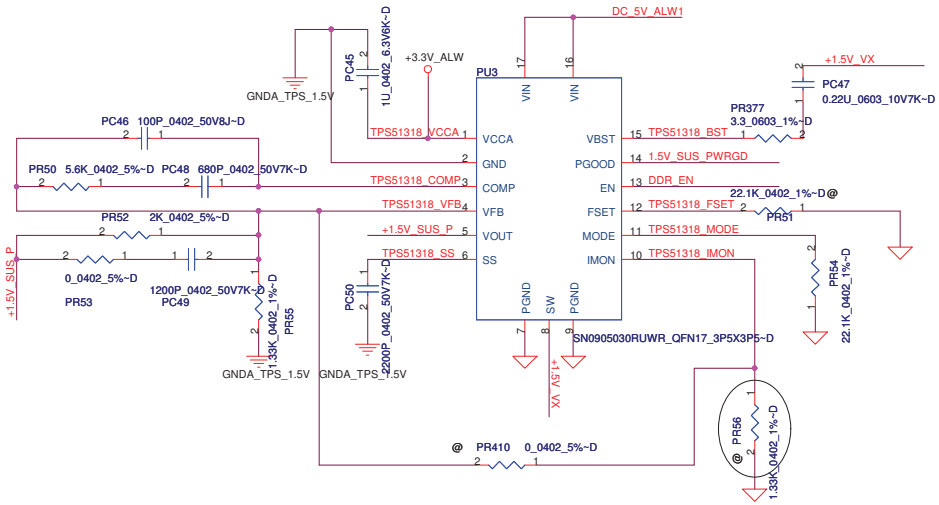
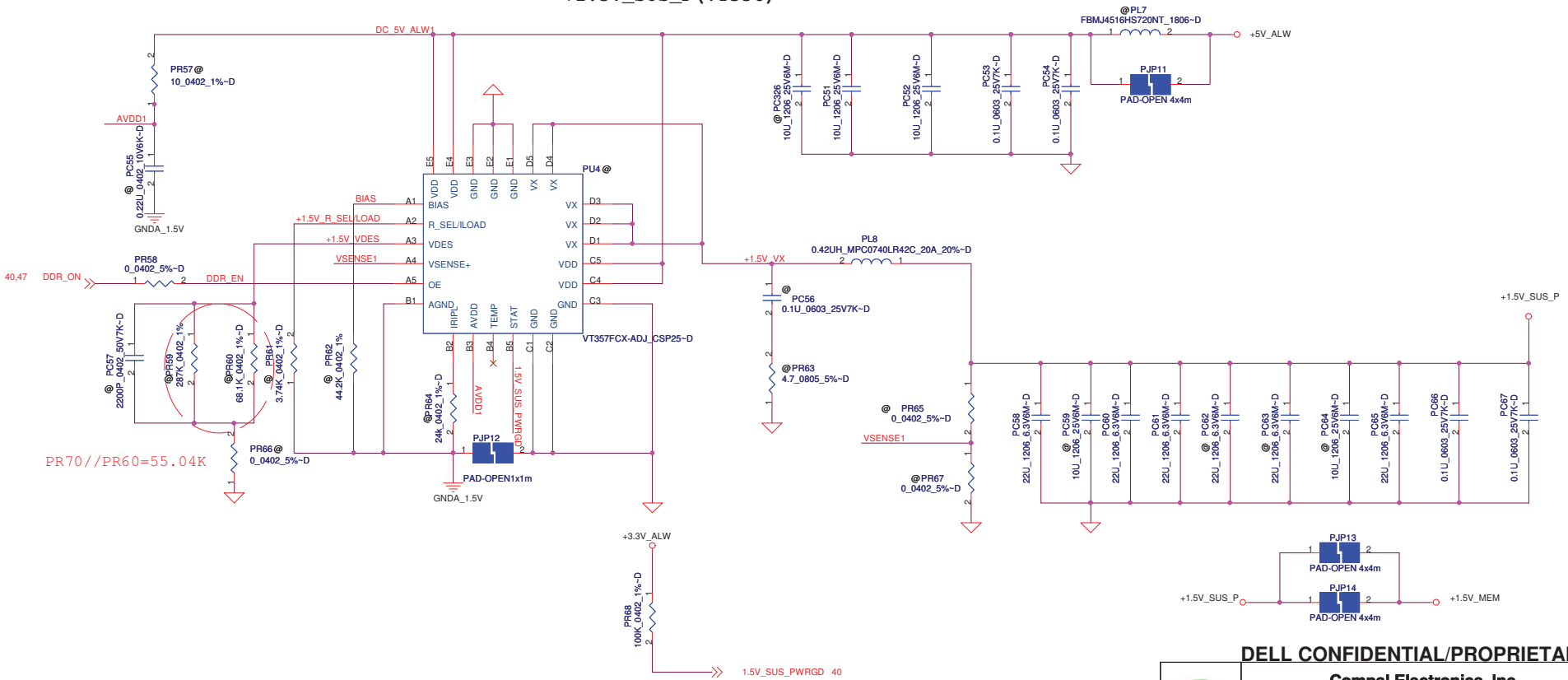
+1.5V_SUS_P (TPS51318)



1.5 Volt +/-5%
Thermal Design Current: 7.876A
Peak current: 11.251A
OCP_MIN:12.376A

+1.5V_SUS_P (VT356)



Compal Electronics, Inc.		
Title: +1.5V_MEM		
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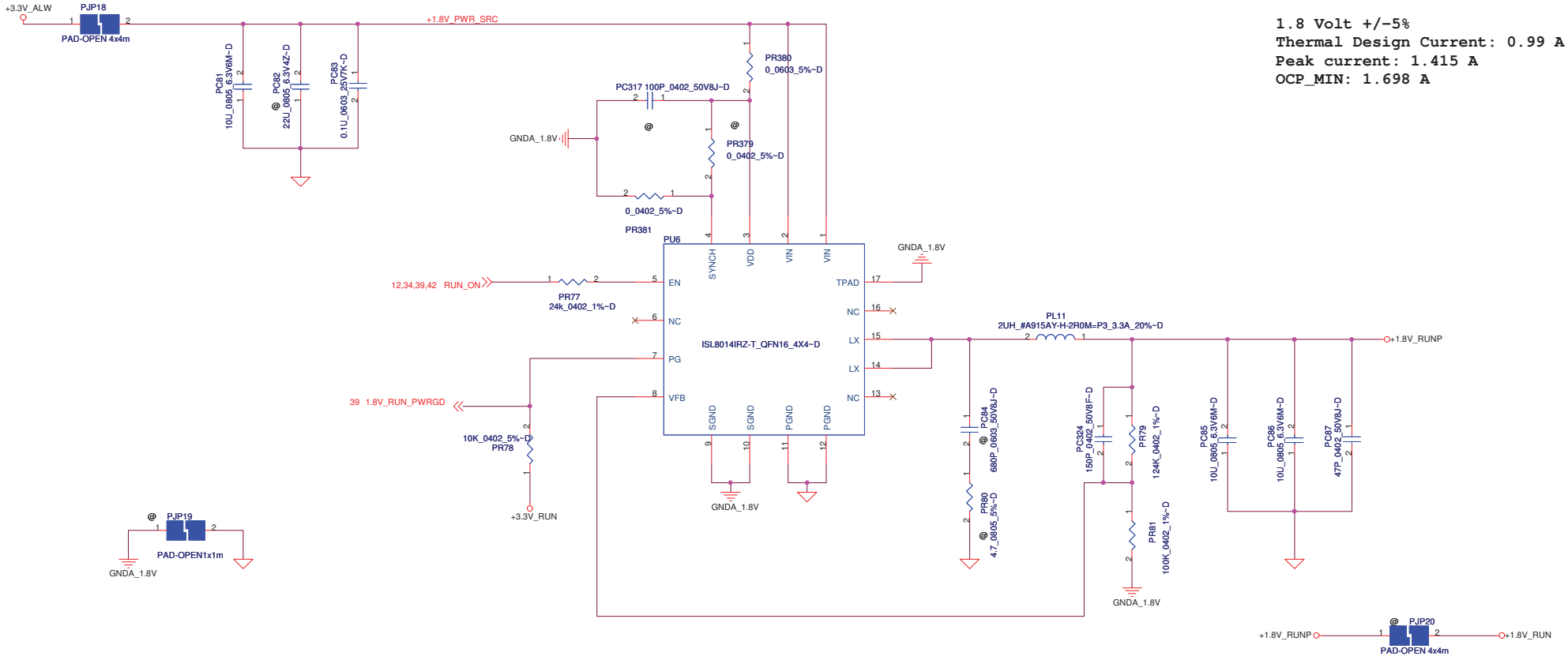
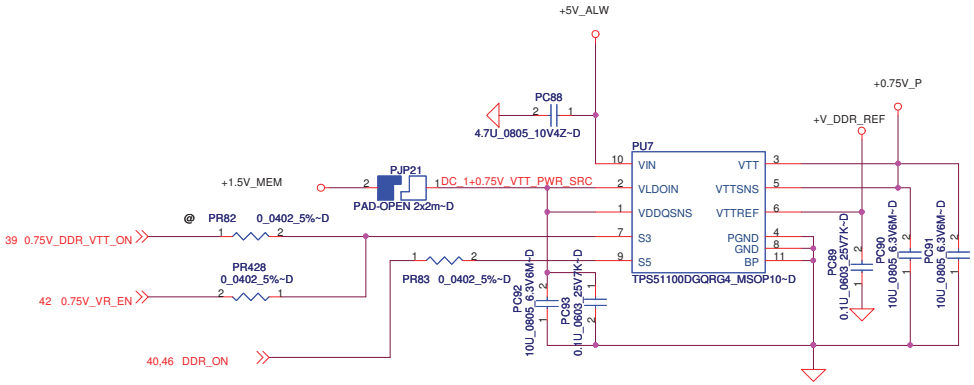
+1.8V_RUNP



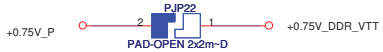
1.8 Volt +/-5%
Thermal Design Current: 0.99 A
Peak current: 1.415 A
OCP_MIN: 1.698 A

+0.75V_DDR_VTT

DDR3 Termination



0.75Volt +/-5%
Thermal Design Current: 0.7A
Peak current: 1A



VOUT=1.8V
L=3.3uF
Fsw=290KHz
D=0.092
Input Ripple Current=TDC*(D*(1-D))^0.5=0.884A
Output Ripple Current=1.707A
Output Ripple Voltage=1.707*15m=20.5mV

Compal Electronics, Inc.

Title: +0.75V_DDR_VT/+1.8V_RUN

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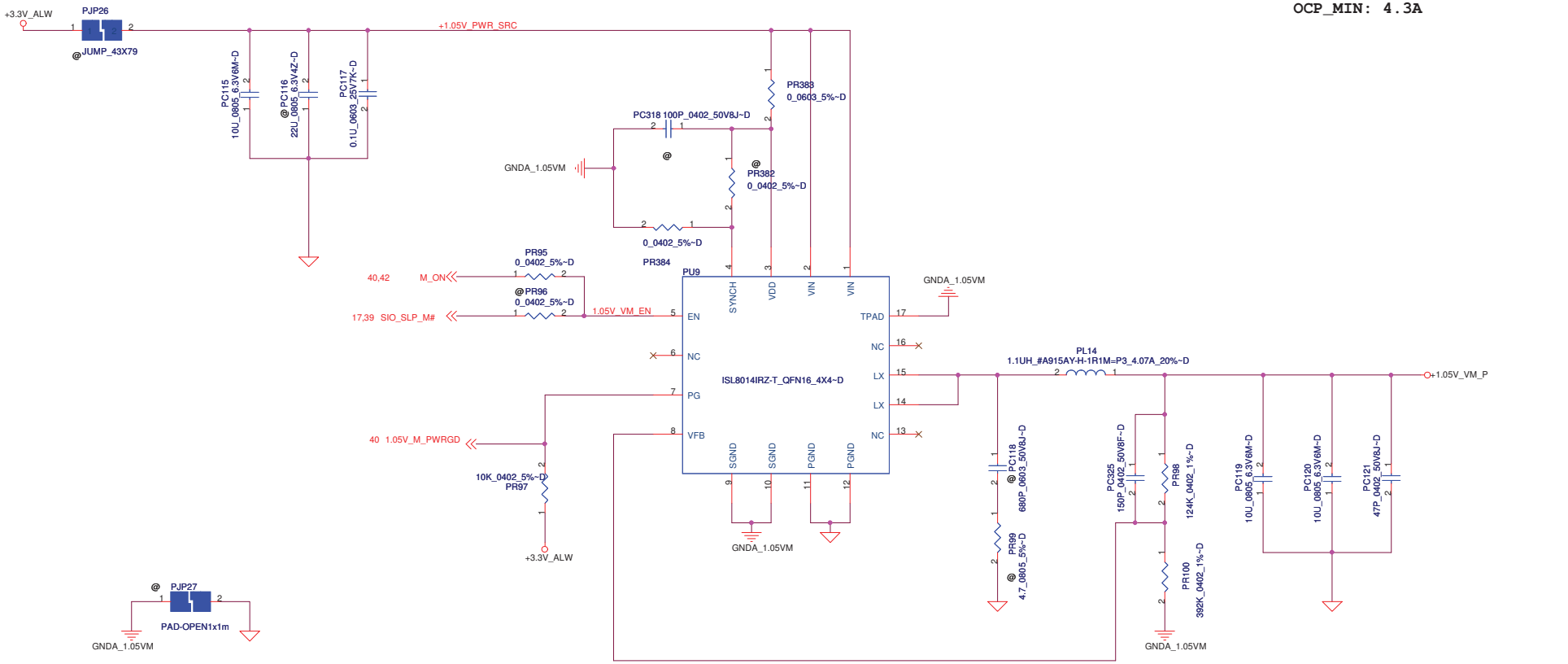
+1.05V_M_P

1.05 Volt +/-5%
Thermal Design Current: 1.518A
Peack current: 2.169A
OCP_MIN: 4.3A



Compal Electronics, Inc.		
Title: +1.05VM		
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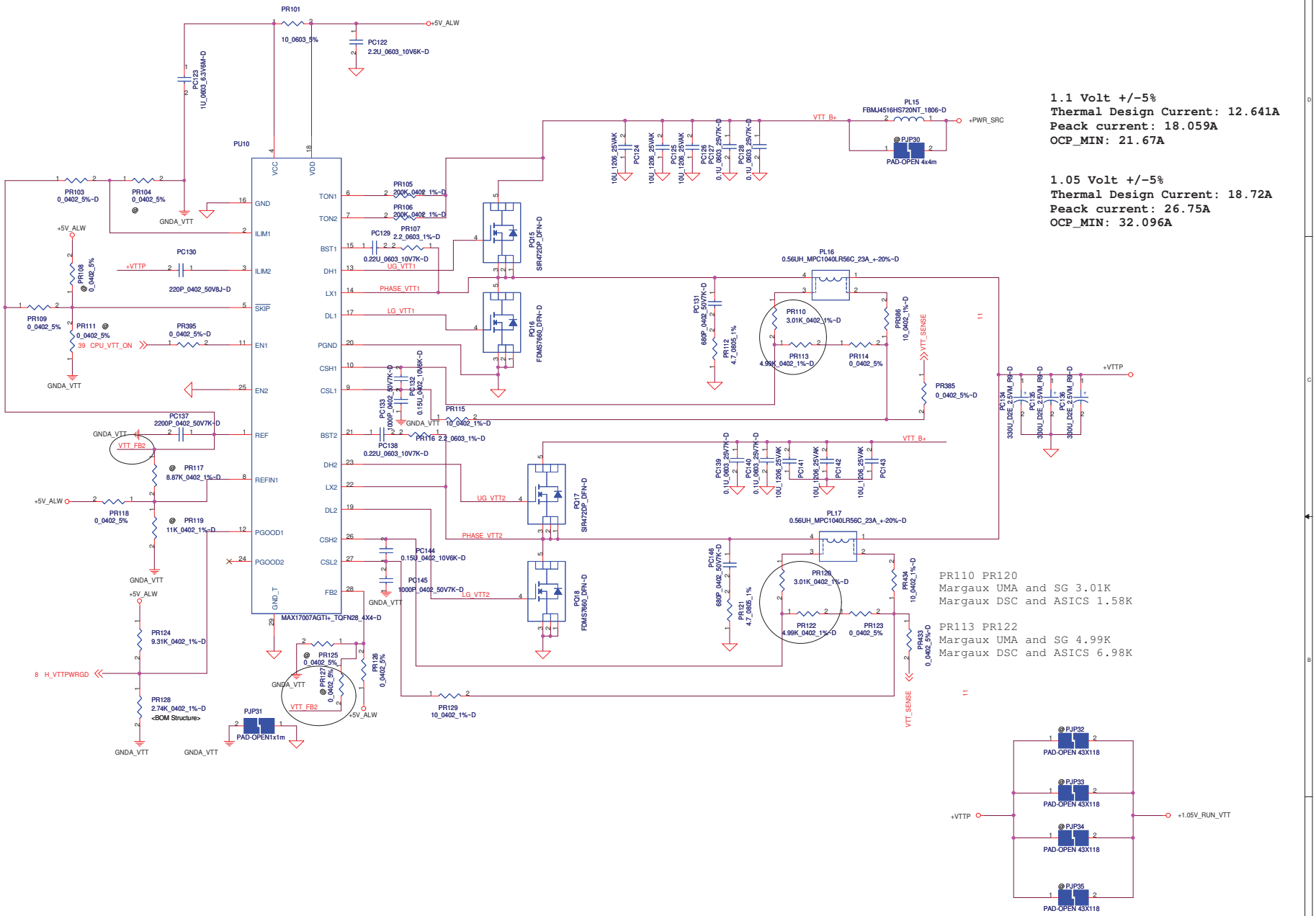

1.1 Volt +/-5%
Thermal Design Current: 12.641A
Peack current: 18.059A
OCP_MIN: 21.67A

1.05 Volt +/-5%
Thermal Design Current: 18.72A
Peack current: 26.75A
OCP_MIN: 32.096A

PR110 PR120
Margaux UMA and SG 3.01K
Margaux DSC and ASICS 1.58K

PR113 PR122
Margaux UMA and SG 4.99K
Margaux DSC and ASICS 6.98K

Title	<Title>	
Size: C	Document Number: LA-5772P	Rev: 1A
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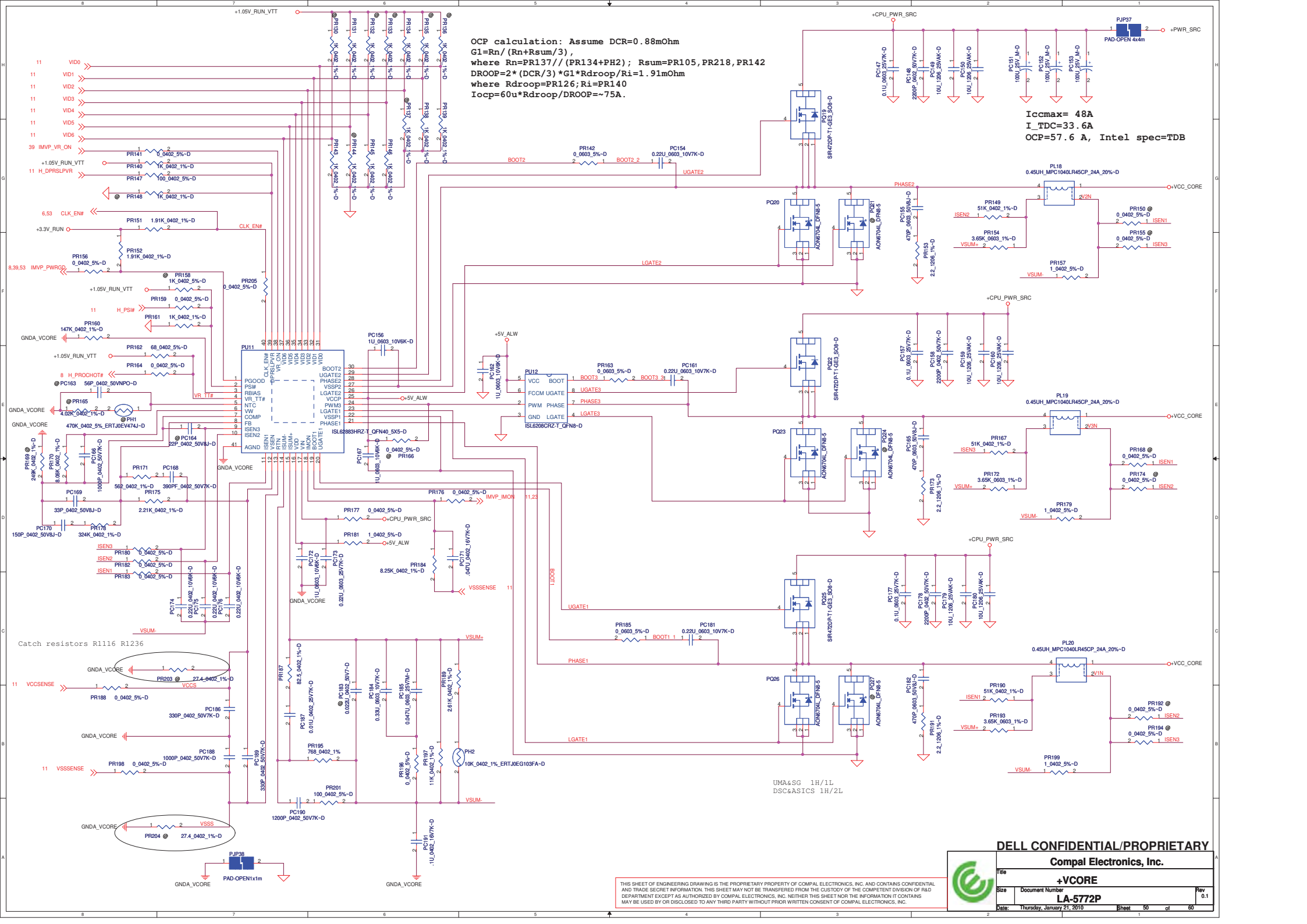
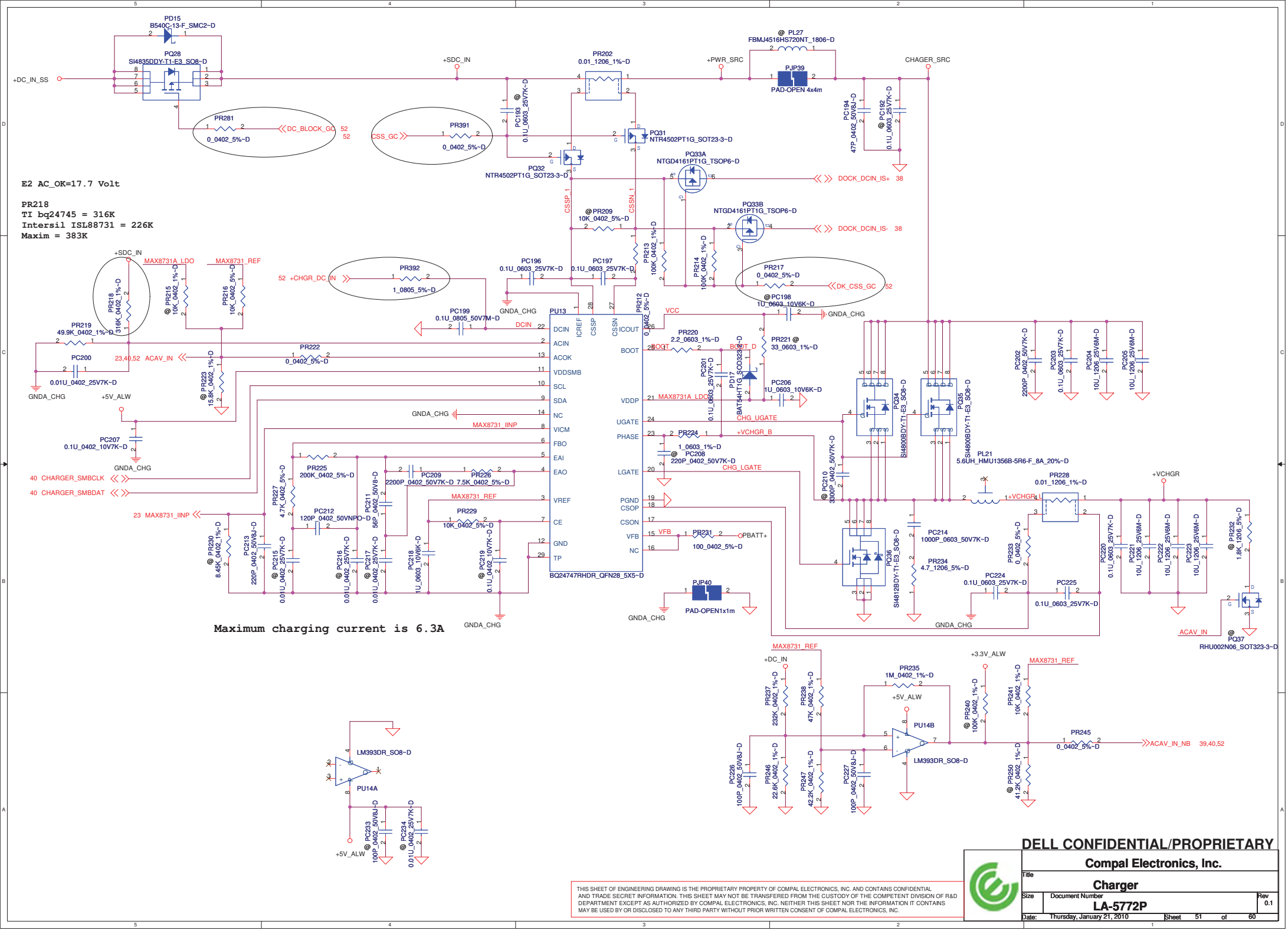
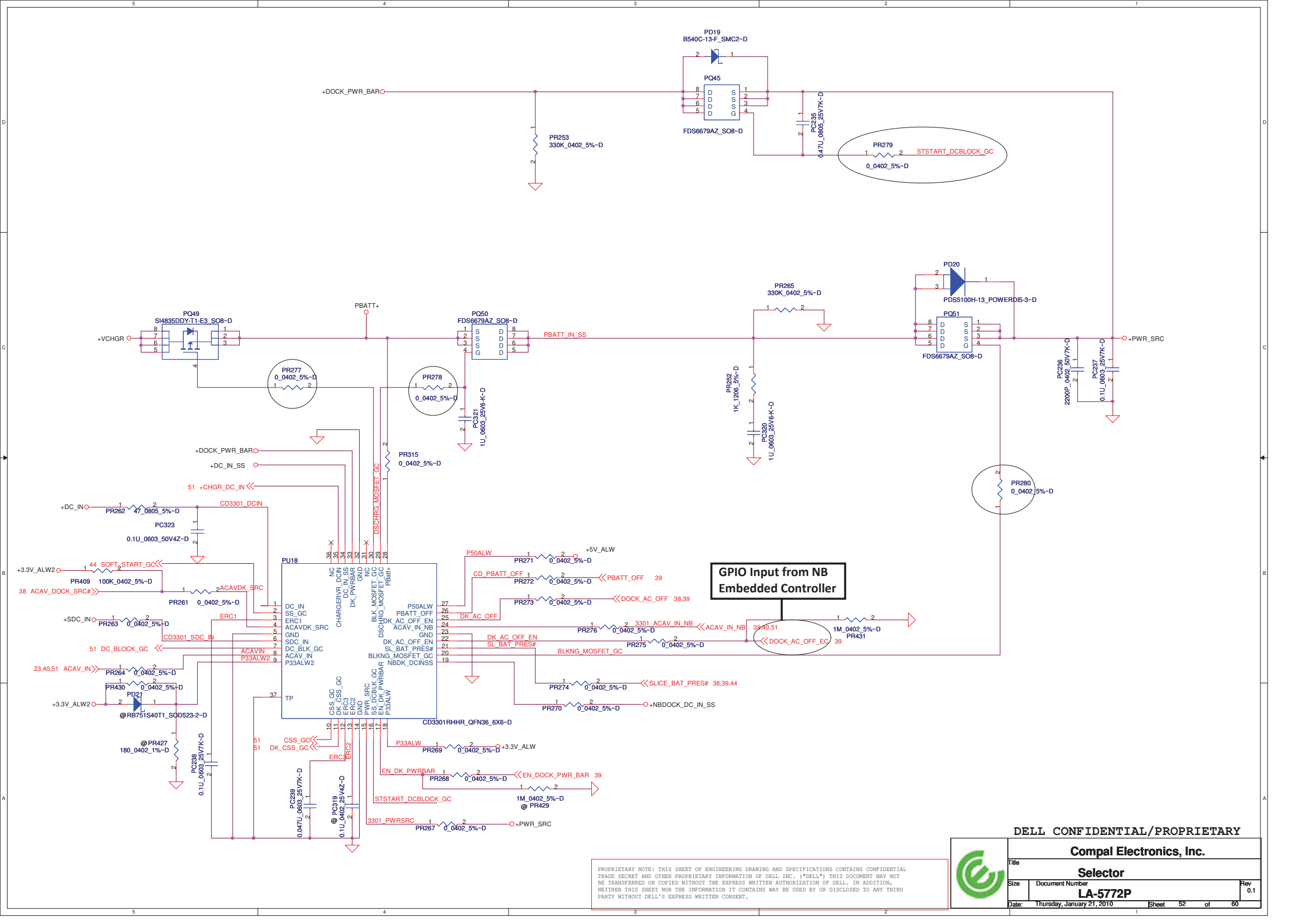


Compal Electronics, Inc.

Title	+VCORE	
Size	Document Number: LA-5772P	Rev: 0.1
Date: Thursday, January 21, 2010	Sheet 50 of 60	





DELL CONFIDENTIAL/PROPRIETARY

Compal Electronics, Inc.		
Title: Selector		
Size	Document Number: LA-5772P	Rev: 0.1
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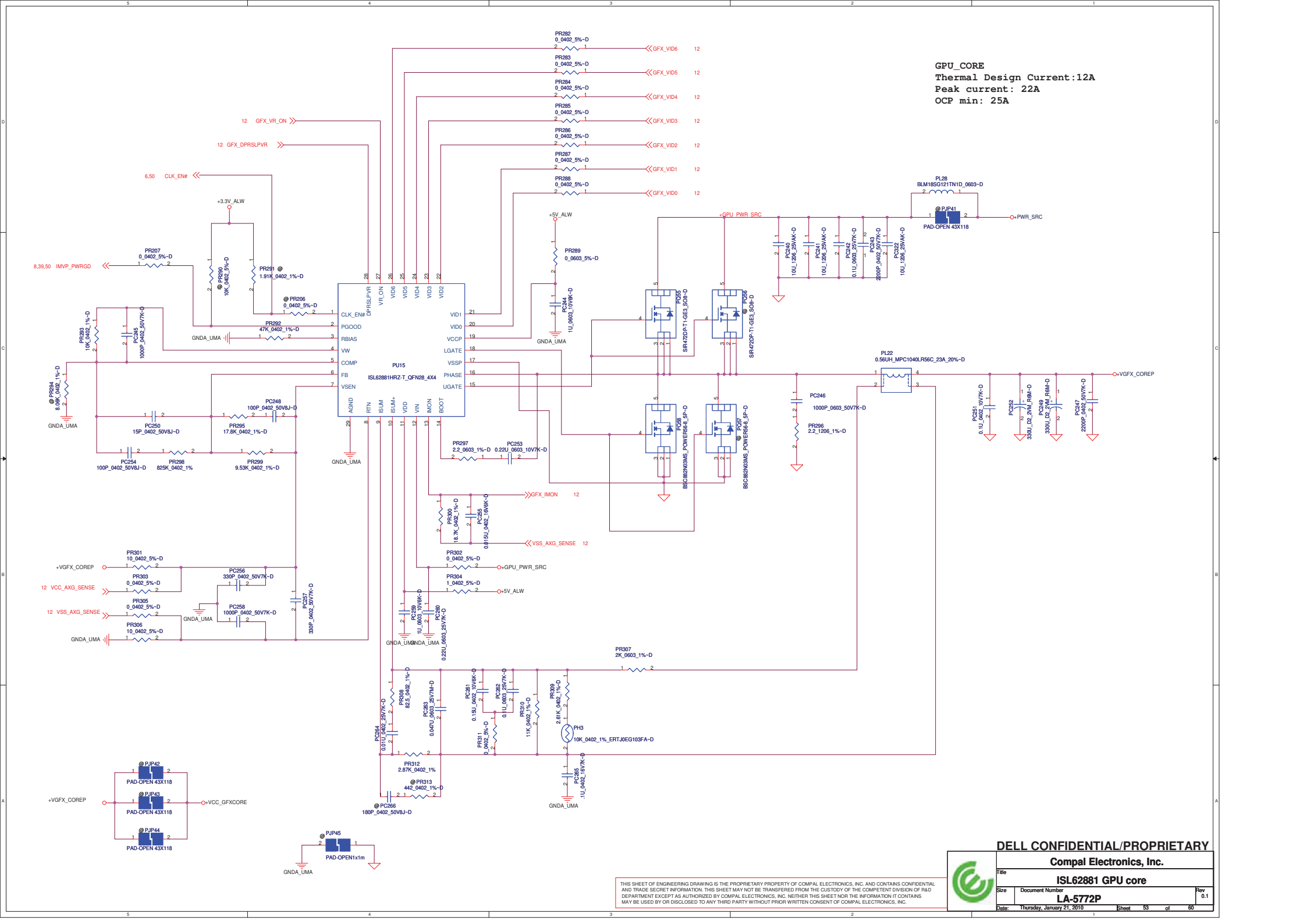
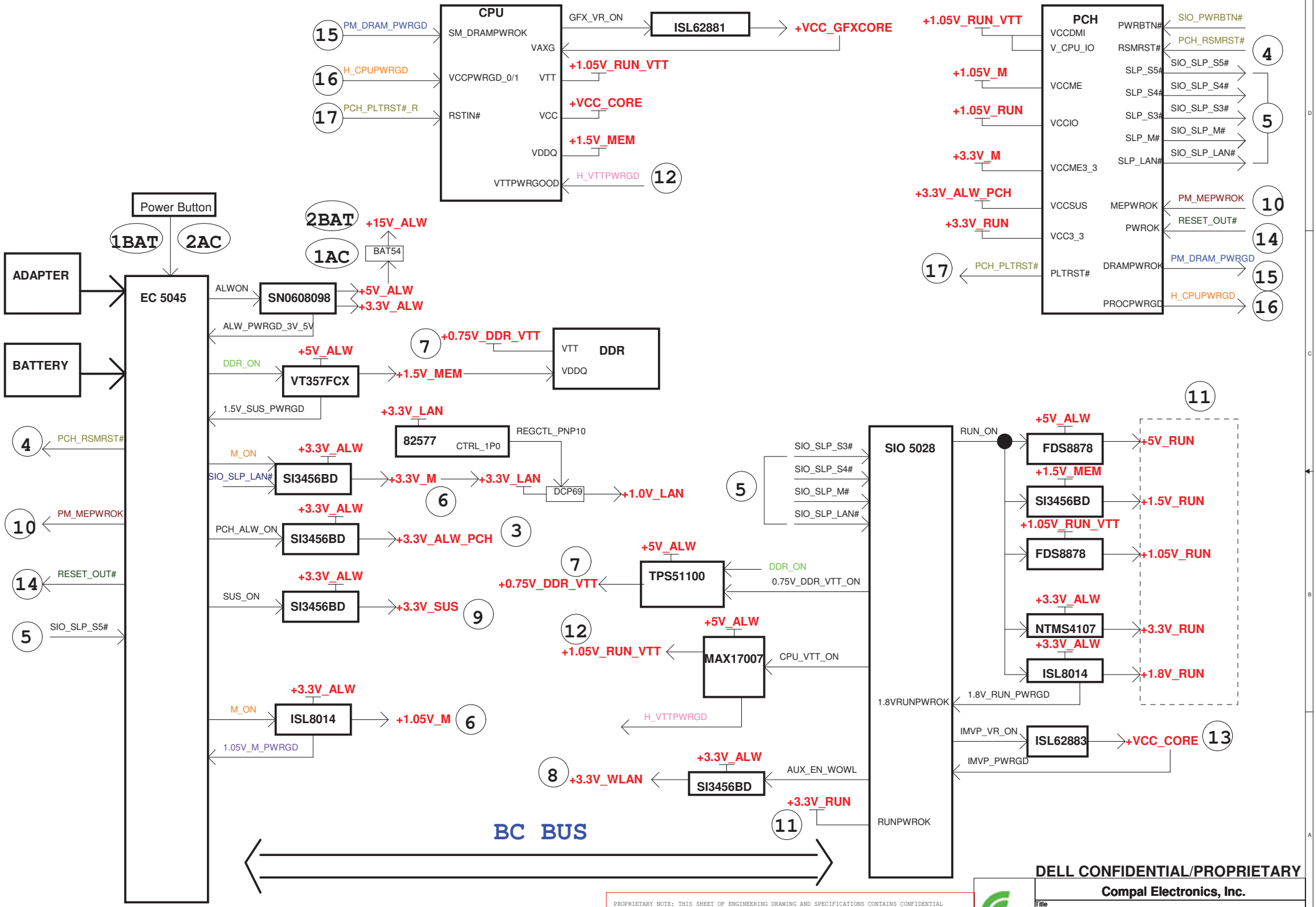


Compal Electronics, Inc.

Title: ISL62881 GPU core

Size | Document Number: LA-5772P | Rev: 0.1

Date: Thursday, January 21, 2010 | Sheet 53 of 60



Compal Electronics, Inc.

Title: Power Sequence

Size | Document Number: LA-5571P | Rev: 0.1

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Version Change List (P. I. R. List)

Item	Page#	Title	Date	Request Owner	Issue Description	Solution Description	Rev.
1	21	HW	5/19/2009	Intel	Remove R689	R689 is only required is power measurements are planned	X01
2	28	HW	5/19/2009	DELL	Remove AGND	Remove the AGND plane and leave everything as DGND. After discussing with IDT there is no value having AGND plane if there is no AGND plane on the IO board and all along the analog signal path.	X01
3	40	HW	5/19/2009	COMPAL	Board ID	R98 change to 130k ohm	X01
4	31	HW	5/21/2009	DELL	5882 support M25 ROM part	Add U19	X01
5	15	HW	5/27/2009	Intel	ES2 deos not need PU/PD for TRST#	Remove R808 & R1316, add test point	X01
6	31	HW	6/01/2009	Broadcom	Reserve SC_TEST & SCC_CMDVCC_N pad	Add @R775 & R776	X01
7	40	HW	6/02/2009	DELL	to prefent Q18 to glitch	Add R595 100K PD at EN_INVPWR	X01
8	34	HW	6/02/2009	DELL	for U52-STBY to both EXPRCRD_STBY# (Depop 0ohm res) and RUN_ON (Pop 0ohm res) for U52-CPPE to both EXPRCRD_PWREN# (Depop 0ohm res) and Card JEXP1 CPPE# pin 17	Add R684, @R687, depop R683	X01
9	15	HW	6/03/2009	Intel	Follow DPDG & ES2 request	R804 change from 47k to 51 ohm, pop R806 & R1315	X01
10	23	HW	6/03/2009	DELL	Fan solution change to M09 design	POP R507, R516, R519, R529, depop R531, R534, R535, D94-D96	X01
11	23	HW	7/01/2009	SMSC	Fan solution change by SMSC request	Change R1463 from 0.56 to 0.27	X01
12	42	HW	7/01/2009	COMPAL	Cost concern & Rdson concern by ADC	Change Q61 to AO4456 & Q55/Q183 to SI4164	X01
13	43	HW	7/01/2009	COMPAL	for derating concern	Change R1001 from 82 to 150 ohm	X01
14	8	HW	7/01/2009	Intel	Follow CRB by Intel request	R1286 needs to change to 0-ohm	X01
15	40	HW	7/01/2009	COMPAL	Board ID	Change R98 to 62K ohm.	X02
16	8,12,13, 42	HW	7/13/2009	Intel	Intel S3 reduction circuit.	Add R1469, R1471-R1474, R1476, R1479-R1484, R1487, C1872-C1879, Q199-Q201, Q204-Q207, U141, PJP57, PJP58, PR428, change R624 to 22 ohm, R879 to 1.5K, R880 to 750, pop Q78, add net DDR_HVREF_RST_GATE from U36.A34, CPU1.5V_S3_GATE from U36.A36, change CPU VDDQ net name to +1.5V_CPU_VDDQ connect RUN_ON_CPU1.5VS3# to Q78.2 Q204.2,	X02
17	30	HW	7/13/2009	COMPAL	+3.3V_LAN enable control follow M09	De-pop R47	X02
18	8,15	HW	7/14/2009	COMPAL	Depop all related components where are located at 0 Z-hight area	Depop JXDP1, JXDP2, JDEG1, JP2 circuit	X02
19	21	HW	7/14/2009	Intel	Add filter for PCH VCCADPLLA/B	Add L97,L98,R1488,C1880-C1883, Remove C105, C106	X02
20	19	HW	7/14/2009	Intel	GPIO1,6,7 PU if not being used	Add R1489-R1491	X02
21	24	HW	7/14/2009	COMPAL	Camera need to be changed from 7 to 8 pin	Change JEDP1 pin definition	X02
22	37	HW	7/16/2009	COMPAL	JTP1, JBIO1 power gnd pins redefined	Change JTP1, JBIO1 pin definition	X02
23	37,40	HW	7/16/2009	SMSC	LAT_ON_SW# needs to be added a 1uF cap	Add @C1884, C1885, R1492, change R560 to 100K, JIO.32 change to LAT_ON_SW_BTN#	X02
24	23	HW	7/16/2009	SMSC	R594 has to be a group with R3P circuit	De-pop R594 for M09 fan solution	X02
25	23	HW	7/16/2009	SMSC	Request by SMSC R3P	Remove D94-D96	X02
26	31	HW	7/17/2009	Braodcom	Found both PD R898 and PU R485 pop	depopulate R898 for normal operation	X02
27	31	HW	7/17/2009	Braodcom	RFID disable circuit remove	Remove R1062-R1065	X02
28	16	HW	7/17/2009	Intel	Intel requires the use of the 25Mhz crystal on UMA and SG platforms	Populate Y6, C1168(18pF), R379, R685, R381 change to C1169(18pF).	X02
29	31	HW	7/17/2009	Braodcom	+SC_VCC Capacitor (C718) Value Change	Broadcom has recommneded changing the value of C718 from .47uF to 220nF	X02
30	42	HW	7/17/2009	COMPAL	Backdrive EA Failure on Margaux/ASICS	Pop R625 and Q79	X02
31	24	HW	7/17/2009	DELL	eDP repeater change to SN75DP119.	update U46 circuit for eDP repeater	X02
32	29	HW	7/17/2009	COMPAL	EMI solution	C676 to 150pF and R1295 to L4 (220 ohm), R1217 change to 47 ohm, pop C673 & R588	X02
33	23	HW	7/17/2009	COMPAL	R3P circuit by SMSC request	R536 depop for 3P FAN, R1457 change to 0 ohm, R138 change to 27K ohm	X02
34	36,39	HW	7/22/2009	DELL	Reconnect the signal UWB_RADIO_DIS#	connect UWB_RADIO_DIS# from EC5028.A56 to MINI3.20	X02
35	23	HW	7/22/2009	DELL	Change FAN solution to M09	De-pop R3P circuit component & pop M09 solution	X02
36	42	HW	7/23/2009	COMPAL	de-rating result fail	Change Q61 from AO4456 to NTMS4107	X02

Version Change List (P. I. R. List)

Item	Page#	Title	Date	Request Owner	Issue Description	Solution Description	Rev.
37	24	HW	7/23/2009	TI	eDP repeater DP119 vender review request	reserve pop option for X1EDP & DP119, change PU/PD to 20K.	X02
38	28	HW	7/23/2009	DELL	We will never disable the power to HDD redriver, go back connected in SSI	Remove R1493 & delete SATA_PWRSAVE	X02
39	18,28,40	HW	7/23/2009	DELL	There has been some confusion due to the net name showing active low	change net name HDD_FALL_INT1# to HDD_FALL_INT to show correct polarity	X02
40	29	HW	7/24/2009	DELL	use the SiTimes part due to the cost savings	change X4 from TXC to SiTimes.	X02
41	31	HW	7/24/2009	Braodcom	connect pin-L10 of U32 to pin-5 of U33, and disconnect pin-D2 from pin-5 of U33	pop R775, de-pop R776	X02
42	33	HW	7/24/2009	COMPAL	fixed SD/MMC Clock overshoot and undershoot	Changing R8 dumping from 0-ohm to 10-ohm	X02
43	31	HW	7/24/2009	Braodcom	BCM5880 Leakage Issue on Margaux	Add Q208,Q209,R1496 circuit to fix.	X02
44	37,39	HW	7/27/2009	DELL	ESATA repeater power saving	Add a 0 ohm jumper between EN pin and VDD, but no-pop it. Then connect the EN pin to 5028.A47 with a 0 ohm jumper that is popped.	X02
45	39	HW	7/27/2009	DELL	Sometimes VGA_ID_DISC and VGA_ID_UMA both read as low	Change R875 and R881 to +3.3V_ALW rail.	X02
46	26	HW	7/27/2009	Parade	new DP PHY test requirement	change R363 value from 499ohm to 1k ohm	X02
47	23	HW	7/27/2009	SMSC	SMSC review feedback	The pull-up source of the R150 should be changed to +VCC_4002	X02
48	31	HW	7/27/2009	NXP	Better for decoupling noise	Change C1015 ,C633 to 10pf	X02
49	33	HW	7/27/2009	TXC	EA result	C514, C515 have to change to 22pF	X02
50	36	HW	7/27/2009	DELL	For PCH GPIOs rail.	PCIE_MCARD3_DET# & USB_MCARD1_DET# pull-ups (R458 & R438) need to change from +3.3V_ALW_PCH rail to +3.3V_RUN rail	X02
51	23,40	HW	7/29/2009	SMSC	per SMSC 5045 AN 19.6, 4002 AN 16.11	R541, R554, R1492 should be 10K, R147 should be populate, Add R1498	X02
52	35	HW	7/29/2009	DELL	Braidwood has been removed from Ibex Peak platforms	De-pop JBW1 & R1453	X02
53	15,40	HW	7/29/2009	KDS	KDS crystal EA result	change UMA C296 & C297 to 12pF, C674, C675 to 27pF	X02
54	39	HW	7/29/2009	DELL	GPIO MAP update	change net name from RESERVED_FOR_ESATA to EN_ESATA_RPTR	X02
55	42	HW	7/29/2009	Compal	By Intel S3 timing concern	reserve R1500 & @R1499 0 ohm for Q206.2 from RUN_ON_CPU1.5VS3# & RUN_ON_ENABLE#	X02
56	13,14	HW	7/30/2009	Compal	EMI concern	POP C1121-C1124, C1145-C1148	X02
57	37	HW	7/30/2009	Intel	Intel continues to recommend that all pre-production and production motherboards include common mode choke footprints to enable a stuffing option in case a choke is required to pass EMI testing	Add @L30, @L31, R424-R427	X02
58	31	HW	7/30/2009	Broadcom	Broadcom schematic review request	pop R537; Remove C647, C641,R634, R498, R898; Add @C1886 & @C1887; Remove L73, R631, C1026, R494, Short net RFREADER_TXN1_PI_R to RFREADER_RXP_C; Remove C642, C640, change R487, R496 to 0 ohm; Add @R1501; de-pop R496 & R497; JCS1 pin2 & pin3 and pin4 & pin5 should be short to carry higher current.	X02
59	31	HW	7/30/2009	Compal	Solve smart card cage vender reverse pin definition.	Reverse JSC1 pin definition	X02
60	27	HW	7/31/2009	Compal	CRB EA result	C390, C518, C996, C251-C253 to 4.7pF; L61-L63 to 5-Ohm Bead	X02
61	31	HW	7/31/2009	Broadcom	Broadcom schematic review request	The pin1 of R497 and R496 should be connected to GND	X02
62	8,15	HW	7/31/2009	Intel	For XDP debug concern	Populate all the resistors and leave out the connector	X02
63	27	HW	8/03/2009	Compal	CRB EA result	C251-C253 to 3.3pF; L61-L63 to 10-Ohm Bead ; De-pop C996, C518, C390	X02
64	23	HW	8/03/2009	Compal	If populate R147 PU resistor for THERM_STP#, it will impact ALWON signal at MEC 5045	De-pop R147	X02
65	30,33	HW	8/04/2009	KDS	KDS crystal EA result	change UMA C427 change to 200 ohm, C514, C515 back to 15P and change X3 from CL=16pF to CL=12pF	X02
66	8	HW	8/05/2009	DELL	fix the Intel S3 power up timing	change C1877 from 0.01uF to 0.22uF 0402 cap.	X02
67	21	HW	8/05/2009	Intel	WW30 Calpella MoW	Intel request change L97 & L98 to 10uH, DCR=0.36 ohm	X02

Version Change List (P. I. R. List)

Item	Page#	Title	Date	Request Owner	Issue Description	Solution Description	Rev.
68	28,37	HW	8/06/2009	Compal	Per ESATA/SATA EA result	pop R1301, R1304, de-pop R1298, R1308	X02
69	10,26,38	HW	8/06/2009	Intel	Per Intel check list rev1.6	change R186, R796, R798 from 100k to 110k ohm, R1109 to 3.3K ohm	X02
70	28	HW	8/06/2009	Compal	ODD_DET# PU from +5V_MOD to +3.3V_RUN	connect R1239.1 to +3.3V_RUN & pop R1239	X02
71	42	HW	8/06/2009	SMSC	Watch dog timer may not be resetED when 4002 VDD_PWRGD is not completely at Logic Low	Pop R616 to 39 & pop Q72	X02
72	30	HW	8/10/2009	Intel	Remove the VCT trace	Remove @R562, @C41	X02
73	35	HW	8/10/2009	DELL	Braidwood Removal on RAM	Remove @JBW1, @C1851, @R1452, @R1453, @C1852, R1411	X02
74	31	HW	8/11/2009	Broadcom	Broadcom review request	Remove @R1061, Change C718 value to 470pF, change C646 value to 220pF. pin2 of R470 should have a 0ohm but de-pop resistor to USB_GPIO27 net.	X02
75	8	HW	8/11/2009	Intel	Intel review request	add @R1504 for DDR3_DRAMRST#_CPU PD & add C1888 for PM_DRAMRST# to slow down gate of FET	X02
76	33	HW	8/11/2009	Richo	Change pop option for R5U242	Change C21 from 10U to 47U, change R46 to C1889 (1uF)	X02
77	24	HW	8/12/2009	DELL	EDP_HPD signal may too low to turn on FET.	Change Q3 to BSS138	X02
78	21	HW	8/12/2009	Intel	Follow CRB rev 1.6 schematic	No stuff C111 and C112	X02
79	31	HW	8/12/2009	Broadcom	Per Broadcom request	pop R496 & R497 (0 ohm)	X02
80	31	HW	8/12/2009	Compal	Smart card EA result	change R772 to 47 Ohm for resolving SC_CLK Rise/Fail timing issue	X02
81	8	HW	8/12/2009	Intel	Follow Intel S3 white paper rev0.9	pop R1504 & change C1888 to 470pF	X02
82	37	HW	8/12/2009	Compal	disconnect IO & DOCK VCT	rename IO VCT to +LOM_VCT_IO & reserve C712 pad for test.	X02
83	31	HW	8/13/2009	Broadcom	Per Broadcom request	need to have 4.7K pull-up to 3.3V_ALW for BCM5882 pin-C1 "RSTOUT_N"	X02
84	8	HW	8/13/2009	DELL	Avoid a glitch for DDR_HVREF_RST_GATE, please add a 1.1K 1% no-stuff pull-up to +1.5V_CPU_VDDQ rail on the PM_DRAM_PWRGD_R signal for a back-up option	change C1888 to 0.1u, add @R1511 for PM_DRAM_PWRGD_R	X02
85	8,45	HW	8/13/2009	DELL	CPU detection since the edge diode has been removed from M'09	Add R1512 for CPU_DETECT# and connect JCPU.AH24 to U36.B18	X02
86	37	HW	8/14/2009	DELL	Invert the EN_ESATA_RPTR signal and connect this to SATAGP4/GPIO16	Add @R1513 & @Q210, pop R1494 and de-pop R1497, change net name from GPIO16 to EN_ESATA_RPTR#	X02
87	33	HW	8/14/2009	Compal	Solve 1394 impedance issue	Change R399, R400, R401, R403 to 54.9 ohm.	X02
88	37	HW	8/14/2009	Compal	EMI solution	pop L30 & L31, de-pop R424-R427	X02
89	11,12	HW	9/11/2009	Compal	Per PWR EA result	De-pop C66, pop C1090, C1091	X02
90	16	HW	9/11/2009	KDS	crystal EA result	Y6 change to CL=12pF & change C1168 & C1169 to 12pF.	X02
91	33,34	HW	9/11/2009	COMPAL	EMI solution for SD CLOCK & EXP card USB	R8 change to 22 ohm, pop L64 & depop R791, R792	X02
92	21	HW	9/11/2009	Intel	Intel request	de-pop C39, C610	X02
93	31	HW	9/11/2009	Broadcom	Broadcom review feedback	change C718 from 470p to .47u, C646 from 220p to .22u	X02
94	30	HW	9/11/2009	Intel	Follow Intel document request	change R1502 to C427 10pF, C475, C476 to 33pF	X02
95	12	HW	9/11/2009	DELL	Intel S3 circuitry issue on Margaux UMA	change C1873 from 4700p to 0.01uF	X02
96	21	HW	10/15/2009	Intel	Isolate pins AF32, AF34 and AH34 of PCH	Add C1893.	X02
97	35	HW	10/23/2009	Compal	Add PD 10k for Minicard PWR	Add R1523-R1525	X03
98	31	HW	10/23/2009	Compal	Smart card connector DFM issue	change JSC1 type (the same with Rothschild)	X03
99	40	HW	10/23/2009	COMPAL	Board ID	Change R98 to 4.3K ohm.	X03
100	17,21	HW	10/23/2009	Intel	Intel schematic check list 2.0 request	R268 change from 1k ohm to 10k ohm, de-pop C1881 & C1883	X03
101	40	HW	10/23/2009	SMSC	SMSC review feed back	R561 and R1046 are too large it is recommend that no PU/PD be larger than 100K	X03
102	12,42	HW	10/23/2009	COMPAL	avoid double bleed off	+3.3V_M, +3.3V_RUN, +1.5V_CPU_VDDQ power plane discharge circuit have been pop, de-pop R612, R607, R1471.	X03
103	36	HW	10/23/2009	DELL	support WiMax LED status	Need to populate R840	X03
104	40	HW	10/25/2009	KDS	KDS Crystal EA result	change C674, C675 from 27pF to 33pF	X03
105	16,32	HW	10/25/2009	COMPAL	Change R910 placement	Please put R910 close to PCH not TCM chip	X03
106	41	HW	10/25/2009	COMPAL	Touch Pad PU need to move from 5V to 3V	R613, R614 change power rail from +5V_ALW to +3.3V_ALW	X03
107	31	HW	10/28/2009	Broadcom	For 5882-B0 request	L71, L72 68nH, 2%, 400mA; C1070, C1071 1500pF, 2%, 50V; C1886, C1887 150pF, 2%, 50V	X03

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Item	Page#	Title	Date	Request Owner	Issue Description	Solution Description	Rev.
108	29	HW	10/28/2009	IDT	create a low pass filter with the pole set at 36kHz to filter out of band noise	de-pop C1066 & C1067, R1090, R1089 ; R340 & R342, R1091 & R1092 change to 2k, add C1894-C1897 1000pF.	X03
109	24	HW	10/28/2009	COMPAL	EMI concern	add 220 ohm bead for BIA_PWM_PCH	X03
110	29	HW	10/28/2009	COMPAL	ME request for JSPK1 swap	JSPK1 Pin 2 and pin 4 swap, pin 3 and pin 5 swap	X03
111	17	HW	10/29/2009	COMPAL	PCH CRT DDC pin up to 3.8V	add CRT DDC level shift, Q217, @R1526, @R1527	X03
112	8,12,13, 15,16,28	HW	10/29/2009	DELL	MEM SMBus design needs to change	Move Q190 connection, add R1528,R1529, add net name DDR_XDP_CLK/DAT	X03
113	31	HW	10/29/2009	DELL	smart card clock resistor	Change R772 from 47 ohm to 22 ohm	X03
114	37	HW	10/29/2009	COMPAL	EMI concern	pop R15 with 10 ohm and C15 with 10pF	X03
115	36	HW	10/29/2009	COMPAL	USB_MCARD2_DET# change to +3.3V_ALW_PCH	R447 pull up should change to +3.3V_ALW_PCH	X03
116	40	HW	10/29/2009	COMPAL	avoid RESET_OUT# double PD	de-pop R5	X03
117	15	HW	11/02/2009	COMPAL	EMI, RF team concern	pop C300, C302	X03
118	24	HW	11/04/2009	COMPAL	LCD power sequencing issue	change R161 from 470 to 130 ohm .	X03
119	37	HW	11/05/2009	COMPAL	EMI concern	Change choke vender from Murata to Delta on L30,L31	X03
120	29	HW	11/05/2009	COMPAL	RF team concern	X4 change from Sitime to TXC	X03
121	15	HW	11/05/2009	COMPAL	RTC issue	Y1 & Y4 change from 30ppm to 10ppm.	X03
122	15	HW	11/05/2009	COMPAL	For flash ROM EOL issue	U13 change from W25X32 to W25Q32	X03
123	19	HW	11/09/2009	DELL	PCH driving the siganl low at GPIO15 initial	add R1530 2.2K PU resistor to +3.3V_ALW_PCH on the SIO_EXT_WAKE# signal.	X03
124	39	HW	11/10/2009	DELL	add a 10K 5% PU to +3.3V_RUN on ME_FWP	Add R1531	X03
125	12	HW	11/11/2009	COMPAL	Surge voltage found at UMA GFX core	R358 changed from 4.7k ohm to 470 ohm	X03
126	8,15	HW	11/13/2009	COMPAL	To cut redundant trace for SMBUS	Add @R1532/R1533/R1536/R1537	X03
127	19	HW	11/17/2009	Intel	By Intel check list request	Add R1543 & R1544 for PCH GPIO22/34	X03
128	41	HW	12/24/2009	Compal	To solve touch pad ESD issue	Change L41 and L42 to R1545 & R1546 with 100 ohm.	X03
129	29	HW	12/24/2009	Compal	RF noise issue concern	change Sitime 12MHz oscillator X4 to driver strength 1x	X03
130	15	HW	12/24/2009	Intel	Follow Intel check list rev2.0	Change R224 to tolerance from 5% to 1%	X03
131	36	HW	12/24/2009	DELL	Wimax LED abnormal operation.	de-pop R1409	X03
132	38	HW	12/24/2009	Compal	Simplo battery slice EMI issue	Add C1899 and C1898(Depop,reserve for EMI test)	A00
133	31	HW	12/24/2009	Braodcom	By Broadcom request	Change L71,L72 from 68nH to 150nH, C1070,C1071 from 1500pF to 390pF.C1887, C1888 from 150pF to 390pF.	A00
134	40	HW	12/30/2009	DELL	Board ID	Change R98 from 4.3K to 1K for A00	A00
135	33,34	HW	12/30/2009	COMPAL	Change R5U242 to rev ES3	Change U94 from ES2 to ES3	A00
136	8,15	HW	12/30/2009	Intel	De-pop XDP & JTAG resistor	de-pop C19,C20,R6,R7,R68,R19,R3,R1153,R1156,R1157,R66,R1241,R780-R785, R22,R24,R78,R91,R101-R116,C1375,R69,R118,R123,R804,R807,R805,R806,R1281, R1282,R1315	A00
137	24	HW	01/14/2010	COMPAL	RF team concern	reserve C1900 for PWM	A00
138	28,37	HW	01/15/2010	COMPAL	Change Esata repeater for power save	Change U95 U96 from 412 to 412A	A00
139	11	HW	01/18/2010	COMPAL	No stuff MLCC caps to fix Acoustic noise	de-pop C50, C52, C57, C59	A00
140	15	HW	01/21/2010	COMPAL	For factory to do JTAG test	Pop R123, R804-R807, R1281, R1282, R1315	A00

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1	52	Selector	6/1	Compal	CD3301 burn issue	Change PR262 to 47_ohm, add PC323 0.1uF. Add PR409 pull up to +3.3V_ALW2. Delete PR266, add PD21 RB751.	
2	49	+1.05VTT	6/1	Compal ADC Guangyong	Change high side MOS to power pak	Change PQ15 PQ17 to Power pak SIR472DP.	
3	47	+0.75_DDR_VT/ +1.8V_RUN	6/1	Compal ADC Guangyong	Add type 3 cap	Add PC324 150pF	
4	48	+1.05V_VM_UMA	6/1	Compal ADC Guangyong	Add type 3 cap	Add PC325 150pF	
5	46	1.5V_MEM_UMA	6/1	Compal ADC Guangyong	Add droop resistor and input cap.	Add PR410 PC326	
6	47	+0.75_DDR_VT/ +1.8V_RUN	6/1	Compal ADC Guangyong	optimize ISL8014	change PR78 to 10K_ohm change PC81 PC85 PC86 to 10uH unpop PC82 unpop PR379 pop PR381	
7	48	+1.05V_VM_UMA	6/1	Compal ADC Guangyong	optimize ISL8014	change PR97 to 10K_ohm change PC115 PC119 PC120 to 10uH unpop PC116 unpop PR382 pop PR384	
8	50	+VCORE	6/8	Intersil	Change Isen resistor to 11K	Change PR149 PR167 PR190 to 11K_ohm SD03411028L	
9	46	+1.5V_MEM_UMA	6/11	Compal / TI	+1.5V_MEM_UMA output voltage over 2V	unpop PR56	
10	44	+DCIN	6/3	Dell	remove PBAT_ALARM# (6/3 Youssef_Daou)	delete DP5 PR6	
11	50	+VCORE	7/14	Dell / intersil	change Cisense GND to VSUM-	PC174 PC175 PC176 pin2 connect to VSUM-	
12	45	+5V/+3.3V	7/14	Compal ADC Guangyong	change 7*7 & 5*5 choke for cost down	change PL5 from SH00000H90L to SH00000FN0L change PL6 from SH00000HB0L to SH00000HR0L change PL11 from SH00000HE0L to SH00000HO0L change PL14 from SH00000HE0L to SH00000HY0L	
13	52	Selector	7/14	TI	CSS GC logic wrong issue	Add PR427 180_ohm to GND	
14	53	ISL62881_UMA	7/16	intersil	change Rbias to 47K_ohm	change PR292 to 47K_ohm	
15	52	Selector	7/16	Compal	Add 1M_ohm pull down to fix ACAV_IN_NB oscillation when battery mode S5	Add PR429	
16	50	+VCORE	7/16	intersil	change Isense resister to 51K_ohm	change PR149 PR167 PR190 to 51K_ohm	
17	52	Selector	7/22	TI	new version CD3301 (PG2.1) dont need PD21	un-pop PD21 add PR430	
18	52	Selector	7/22	TI	DOCK_AC_OFF_EC floating issue	add PR431	
19	53	ISL62881_UMA	7/22	Intersil	change frequency to 300K	change PR293 to 10K	
20	53	ISL62881_UMA	7/22	Intersil	change Rsum to 0603 package improve Vout accuracy	change PR307 from SD03436518L to SD01436518L	
21	50 / 53	+VCORE / ISL62881_UMA	8/10	Compal	change thermistor from 0603 to 0402 package for cost down	Change PH2 PH3 from SL200000B0L to SL20000100L	

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24	45 / 49 50 / 51	+5V/+3.3V +1.05VTT +Vcore charger	8/11	Compal	solve EMI issue	pop PC32 PC33 PR36 PR39 PL15 PC155 PC165 PC182 PR153 PR173 PR191 add PL27 PL28	
25	50	+Vcore	8/11	intersil / Gary	FAE suggestion (8/5)	PR175 change to 2.21K_ohm depop PC190 PR201	
26	50	+Vcore	8/11	Compal	adjust Vimon	change PC171 to 47nF	
27	53	ISL62881_UMA	8/13	Intersil	FAE suggestion (Kidwell gary) (maill from AJ 0813)	PR307 change to 2k,PR312 change to 2.87k,PR299 change to 10.5k, PC262 change to 0.12uF, PC255 change to 0.015uF,PC266 PR313 depop.	
28	45	+5V/+3.3V	8/17	TI/Compal	adjust OCP setting	Change PR31 from 243K to 232K, PR32 from 232K to 215K	
29	44	+DCIN	10/23	TI/Compal	slow soft star to fast issue	Change PR20 from 0_ohm to 10K.	
30	49	+1.05VTT	10/23	Intel	VTT power good voltage level change	Change PR124 from 28.7K to 9.31K. Change PR128 from 10K to 2.74K.	
31	51	Charger	10/23	Compal EMI	EMI solution	pop PC214 1000pF, PR234 4.7_ohm	
32	49	+1.05VTT	10/23	Maxim	fix VTT drop issue	ILIM = 30mV, un-pop PR104, PR103=0_ohm, PR110, PR120=3.01K_ohm ; PR113, PR122=4.99K_ohm ; PR114, PR123=0_ohm Ceq PC132,PC144 =0.15uF ; Filter PC133, PC145=un-pop ; PR115, PR129=0_ohm REF capacitor PC137 change to 2.2nF Add PR432, PR433 for dual remote sense	
33	51	Charger	10/23	TI	Reduce CD3301 pin34 pin 35 peak current	Change PR392 to 0805 size.	
34	51	Charger	11/10	Compal	ACAV_IN_NB level adjust. (10/29)	Change PR246 from 21.5K to 22.6K	
35	50	+Vcore	11/17	Compal	pop PC190 PR201 for improve 2nd source FDIM	pop PC190 PR201	
36	53	ISL62881_UMA	11/17	Compal	adjust Load Line for 2nd source	change PR299 from 10.5K to 9.53K.	
37	49	+1.05VTT	01/20	Maxim	fix dual palse issue	pop filter PC133, PC145=1000p ; PR115, PR129=10_ohm	
38	51	Charger	01/20	Compal	reduce surge current. (for CD3301)	Change PR392 form 0_ohm to 1ohm change PC199 from 1uF to 0.1uF	
39	51	Charger	01/20	Compal	EMI can pass without this bead. remove for cost saving.	un-pop PL27	

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